



Precision Analog-to-Digital Converter (ADC) and Digital-to-Analog Converters (DACs) with 8051 Microcontroller and Flash Memory

FEATURES

ANALOG FEATURES

- 24-BITS NO MISSING CODES
- 22-BITS EFFECTIVE RESOLUTION AT 10Hz Low Noise: 75nV
- PGA FROM 1 TO 128
- PRECISION ON-CHIP VOLTAGE REFERENCE: Accuracy: 0.2% Drift: 5ppm/°C
- 8 DIFFERENTIAL/SINGLE-ENDED CHANNELS
- ON-CHIP OFFSET/GAIN CALIBRATION
- OFFSET DRIFT: 0.02PPM/°C
- GAIN DRIFT: 0.5PPM/°C
- ON-CHIP TEMPERATURE SENSOR
- SELECTABLE BUFFER INPUT
- BURNOUT DETECT
- QUAD 16-BIT MONOTONIC VOLTAGE DACs:
 2 VDACs Can Be Programmed as IDACs 8μs Settling Time

DIGITAL FEATURES

Microcontroller Core

- 8051 COMPATIBLE
 HIGH SPEED CORE: 4 Clocks per Instruction Cycle
- DC TO 30MHz
- SINGLE INSTRUCTION 133ns
- DUAL DATA POINTER

Memory

- UP TO 32kB FLASH DATA MEMORY
- FLASH MEMORY PARTITIONING
- ENDURANCE 1M ERASE/WRITE CYCLES, 100 YEAR DATA RETENTION
- IN-SYSTEM SERIALLY PROGRAMMABLE
- EXTERNAL PROGRAM/DATA MEMORY (64kB)
- 1280 BYTES DATA SRAM
- FLASH MEMORY SECURITY
- 2kB BOOT ROM
- PROGRAMMABLE WAIT STATE CONTROL

Peripheral Features

- 34 I/O PINS
- ADDITIONAL 32-BIT ACCUMULATOR
- THREE 16-BIT TIMER/COUNTERS
- SYSTEM TIMERS
- PROGRAMMABLE WATCHDOG TIMER
- FULL DUPLEX DUAL UART
- MASTER/SLAVE SPI[™] WITH DMA
- MULTI-MASTER I²CTM
- 16-BIT PWM
- POWER MANAGEMENT CONTROL
- INTERNAL CLOCK DIVIDER
- IDLE MODE CURRENT < 200µA
- STOP MODE CURRENT < 100nA
- PROGRAMMABLE BROWNOUT RESET
- PROGRAMMABLE LOW VOLTAGE DETECT
- 21 INTERRUPT SOURCES
- TWO HARDWARE BREAKPOINTS

GENERAL FEATURES

- PIN COMPATIBLE WITH MSC1210 FAMILY
- PACKAGE: TQFP-64
- LOW POWER: 4mW
- INDUSTRIAL TEMPERATURE RANGE: -40°C to +85°C
- POWER SUPPLY: 2.7V to 5.25V

APPLICATIONS

- INDUSTRIAL PROCESS CONTROL
- INSTRUMENTATION
- LIQUID/GAS CHROMATOGRAPHY
- BLOOD ANALYSIS
- SMART TRANSMITTERS
- PORTABLE INSTRUMENTS
- WEIGH SCALES
- PRESSURE TRANSDUCERS
- INTELLIGENT SENSORS
- PORTABLE APPLICATIONS
- DAS SYSTEMS



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PACKAGE/ORDERING INFORMATION

PRODUCT	FLASH MEMORY	PACKAGE-LEAD	PACKAGE DESIGNATOR ⁽¹⁾	SPECIFIED TEMPERATURE RANGE	PACKAGE MARKING	ORDERING NUMBER	TRANSPORT MEDIA, QUANTITY
MSC1211Y2	4k	TQFP-64	PAG	–40°C to +85°C	MSC1211Y2	MSC1211Y2PAGT	Tape and Reel, 250
MSC1211Y2	4k	"	"	"	"	MSC1211Y2PAGR	Tape and Reel, 2000
MSC1211Y3	8k	TQFP-64	PAG	–40°C to +85°C	MSC1211Y3	MSC1211Y3PAGT	Tape and Reel, 250
MSC1211Y3	8k	"	"	"	"	MSC1211Y3PAGR	Tape and Reel, 2000
MSC1211Y4	16k	TQFP-64	PAG	–40°C to +85°C	MSC1211Y4	MSC1211Y4PAGT	Tape and Reel, 250
MSC1211Y4	16k	"	"	"	"	MSC1211Y4PAGR	Tape and Reel, 2000
MSC1211Y5	32k	TQFP-64	PAG	−40°C to +85°C	MSC1211Y5	MSC1211Y5PAGT	Tape and Reel, 250
MSC1211Y5	32k	"	"	"	"	MSC1211Y5PAGR	Tape and Reel, 2000

NOTE: (1) For the most current specifications and package information, refer to our web site at www.ti.com/msc.

ABSOLUTE MAXIMUM RATINGS⁽¹⁾

Analog Inputs	
Input Current 10	
Input Current 1	
Input Voltage AGND – 0.5	V to AV _{DD} + 0.5V
Power Supply	
DV _{DD} to DGND	0.3V to 6V
AV _{DD} to AGND	0.3V to 6V
AGND to DGND	0.3V to +0.3V
V _{REF} to AGND0.3	V to AV _{DD} + 0.3V
Digital Input Voltage to DGND0.3	
Digital Output Voltage to DGND0.3	V to DV _{DD} + 0.3V
Maximum Junction Temperature	+150°C
Operating Temperature Range	. –40°C to +85°C
Storage Temperature Range	–65°C to +150°C
Lead Temperature (soldering, 10s)	+300°C
Package Power Dissipation	900mW
Output Current All Pins	200mA
Output Pin Short Circuit	10s
Thermal Resistance, Junction-to-Ambient (θ_{IA})	66.6°C/W
Thermal Resistance, Junction-to-Case (θ_{JC})	4.3°C/W
Digital Outputs	
Output Current 10	0mA, Continuous
I/O Source/Sink Current	100mA
Power Pin Maximum	300mA

NOTE: (1) Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. Exposure to absolute-maximumrated conditions for extended periods may affect device reliability.

ELECTROSTATIC DISCHARGE SENSITIVITY

This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

MSC1211YX FAMILY FEATURES

FEATURES ⁽¹⁾	MSC1211Y2 ⁽²⁾	MSC1211Y3 ⁽²⁾	MSC1211Y4 ⁽²⁾	MSC1211Y5 ⁽²⁾
Flash Program Memory (Bytes)	Up to 4k	Up to 8k	Up to 16k	Up to 32k
Flash Data Memory (Bytes)	Up to 4k	Up to 8k	Up to 16k	Up to 32k
Internal Scratchpad RAM (Bytes)	256	256	256	256
Internal MOVX SRAM (Bytes)	1024	1024	1024	1024
Externally Accessible Memory (Bytes)	64k Program, 64k Data			

NOTES: (1) All peripheral features are the same on all devices; the flash memory size is the only difference. (2) The last digit of the part number (N) represents the onboard flash size = $(2^N)kBytes$.



ELECTRICAL CHARACTERISTICS: $AV_{DD} = 5V$

All specifications from T_{MIN} to T_{MAX} , DV_{DD} = +2.7V to 5.25V, f_{MOD} = 15.625kHz, PGA = 1, Buffer ON, f_{DATA} = 10Hz, Bipolar, and $V_{REF} \equiv (REF IN+) - (REF IN-) = +2.5V$, unless otherwise noted. For V_{DAC} , V_{REF} = AV_{DD} , R_{LOAD} = 10k Ω , and C_{LOAD} = 200pF, unless otherwise noted.

PARAMETER	CONDITION	MIN	TYP MAX		UNITS	
ANALOG INPUT (AIN0-AIN7, AINCOM) Analog Input Range Full-Scale Input Voltage Range Differential Input Impedance Input Current Bandwidth	Buffer OFF Buffer ON (In+) – (In–) See Figure 4 Buffer OFF Buffer ON	AGND - 0.1 AGND + 50mV	5/PGA 0.5	$AV_{DD} + 0.1$ $AV_{DD} - 1.5$ $\pm V_{REF}/PGA$	V V MΩ nA	
Fast Settling Filter Sinc ² Filter Sinc ³ Filter Programmable Gain Amplifier Input Capacitance Input Leakage Current Burnout Current Sources	3dB 3dB 3dB User-Selectable Gain Ranges Buffer ON Multiplexer Channel Off, T = +25℃ Sensor Input Open Circuit	1	0.469 • f _{DATA} 0.318 • f _{DATA} 0.262 • f _{DATA} 4 0.5 ±2	128	pF pA μA	
ADC OFFSET DAC Offset DAC Range Offset DAC Monotonicity Offset DAC Gain Error Offset DAC Gain Error Drift		8	±V _{REF} /(2 • PGA) ±1.5 1		V Bits % of Range ppm/°C	
SYSTEM PERFORMANCE Resolution ENOB		24	22	riation	Bits Bits	
Output Noise No Missing Codes Integral Nonlinearity Offset Error Offset Drift ⁽¹⁾ Gain Error ⁽²⁾ Gain Error Drift ⁽¹⁾ System Gain Calibration Range System Offset Calibration Range Common-Mode Rejection	$\begin{array}{c} \text{Sinc}^3 \text{ Filter} \\ \text{End Point Fit, Differential Input} \\ \text{After Calibration} \\ \text{Before Calibration} \\ \text{After Calibration} \\ \text{Before Calibration} \\ \end{array}$	See - 24 80 -50 100	Fypical Characte 7.5 0.02 0.005 0.5 115 130 120 120 120	ristics ±0.0015 120 50	Bits %FSR ppm of FS/°C % ppm/°C % of FS % of FS dB dB dB dB dB	
Power-Supply Rejection VOLTAGE REFERENCE INPUTS	$\label{eq:f_SIG} \begin{split} f_{SIG} &= 60Hz, \ f_{DATA} = 60Hz \\ At \ DC, \ dB &= -20log(\Delta V_{OUT}/\Delta V_{DD})^{(3)} \end{split}$		100 88		dB dB	
Reference Input Range ADC V _{REF} Common-Mode Rejection Input Current ⁽⁴⁾ DAC Reference Current	$\begin{array}{l} {\rm REF~IN+,~REF~IN-}\\ {\rm V_{REF}\equiv(REF~IN+)-(REF~IN-)}\\ {\rm At~DC}\\ {\rm V_{REF}=2.5V,~ADC~Only}\\ {\rm For~Each~DAC,~5V~Reference} \end{array}$	0.0 0.3	2.5 110 10 25	AV _{DD} ⁽²⁾ AV _{DD}	V V dB μA μA	
ON-CHIP VOLTAGE REFERENCE Output Voltage Power-Supply Rejection Ratio Short-Circuit Current Source Short-Circuit Current Sink Short-Circuit Duration Drift Output Impedance Startup Time from Power ON Temperature Sensor	VREFH = 1 at +25°C, PGA = 1, 2, 4, 8 VREFH = 0 Sink or Source Sourcing 100 μ A C _{REFOUT} = 0.1 μ F T = +25°C	2.495	2.5 1.25 65 8 50 Indefinite 5 3 8	2.505	V V dB mA μA ppm/°C Ω ms	
Temperature Sensor Voltage Temperature Sensor Coefficient VOLTAGE DAC STATIC PERFORMANCE ⁽⁵⁾ Resolution	T = +25°C	16	115 375		mV μV/°C Bits	
Relative Accuracy Differential Nonlinearity Zero Code Error Full-Scale Error Gain Error Zero Code Error Drift Gain Temperature Coefficient	All 0s Loaded to DAC Register All 1s Loaded to DAC Register	-1.25 -1.25	±0.05 +13 0 0 ±20 ±5	±0.146 ±1 +35 +1.25	% LSB mV % of FSR % of FSR μV/°C ppm of FSR/°	



ELECTRICAL CHARACTERISTICS: AV_{DD} = 5V (Cont.)

All specifications from T_{MIN} to T_{MAX} , $DV_{DD} = +2.7V$ to 5.25V, $f_{MOD} = 15.625$ kHz, PGA = 1, Buffer ON, $f_{DATA} = 10$ Hz, Bipolar, and $V_{REF} = (REF IN+) - (REF IN-) = +2.5V$, unless otherwise noted. For V_{DAC} , $V_{REF} = AV_{DD}$, $R_{LOAD} = 10$ k Ω , and $C_{LOAD} = 200$ pF, unless otherwise noted.

			MSC1211Yx		
PARAMETER	CONDITION	MIN	TYP	MAX	UNITS
VOLTAGE DAC OUTPUT CHARACTERISTICS(6)					
Output Voltage Range		AGND		AV _{DD}	V
Output Voltage Settling Time	To $\pm 0.003\%$ FSR, 0200_{H} to FD00 _H		8		μs
Slew Rate			1		V/µs
DC Output Impedance			7		Ω
Short-Circuit Current	All 1s Loaded to DAC Register		20		mA
IDAC OUTPUT CHARACTERISTICS					
Full-Scale Output Current	Maximum V _{REF} = 2.5V		25		mA
Maximum Short-Circuit Current Duration			Indefinite		
Compliance Voltage			AV _{DD} – 1.5		V
Relative Accuracy	Over Full Range		0.185		% of FSR
Zero Code Error			0.5		% of FSR
Full-Scale Error			-0.4		% of FSR
Gain Error			-0.6		% of FSR
ANALOG POWER-SUPPLY REQUIREMENTS					
Power-Supply Voltage	AV _{DD}	4.75		5.25	V
Analog Current I _{ADC} + I _{VREF}	Analog OFF, PDAD = 1		< 1		nA
ADC Current I _{ADC}	PGA = 1, Buffer OFF		200		μΑ
	PGA = 128, Buffer OFF		500		μΑ
	PGA = 1, Buffer ON		240		μΑ
	PGA = 128, Buffer ON		850		μΑ
VDAC Current I _{VDAC}	Excluding Load Current External Reference		250		μΑ
V _{REF} Supply Current I _{VREF}	ADC ON, V _{DAC} OFF		250		μΑ

NOTES: (1) Calibration can minimize these errors. (2) The gain calibration cannot have a REF IN+ of more than $AV_{DD} - 1.5V$ with buffer ON. To calibrate gain, turn buffer off. (3) DV_{OUT} is change in digital result. (4) 12pF switched capacitor at f_{SAMP} clock frequency (see Figure 6). (5) Linearity calculated using a reduced code range of 512 to 65024; output unloaded. (6) Ensured by design and characterization, not production tested.

ELECTRICAL CHARACTERISTICS: $AV_{DD} = 3V$

All specifications from T_{MIN} to T_{MAX} , $AV_{DD} = +3V$, $DV_{DD} = +2.7V$ to 5.25V, $f_{MOD} = 15.625$ kHz, PGA = 1, Buffer ON, $f_{DATA} = 10$ Hz, Bipolar, and $V_{REF} \equiv (REF IN+) - (REF IN-) = +1.25V$, unless otherwise noted. For V_{DAC} , $V_{REF} = AV_{DD}$, $R_{LOAD} = 10$ k Ω , and $C_{LOAD} = 200$ pF, unless otherwise noted.

			MSC1211Yx		
PARAMETER	CONDITION	MIN	TYP	MAX	UNITS
ANALOG INPUT (AIN0-AIN7, AINCOM)					
Analog Input Range	Buffer OFF	AGND - 0.1		AV _{DD} + 0.1	V
	Buffer ON	AGND + 50mV		AV _{DD} – 1.5	V
Full-Scale Input Voltage Range	(In+) – (In–) See Figure 4			±V _{REF} /PGA	V
Differential Input Impedance	Buffer OFF		5/PGA		MΩ
Input Current	Buffer ON		0.5		nA
Bandwidth					
Fast Settling Filter	–3dB		0.469 • f _{DATA}		
Sinc ² Filter	–3dB		0.318 • f _{DATA}		
Sinc ³ Filter	–3dB		0.262 • f _{DATA}		
Programmable Gain Amplifier	User-Selectable Gain Ranges	1		128	
Input Capacitance	Buffer On		4		pF
Input Leakage Current	Multiplexer Channel Off, T = +25°C		0.5		pА
Burnout Current Sources	Sensor Input Open Circuit		±2		μΑ
ADC OFFSET DAC					
Offset DAC Range			±V _{RFF} /(2 • PGA)		V
Offset DAC Monotonicity		8			Bits
Offset DAC Gain Error			±1.5		% of Range
Offset DAC Gain Error Drift			1		ppm/°C
SYSTEM PERFORMANCE					
Resolution		24			Bits
ENOB			22		Bits
Output Noise		See -	Typical Characte	eristics	
No Missing Codes	Sinc ³ Filter	24		I	Bits
Integral Nonlinearity	End Point Fit, Differential Input			±0.0015	%FSR
Offset Error	After Calibration		7.5		ppm of FS
Offset Drift ⁽¹⁾	Before Calibration		0.02		ppm of FS/°C
Gain Error ⁽²⁾	After Calibration		0.005		%
Gain Error Drift ⁽¹⁾	Before Calibration		1.0		ppm/°C
System Gain Calibration Range		80		120	% of FS
System Offset Calibration Range		-50		50	% of FS





ELECTRICAL CHARACTERISTICS: AV_{DD} = 3V (Cont.)

All specifications from T_{MIN} to T_{MAX} , $AV_{DD} = +3V$, $DV_{DD} = +2.7V$ to 5.25V, $f_{MOD} = 15.625$ kHz, PGA = 1, Buffer ON, $f_{DATA} = 10$ Hz, and Bipolar, $V_{REF} \equiv (REF IN+) - (REF IN-) = +1.25V$, unless otherwise noted. For V_{DAC} , $V_{REF} = AV_{DD}$, $R_{LOAD} = 10$ k Ω , and $C_{LOAD} = 200$ pF, unless otherwise noted.

			MSC1211Yx		-	
PARAMETER	CONDITION	MIN	TYP MAX		UNITS	
SYSTEM PERFORMANCE (Cont.) Common-Mode Rejection Normal Mode Rejection	$\begin{array}{c} \text{At DC} \\ f_{\text{CM}} = 60\text{Hz}, f_{\text{DATA}} = 10\text{Hz} \\ f_{\text{CM}} = 50\text{Hz}, f_{\text{DATA}} = 50\text{Hz} \\ f_{\text{CM}} = 60\text{Hz}, f_{\text{DATA}} = 60\text{Hz} \\ f_{\text{SIG}} = 50\text{Hz}, f_{\text{DATA}} = 50\text{Hz} \end{array}$	100	115 130 120 120 100		dB dB dB dB dB	
Power-Supply Rejection	$f_{SIG} = 60Hz$, $f_{DATA} = 60Hz$ At DC, dB = $-20log(DV_{OUT}/DV_{DD})^{(3)}$		100 85		dB dB	
VOLTAGE REFERENCE INPUTS Reference Input Range ADC V _{REF} Common-Mode Rejection Input Current ⁽⁴⁾	$\begin{array}{c} \text{REF IN+, REF IN-} \\ \text{V}_{\text{REF}} \equiv (\text{REF IN+}) - (\text{REF IN-}) \\ \text{At DC} \\ \text{V}_{\text{REF}} = 1.25\text{V}, \text{ADC Only} \end{array}$	0.0 0.3	1.25 110 10	AV _{DD} ⁽²⁾ AV _{DD}	V V dB μA	
DAC Reference Current	For each DAC, 3V Reference		25		μA	
ON-CHIP VOLTAGE REFERENCE Output Voltage Power-Supply Rejection Ratio Short-Circuit Current Source Short-Circuit Current Sink	VREFH = 0 at +25°C, PGA = 1, 2, 4, 8	1.245	1.25 65 2.6 50	1.255	V dB mA μA	
Short-Circuit Duration Drift Output Impedance Startup Time from Power ON Temperature Sensor	Sink or Source Sourcing 100μA C _{REFOUT} = 0.1μF		Indefinite 5 3 8		ppm/°C Ω ms	
Temperature Sensor Voltage Temperature Sensor Coefficient	T = +25°C		115 375		mV μV/°C	
VOLTAGE DAC STATIC PERFORMANCE ⁽⁵⁾ Resolution Relative Accuracy Differential Nonlinearity Zero Code Error Full-Scale Error Gain Error Zero Code Error Drift Gain Temperature Coefficient	Ensured Monotonic by Design All 0s Loaded to DAC Register All 1s Loaded to DAC Register	16 -1.25 -1.25	±0.05 +13 0 ±20 ±5	±0.146 ±1 +35 ±1.25	Bits % of FSR LSB mV % of FSR % of FSR µV/°C ppm of FSR/	
VOLTAGE DAC OUTPUT CHARACTERISTICS ⁽⁶⁾ Output Voltage Range Output Voltage Settling Time Slew Rate DC Output Impedance	To $\pm 0.003\%$ FSR, 0200_{H} to FD00_{H}	AGND	8 1 7	AV _{DD}	V μs V/μs Ω	
Short-Circuit Current	All 1s Loaded to DAC Register		16		mA	
IDAC OUTPUT CHARACTERISTICS Full-Scale Output Current Maximum Short-Circuit Current Duration Compliance Voltage Relative Accuracy Zero Code Error Full-Scale Error Gain Error	Maximum V _{REF} = 2.5V Over Full Range		25 Indefinite AV _{DD} - 1.5 0.185 0.5 -0.4 -0.6		mA % of FSR % of FSR % of FSR % of FSR	
POWER-SUPPLY REQUIREMENTS Power-Supply Voltage Analog Current I _{ADC} + I _{VREF} ADC Current I _{ADC} VDAC Current I _{VDAC} V _{REF} Current I _{VREF}	AV _{DD} Analog OFF, PDAD = 1 PGA = 1, Buffer OFF PGA = 128, Buffer OFF PGA = 1, Buffer ON PGA = 128, Buffer ON Excluding Load Current External Reference	2.7	< 1 200 500 240 850 250 250	3.6	V nA μA μA μA μA	

NOTES: (1) Calibration can minimize these errors. (2) The gain calibration cannot have a REF IN+ of more than $AV_{DD} - 1.5V$ with buffer ON. To calibrate gain, turn buffer off. (3) DV_{OUT} is change in digital result. (4) 12pF switched capacitor at f_{SAMP} clock frequency (see Figure 6). (5) Linearity calculated using a reduced code range of 512 to 65024; output unloaded. (6) Ensured by design and characterization, not production tested.



DIGITAL CHARACTERISTICS: $DV_{DD} = 2.7V$ to 5.25V

All specifications from T_{MIN} to $T_{\text{MAX}},$ unless otherwise specified.

		MSC1211Yx		[
PARAMETER	CONDITION	MIN	ТҮР	MAX	UNITS
POWER-SUPPLY REQUIREMENTS					
	DV _{DD}	2.7		3.6	V
	Normal Mode, f _{OSC} = 1MHz		1.3		mA
	Normal Mode, f _{OSC} = 8MHz		6		mA
	Stop Mode		100		nA
	DV _{DD}	4.75		5.25	V
	Normal Mode, f _{OSC} = 1MHz		2.2		mA
	Normal Mode, f _{OSC} = 8MHz		14		mA
	Stop Mode		100		nA
DIGITAL INPUT/OUTPUT (CMOS)					
Logic Level: V _{IH} (except XIN pin)		0.6 • DV _{DD}		DV _{DD}	V
V _{IL} (except XIN pin)		DGND		0.2 • DV _{DD}	V
Ports 0-3, Input Leakage Current, Input Mode	$V_{IH} = DV_{DD}$ or $V_{IH} = 0V$	-10	0	+10	μA
Pins EA, XIN Input Leakage Current			0		μA
V _{OL} , ALE, PSEN, Ports 0-3, All Output Modes	I _{OL} = 1mA	DGND		0.4	V
V _{OL} , ALE, PSEN, Ports 0-3, All Output Modes	I _{OL} = 30mA, 3V (20mA)		1.5		V
V _{OH} , ALE, PSEN, Ports 0-3, Strong Drive Output	I _{OH} = 1mA	DV _{DD} - 0.4	DV _{DD} - 0.1	DV _{DD}	V
V _{OH} , ALE, PSEN, Ports 0-3, Strong Drive Output	I _{OH} = 30mA, 3V (20mA)		DV _{DD} – 1.5		V
Ports 0-3 Pull-Up Resistors			9		kΩ
Pins ALE, PSEN, Pull-Up Resistors	Flash Programming Mode Only		9		kΩ
Pin RST, Pull-Down Resistor			200		kΩ

FLASH MEMORY CHARACTERISTICS: $DV_{DD} = 2.7V$ to 5.25V

 $t_{USEC} = 1\mu s, t_{MSEC} = 1ms$

		MSC1211Yx			
PARAMETER	CONDITION	MIN	ТҮР	МАХ	UNITS
Flash Memory Endurance		100,000	1,000,000		cycles
Flash Memory Data Retention		100			Years
Mass and Page Erase Time	Set with FER Value in FTCON	10			ms
Flash Memory Data Retention	Set with FWR Value in FTCON	30		40	μs



AC ELECTRICAL CHARACTERISTICS⁽¹⁾⁽²⁾: $DV_{DD} = 2.7V$ to 5.25V

			2.7V 1	to 3.6V	4.75V to 5.25V		, 5.25V	
SYMBOL	FIGURE	PARAMETER	MIN	MAX	MIN	MAX	UNITS	
System Clock								
f _{OSC} ⁽³⁾	D	External Crystal Frequency (f _{OSC})	1	16	1	30	MHz	
1/t _{OSC} ⁽³⁾	D	External Clock Frequency (f _{OSC})	0	16	1	30	MHz	
f _{OSC} ⁽³⁾	D	External Ceramic Resonator Frequency (f _{OSC})	1	12	1	12	MHz	
Program Memory								
t _{LHLL}	A	ALE Pulse Width	1.5t _{CLK} – 5		1.5t _{CLK} – 5		ns	
t _{AVLL}	A	Address Valid to ALE LOW	0.5t _{CLK} – 10		0.5t _{CLK} – 7		ns	
t _{LLAX}	A	Address Hold After ALE LOW	0.5t _{CLK}		0.5t _{CLK}		ns	
t _{LLIV}	A	ALE LOW to Valid Instruction In		2.5t _{CLK} – 35		2.5t _{CLK} – 25	ns	
t _{LLPL}	A	ALE LOW to PSEN LOW	0.5t _{CLK}		0.5t _{CLK}		ns	
t _{PLPH}	A	PSEN Pulse Width	2t _{CLK} – 5		2t _{CLK} – 5		ns	
t _{PLIV}	A	PSEN LOW to Valid Instruction In		2t _{CLK} – 40		2t _{CLK} – 30	ns	
t _{PXIX}	A	Input Instruction Hold After PSEN	5		-5		ns	
t _{PXIZ}	Α	Input Instruction Float After PSEN		t _{CLK} – 5		t _{CLK}	ns	
t _{AVIV}	A	Address to Valid Instruction In		3t _{CLK} – 40		3t _{CLK} – 25	ns	
t _{PLAZ}	A	PSEN LOW to Address Float		0		0	ns	
Data Memory								
t _{RLRH}	В	$\overline{\text{RD}}$ Pulse Width $(t_{\text{MCS}} = 0)^{(4)}$	2t _{CLK} – 5		2t _{CLK} – 5		ns	
	В	$\overline{\text{RD}}$ Pulse Width (t _{MCS} > 0) ⁽⁴⁾	t _{MCS} – 5		t _{MCS} – 5		ns	
t _{WLWH}	С	$\overline{\text{WR}}$ Pulse Width (t _{MCS} = 0) ⁽⁴⁾	2t _{CLK} – 5		2t _{CLK} – 5		ns	
	С	Pulse Width $(t_{MCS} > 0)^{(4)}$	t _{MCS} – 5		$t_{\text{MCS}} - 5$		ns	
t _{RLDV}	В	$\overline{\text{RD}}$ LOW to Valid Data In $(t_{\text{MCS}} = 0)^{(4)}$		2t _{CLK} - 40		2t _{CLK} – 30	ns	
	В	$\overline{\text{RD}}$ LOW to Valid Data In $(t_{\text{MCS}} > 0)^{(4)}$		t _{MCS} - 40		t _{MCS} - 30	ns	
t _{RHDX}	В	Data Hold After Read	-5		-5		ns	
t _{RHDZ}	В	Data Float After Read $(t_{MCS} = 0)^{(4)}$		t _{CLK}		t _{CLK}	ns	
	В	Data Float After Read $(t_{MCS} > 0)^{(4)}$		2t _{CLK}		2t _{CLK}	ns	
t _{LLDV}	В	ALE LOW to Valid Data In $(t_{MCS} = 0)^{(4)}$		2.5t _{CLK} – 40		2.5t _{CLK} – 25	ns	
	В	ALE LOW to Valid Data In $(t_{MCS} > 0)^{(4)}$		$t_{CLK} + t_{MCS} - 40$		$t_{CLK} + t_{MCS} - 25$	ns	
t _{AVDV}	В	Address to Valid Data In $(t_{MCS} = 0)^{(4)}$		3t _{CLK} – 40		3t _{CLK} – 25	ns	
	В	Address to Valid Data In $(t_{MCS} > 0)^{(4)}$		$1.5t_{CLK} + t_{MCS} - 40$		$1.5t_{CLK} + t_{MCS} - 25$	ns	
t _{LLWL}	B, C	ALE LOW to \overline{RD} or \overline{WR} LOW $(t_{MCS} = 0)^{(4)}$	0.5t _{CLK} – 5	0.5t _{CLK} + 5	0.5t _{CLK} – 5	0.5t _{CLK} + 5	ns	
	B, C	ALE LOW to \overline{RD} or \overline{WR} LOW $(t_{MCS} > 0)^{(4)}$	t _{CLK} – 5	t _{CLK} + 5	t _{CLK} – 5	t _{CLK} + 5	ns	
t _{AVWL}	B, C	Address to \overline{RD} or \overline{WR} LOW $(t_{MCS} = 0)^{(4)}$	t _{CLK} – 5		$t_{CLK} - 5$		ns	
	B, C	Address to \overline{RD} or \overline{WR} LOW $(t_{MCS} > 0)^{(4)}$	2t _{CLK} – 5		2t _{CLK} – 5		ns	
t _{QVWX}	С	Data Valid to WR Transition	-8		-5		ns	
t _{WHQX}	С	Data Hold After WR	t _{CLK} – 8		t _{CLK} – 5		ns	
t _{RLAZ}	В	RD LOW to Address Float		-0.5t _{CLK} - 5		-0.5t _{CLK} - 5	ns	
t _{WHLH}	B, C	$\overline{\text{RD}}$ or $\overline{\text{WR}}$ HIGH to ALE HIGH $(t_{\text{MCS}} = 0)^{(4)}$	-5	5	-5	5	ns	
	В, С	$\overline{\text{RD}}$ or $\overline{\text{WR}}$ HIGH to ALE HIGH $(t_{\text{MCS}} > 0)^{(4)}$	t _{CLK} – 5	t _{CLK} + 5	t _{CLK} – 5	t _{CLK} + 5	ns	
External Clock								
t _{HIGH}	D	HIGH Time ⁽⁵⁾	15		10		ns	
t _{LOW}	D	LOW Time ⁽⁵⁾	15		10		ns	
t _R	D	Rise Time ⁽⁵⁾		5		5	ns	
							ns	
t _F	D	Fall Time ⁽⁵⁾		5		5		

NOTES: (1) Parameters are valid over operating temperature range, unless otherwise specified. (2) Load capacitance for Port 0, ALE, and $\overrightarrow{\text{PSEN}}$ = 100pF, load capacitance for all other outputs = 80pF. (3) t_{CLK} = 1/f_{OSC} = one oscillator clock period for clock divider = 1. (4) t_{MCS} is a time period related to the Stretch MOVX selection. The following table shows the value of t_{MCS} for each stretch selection. (5) These values are characterized but not 100% production tested.

MD2	MD1	MD0	MOVX DURATION	t _{MCS}
0	0	0	2 Machine Cycles	0
0	0	1	3 Machine Cycles (default)	4t _{CLK}
0	1	0	4 Machine Cycles	8t _{CLK}
0	1	1	5 Machine Cycles	12t _{CLK}
1	0	0	6 Machine Cycles	16t _{CLK}
1	0	1	7 Machine Cycles	20t _{CLK}
1	1	0	8 Machine Cycles	24t _{CLK}
1	1	1	9 Machine Cycles	28t _{CLK}

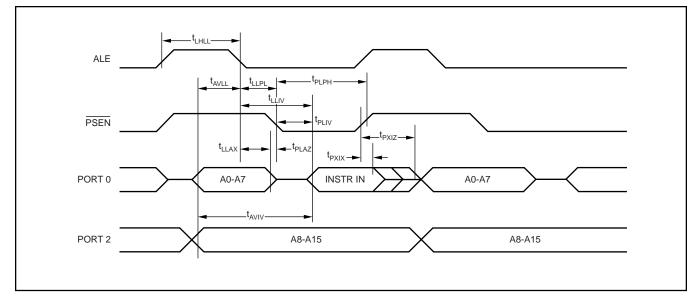


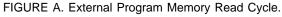
EXPLANATION OF THE AC SYMBOLS

Each Timing Symbol has five characters. The first character is always 't' (= time). The other characters, depending on their positions, indicate the name of a signal or the logical status of that signal. The designators are:

- A—Address
- C—Clock
- D-Input Data
- H—Logic Level HIGH
- I-Instruction (program memory contents)
- L-Logic Level LOW, or ALE
- P-PSEN
- Q-Output Data

R—RD Signal t—Time V—Valid W—WR Signal X—No Longer a Valid Logic Level Z—Float Examples: (1) t_{AVIL} = Time for address valid to ALE LOW. (2) t_{LLPL} = Time for ALE LOW to PSEN LOW.





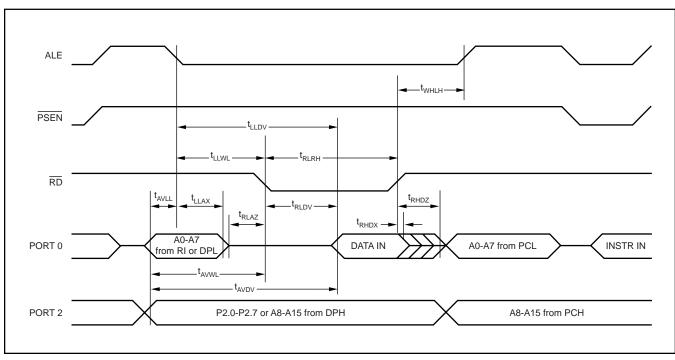


FIGURE B. External Data Memory Read Cycle.

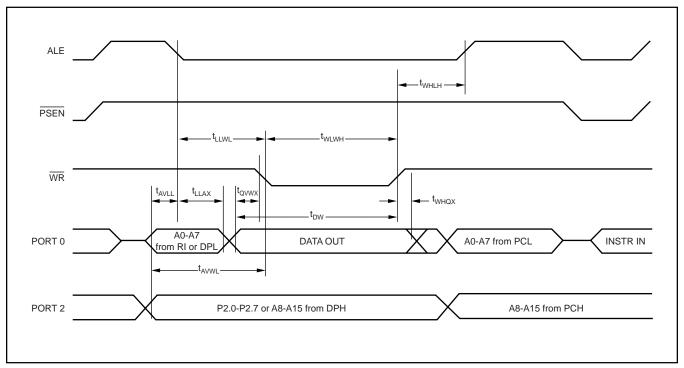


FIGURE C. External Data Memory Write Cycle.

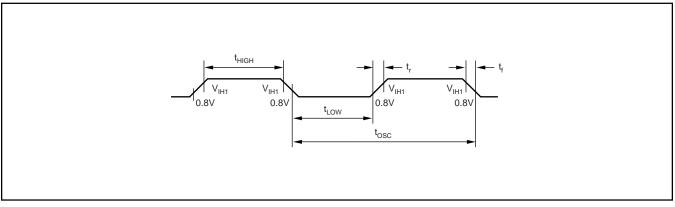


FIGURE D. External Clock Drive CLK.



RESET AND POWER-ON TIMING

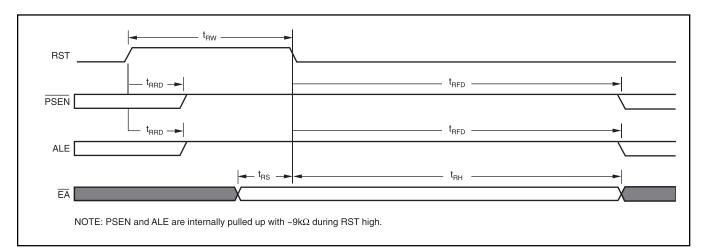


FIGURE E. Reset Timing.

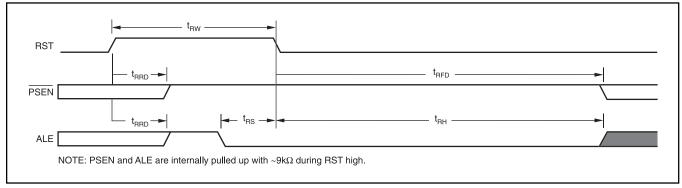


FIGURE F. Parallel Flash Programming Power-On Timing (\overline{EA} is ignored).

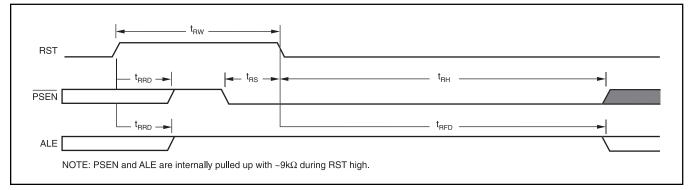
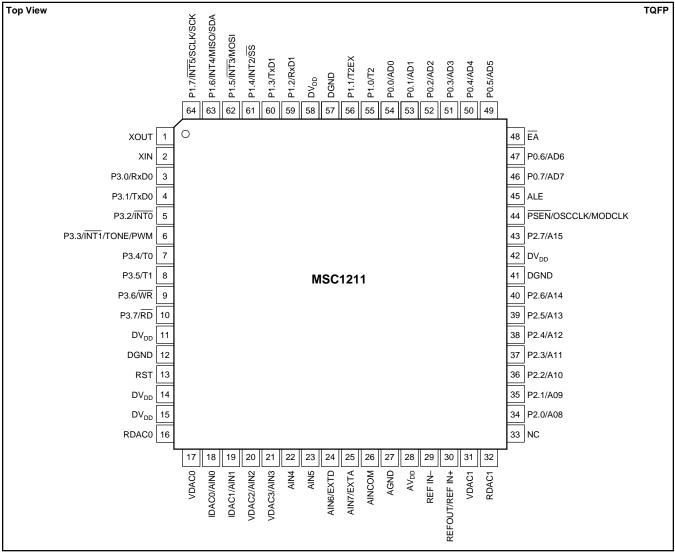


FIGURE G. Serial Flash Programming Power-On Timing (\overline{EA} is ignored).

SYMBOL	PARAMETER	MIN	МАХ	UNIT
t _{RW}	RST width	2 t _{osc}	—	ns
t _{RRD}	RST rise to PSEN ALE internal pull high	—	5	μs
t _{RFD}	RST falling to PSEN and ALE start	_	(2 ¹⁷ + 512) t _{OSC}	ns
t _{RS}	Input signal to RST falling setup time	tosc	—	ns
t _{RH}	RST falling to input signal hold time	(2 ¹⁷ + 512) t _{OSC}	—	ns







PIN DESCRIPTIONS

PIN #	NAME	DESCRIPTION						
1	XOUT	The crystal oscillator pin XOUT supports parallel resonant AT cut crystals and ceramic resonators. XOUT serves as the output of the crystal amplifier.						
2	XIN	The crystal oscillator pin XIN supports parallel resonant AT cut crystals and ceramic resonators. XIN can also be an input if there is an external clock source instead of a crystal.						
3-10	P3.0-P3.7	ort 3 is a bidirectional I/O port. The alternate functions for Port 3 are listed below. Fort 3—Alternate Functions:						
		PORT ALTERNATE MODE						
		P3.0 RxD0 Serial Port 0 Input						
		P3.1 TxD0 Serial Port 0 Output						
		P3.2 INTO External Interrupt 0						
		P3.3 INT1/TONE/PWM External Interrupt 1/TONE/PWM Output						
		P3.4 T0 Timer 0 External Input						
		P3.5 T1 Timer 1 External Input						
		P3.6 WR External Data Memory Write Strobe						
		P3.7 RD External Data Memory Read Strobe						
11, 14, 15, 42, 58	DV _{DD}	Digital Power Supply						
12, 41, 57	DGND	Digital Ground						
13	RST	A HIGH on the reset input for two t _{OSC} periods will reset the device.						
16	RDAC0	RDAC0 Output						
17	VDAC0	VDAC0 Output						
27	AGND	Analog Ground						
18	IDAC0/AIN0	IDAC0 Output/Analog Input Channel 0						
19	IDAC1/AIN1	IDAC1 Output/Analog Input Channel 1						



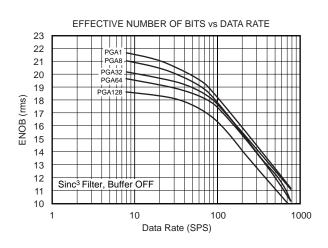
PIN DESCRIPTIONS (Cont.)

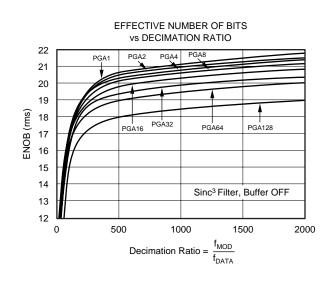
PIN #	NAME	DESCRIPTION							
20	VDAC2/AIN2	VDAC2 Output/Analog Input	Channel	2					
20	VDAC3/AIN3	VDAC3 Output/Analog Input							
22	AIN4	Analog Input Channel 4	onanner	0					
23	AIN5	Analog Input Channel 5							
24	AIN6, EXTD	Analog Input Channel 6, Lov	w Voltage	Detect Int	out Ger	erates DLVD Interrup	t		
25	AIN7, EXTA	Analog Input Channel 7, Lo	-						
26	AINCOM	Analog Common for Single-	Ŭ,						
28	AV _{DD}	Analog Power Supply							
29	REF IN-	Voltage Reference Negative	Input						
30	REFOUT/REF IN+	Voltage Reference Output/	Voltage Re	eference P	Positive	Input			
31	VDAC1	VDAC1 Output	DAC1 Output						
32	RDAC1	RDAC1 Output	DAC1 Output						
33	NC	No Connection	lo Connection						
34-40, 43	P2.0-P2.7		Port 2 is a bidirectional I/O port. The alternate functions for Port 2 are listed below. Port 2—Alternate Functions:						
			PORT	ALTER	NATE	MODE			
			P2.0	A	8	Address Bit 8			
			P2.1	AS		Address Bit 9			
			P2.2 P2.3	A1		Address Bit 10 Address Bit 11			
			P2.4	A1		Address Bit 12			
			P2.5	A1		Address Bit 13			
			P2.6	A1		Address Bit 14			
			P2.7	A1	5	Address Bit 15			
	OSCCLK MODCLK	In programming mode, PSE PSEN is held HIGH for para using external memory) to o	allel progra	amming an Oscillator	nd tied clock, N	LOW for serial program Nodulator clock, HIGH	nming. This pin can also , or LOW for light loads.	-	
			ALE	PSEN					
			NC 0	NC NC		al Operation (user app el Programming	lication mode)		
			NC	0		Programming			
			0	0	Reser				
45	ALE	Address Latch Enable: Used at a constant rate of 1/2 the during each access to exter serial or parallel programmin pin can also be selected (with	e oscillator nal data m ng mode.	frequency nemory. In ALE is hel	/, and c progra	an be used for extern mming mode, ALE is I for serial programmir	al timing or clocking. On used as an input along v ng and tied LOW for para	e ALE pulse is skipped with PSEN to define	
48	ĒĀ	External Access Enable: EA locations starting with 0000 _F		externally	held L	OW to enable the dev	ice to fetch code from ex	ternal program memory	
46, 47, 49-54	P0.0-P0.7	Port 0 is a bidirectional I/O	port. The a	alternate f	unction	s for Port 0 are listed	below.		
		Port 0—Alternate Functions	PORT	ALTER	NATE	MODE	7		
			P0.0	AD	0	Address/Data Bit 0			
			P0.1	AD		Address/Data Bit 1			
			P0.2 P0.3	AD AD		Address/Data Bit 2 Address/Data Bit 3			
			P0.4	AD		Address/Data Bit 4			
			P0.5	AD		Address/Data Bit 5			
			P0.6 P0.7	AD AD		Address/Data Bit 6 Address/Data Bit 7			
			1 0.7	, no		/ ddie35/Data Dit /			
55, 56, 59-64	P1.0-P1.7	Port 1 is a bidirectional I/O	port. The a	alternate f	unction	s for Port 1 are listed	below.		
		Port 1—Alternate Functions:	PORT	ALTER	NATE	MODE			
			P1.0	Tź		T2 Input			
			P1.1	T2E		T2 External Input			
			P1.2 P1.3	RxI TxI		Serial Port Input Serial Port Output			
			P1.4	INT2		External Interrupt/Sla	ave Select		
			P1.5	INT3/	MOSI	External Interrupt/Ma	aster Out-Slave In		
			P1.6				aster In-Slave Out/SDA		
			P1.7	INT5/	SUK	External Interrupt/Se]	



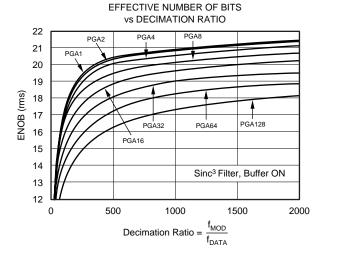
TYPICAL CHARACTERISTICS

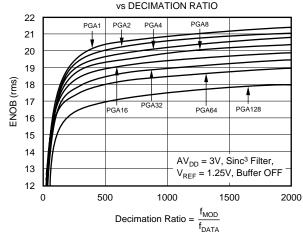
 $AV_{DD} = +5V$, $DV_{DD} = +5V$, $f_{OSC} = 8MHz$, PGA = 1, $f_{MOD} = 15.625kHz$, Bipolar, Buffer On, and $V_{REF} = (REF IN+) - (REF IN-) = +2.5V$, unless otherwise specified. For V_{DAC} , $V_{REF} = AV_{DD}$, $R_{LOAD} = 10k\Omega$, and $C_{LOAD} = 200$ pF, unless otherwise noted.

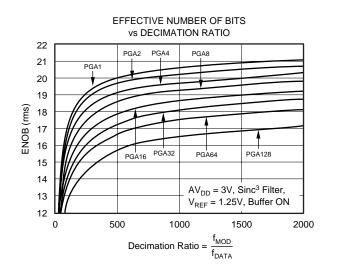




EFFECTIVE NUMBER OF BITS vs DECIMATION RATIO



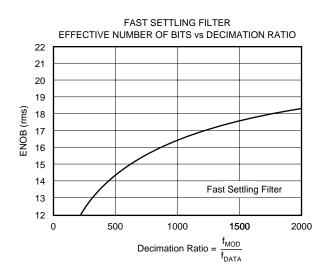


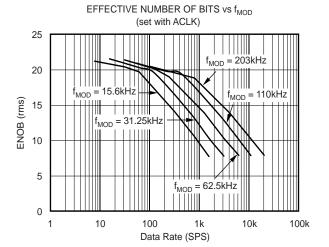


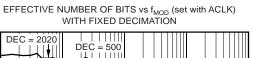
EFFECTIVE NUMBER OF BITS vs DECIMATION RATIO 22 PGA2 PGA4 PGA8 21 PGA 20 19 ENOB (rms) 18 17 PGA32 PGA16 PGA64 PGA128 16 15 14 Sinc² Filter 13 12 500 0 1000 1500 2000 f_{MOD} Decimation Ratio = f_{DATA}

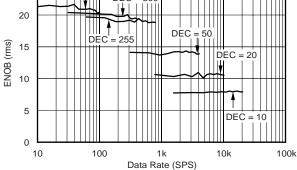


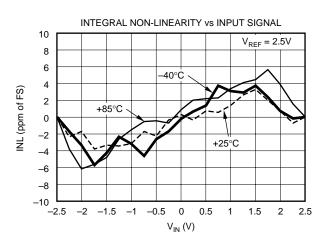
 $AV_{DD} = +5V, DV_{DD} = +5V, f_{OSC} = 8MHz, PGA = 1, f_{MOD} = 15.625 \text{kHz}, Bipolar, Buffer On, and V_{REF} = (REF IN+) - (REF IN-) = +2.5V, unless otherwise specified.$ For $V_{DAC}, V_{REF} = AV_{DD}, R_{LOAD} = 10 \text{k}\Omega$, and $C_{LOAD} = 200 \text{pF}$, unless otherwise noted.

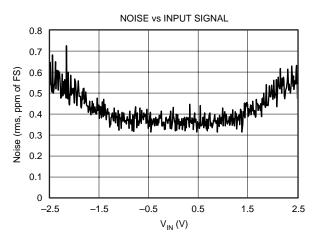


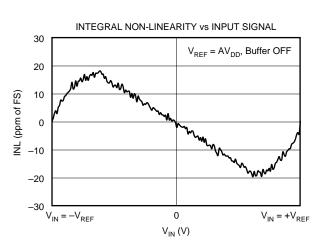








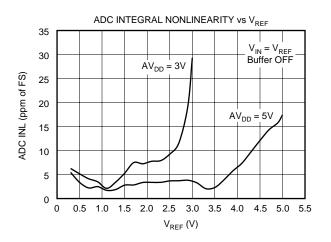


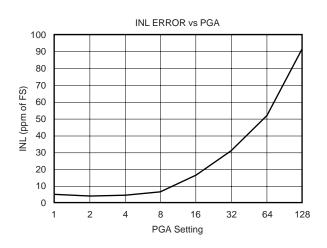


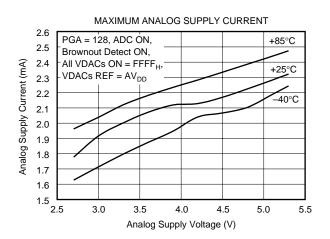


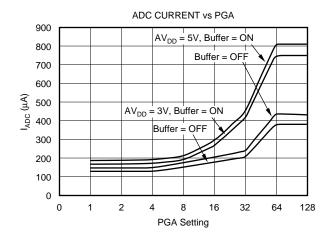
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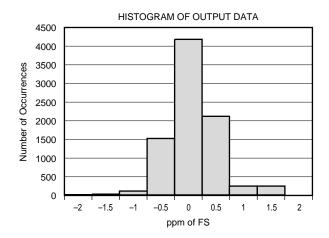
 $AV_{DD} = +5V, DV_{DD} = +5V, f_{OSC} = 8MHz, PGA = 1, f_{MOD} = 15.625kHz, Bipolar, Buffer On, and V_{REF} = (REF IN+) - (REF IN-) = +2.5V, unless otherwise specified.$ For $V_{DAC}, V_{REF} = AV_{DD}, R_{LOAD} = 10k\Omega$, and $C_{LOAD} = 200pF$, unless otherwise noted.

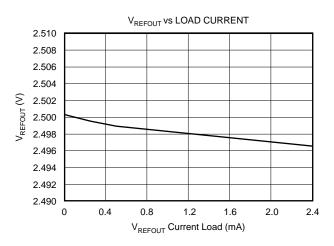






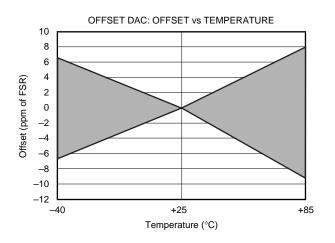


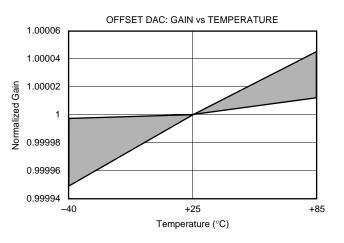


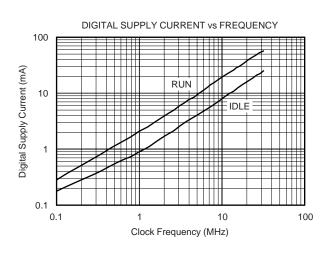


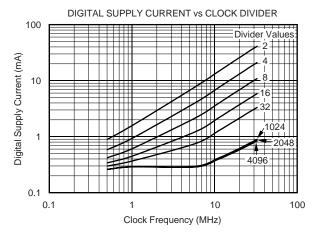


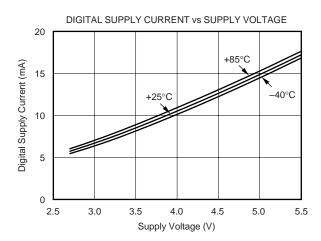
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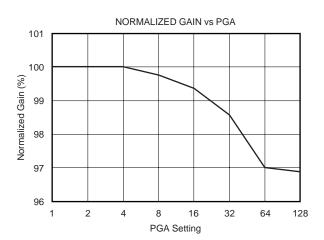






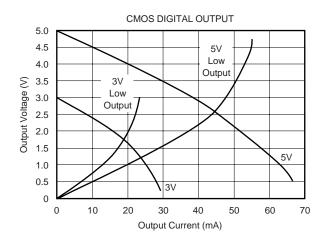


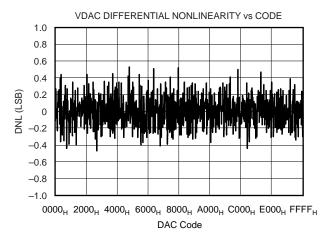


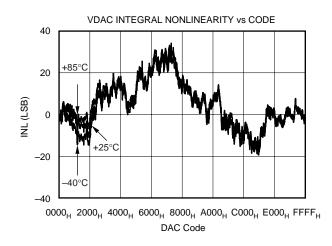


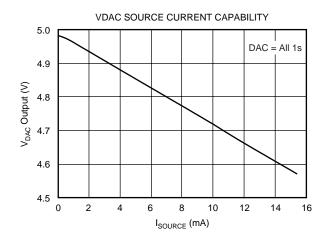


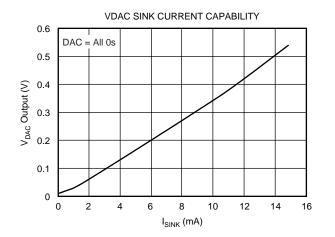
 $AV_{DD} = +5V, DV_{DD} = +5V, f_{OSC} = 8MHz, PGA = 1, f_{MOD} = 15.625 \text{kHz}, Bipolar, Buffer On, and V_{REF} = (REF IN+) - (REF IN-) = +2.5V, unless otherwise specified.$ For $V_{DAC}, V_{REF} = AV_{DD}, R_{LOAD} = 10 \text{k}\Omega$, and $C_{LOAD} = 200 \text{pF}$, unless otherwise noted.

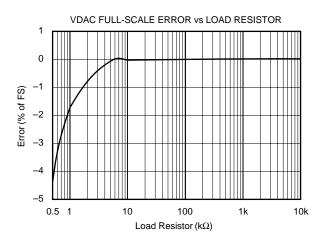






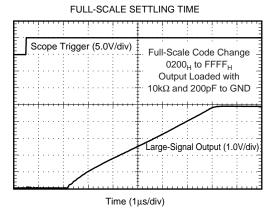


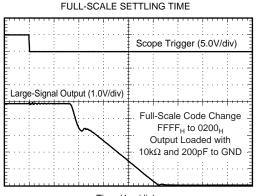




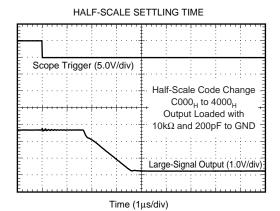


 $AV_{DD} = +5V, DV_{DD} = +5V, f_{OSC} = 8MHz, PGA = 1, f_{MOD} = 15.625kHz, Bipolar, Buffer On, and V_{REF} = (REF IN+) - (REF IN-) = +2.5V, unless otherwise specified.$ For $V_{DAC}, V_{REF} = AV_{DD}, R_{LOAD} = 10k\Omega$, and $C_{LOAD} = 200pF$, unless otherwise noted.





Time (1µs/div)



HALF-SCALE SETTLING TIME

Half-Scale Code Change 4000 _H to C000 _H
Output Loaded with $10k\Omega$ and $200pF$ to GND

Time (1µs/div)



DESCRIPTION

The MSC1211Yx is a completely integrated family of mixedsignal devices incorporating a high-resolution delta-sigma ADC, quad 16-bit DACs, 8-channel multiplexer, burnout detect current sources, selectable buffered input, offset DAC (Digital-to-Analog Converter), Programmable Gain Amplifier (PGA), temperature sensor, voltage reference, 8-bit microcontroller, Flash Program Memory, Flash Data Memory, and Data SRAM, as shown in Figure 1.

On-chip peripherals include an additional 32-bit accumulator, an SPI compatible serial port with FIFO, I²C, dual UARTs, multiple digital input/output ports, watchdog timer, low-voltage detect, on-chip power-on reset, 16-bit PWM, breakpoints, brownout reset, three timer/counters, and a system clock divider.

The device accepts low-level differential or single-ended signals directly from a transducer. The ADC provides 24 bits of resolution and 24 bits of no-missing-code performance using a sinc³ filter with a programmable sample rate. The ADC also has a selectable filter that allows for high-resolution single-cycle conversion.

The microcontroller core is 8051 instruction set compatible. The microcontroller core is an optimized 8051 core which executes up to three times faster than the standard 8051 core, given the same clock source. That makes it possible to run the device at a lower external clock frequency and achieve the same performance at lower power than the standard 8051 core.

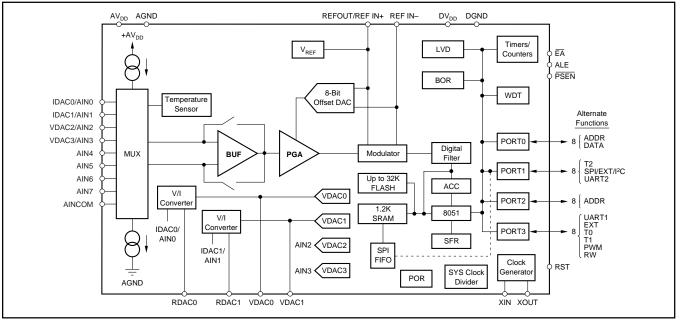
The MSC1211Yx allows the user to uniquely configure the Flash and SRAM memory maps to meet the needs of their application. The Flash is programmable down to 2.7V using both serial and parallel programming methods. The Flash endurance is 100k Erase/Write cycles. In addition, 1280 bytes of RAM are incorporated on-chip.

The part has separate analog and digital supplies, which can be independently powered from 2.7V to +5.5V. At +3V operation, the power dissipation for the part is typically less than 4mW. The MSC1211Yx is packaged in a TQFP-64 package.

The MSC1211Yx is designed for high-resolution measurement applications in smart transmitters, industrial process control, weigh scales, chromatography, and portable instrumentation.

ENHANCED 8051 CORE

All instructions in the MSC1211 family perform exactly the same functions as they would in a standard 8051. The effect on bits, flags, and registers is the same. However, the timing is different. The MSC1211 family utilizes an efficient 8051 core which results in an improved instruction execution speed of between 1.5 and 3 times faster than the original core for the same external clock speed (4 clock cycles per instruction versus 12 clock cycles per instruction, as shown in Figure 2). This translates into an effective throughput improvement of more than 2.5 times, using the same code and same external clock speed. Therefore, a device frequency of 30MHz for the MSC1211Yx actually performs at an





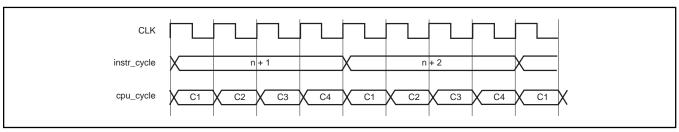


FIGURE 2. Instruction Cycle Timing.



equivalent execution speed of 75MHz compared to the standard 8051 core. This allows the user to run the device at slower external clock speeds which reduces system noise and power consumption, but provides greater throughput. This performance difference can be seen in Figure 3. The timing of software loops will be faster with the MSC1211. However, the timer/counter operation of the MSC1211 may be maintained at 12 clocks per increment or optionally run at 4 clocks per increment.

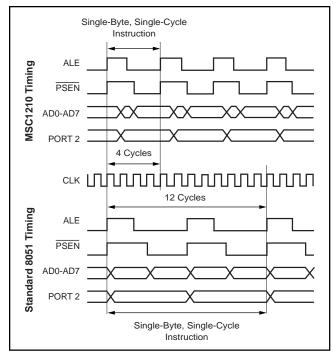


FIGURE 3. Comparison of MSC1211 Timing to Standard 8051 Timing.

The MSC1211 also provides dual data pointers (DPTRs) to speed block Data Memory moves.

Additionally, it can stretch the number of memory cycles to access external Data Memory from between two and nine instruction cycles in order to accommodate different speeds of memory or devices, as shown in Table I. The MSC1211 provides an external memory interface with a 16-bit address bus (P0 and P2). The 16-bit address bus makes it necessary to multiplex the low address byte through the P0 port. To enhance P0 and P2 for high-speed memory access, hardware configuration control is provided to configure the ports for external memory/peripheral interface or general-purpose I/O.

CKCON (8E _H) MD2:MD0	INSTRUCTION CYCLES (for MOVX)	RD or WR STROBE WIDTH (SYS CLKs)	RD or WR STROBE WIDTH (µs) AT 12MHz
000	2	2	0.167
001	3 (default)	4	0.333
010	4	8	0.667
011	5	12	1.000
100	6	16	1.333
101	7	20	1.667
110	8	24	2.000
111	9	28	2.333

TABLE I. Memory Cycle Stretching. Stretching of MOVX timing as defined by MD2, MD1, and MD0 bits in CKCON register (address 8E_H).

Furthermore, improvements were made to peripheral features that offload processing from the core, and the user, to further improve efficiency. For instance, the SPI interface uses a FIFO, which allows the SPI interface to transmit and receive data with minimum overhead needed from the core. Also, a 32-bit accumulator was added to significantly reduce the processing overhead for the multiple byte data from the ADC or other sources. This allows for 24-bit addition and shifting to be accomplished in a few instruction cycles, compared to hundreds of instruction cycles through software implementation.

Family Device Compatibility

The hardware functionality and pin configuration across the MSC1211 family is fully compatible. To the user the only difference between family members is the memory configuration. This makes migration between family members simple. Code written for the MSC1211Y2 can be executed directly on an MSC1211Y3, MSC1211Y4, or MSC1211Y5. This gives the user the ability to add or subtract software functions and to freely migrate between family members. Thus, the MSC1211 can become a standard device used across several application platforms.

Family Development Tools

The MSC1211 is fully compatible with the standard 8051 instruction set. This means that the user can develop software for the MSC1211 with their existing 8051 development tools. Additionally, a complete, integrated development environment is provided with each demo board, and third-party developers also provide support.

Power Down Modes

The MSC1211 can power several of the peripherals and put the CPU into IDLE. This is accomplished by shutting off the clocks to those sections, as shown in Figure 4.

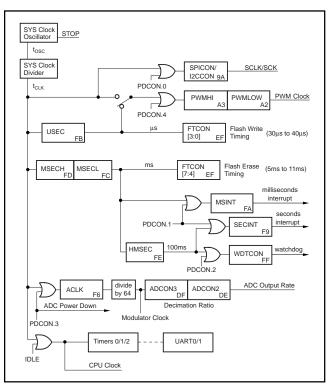


FIGURE 4. MSC1211 Timing Chain and Clock Control.



OVERVIEW

INPUT MULTIPLEXER

The input multiplexer provides for any combination of differential inputs to be selected as the input channel, as shown in Figure 5. If AINO is selected as the positive differential input channel, any other channel can be selected as the negative differential input channel. With this method, it is possible to have up to eight fully differential input channels. It is also possible to switch the polarity of the differential input pair to negate any offset voltages.

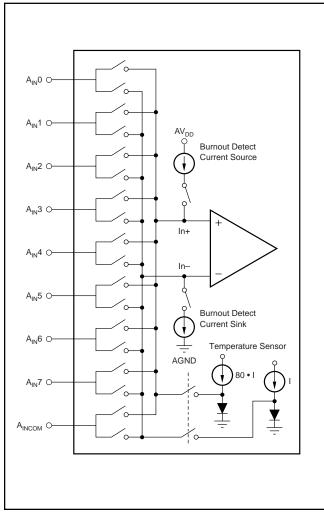


FIGURE 5. Input Multiplexer Configuration.

In addition, current sources are supplied that will source or sink current to detect open or short circuits on the pins.

TEMPERATURE SENSOR

On-chip diodes provide temperature sensing capability. When the configuration register for the input MUX is set to all 1s, the diodes are connected to the input of the ADC. All other channels are open.

BURNOUT DETECT

When the Burnout Detect (BOD) bit is set in the ADC control configuration register (ADCON0 DC_H), two current sources are enabled. The current source on the positive input channel sources approximately 2μ A of current. The current source on the negative input channel sinks approximately 2μ A. This allows for the detection of an open circuit (full-scale reading) or short circuit (small differential reading) on the selected input differential pair.

INPUT BUFFER

The analog input impedance is always high, regardless of PGA setting (when the buffer is enabled). With the buffer enabled, the input voltage range is reduced and the analog power-supply current is higher. If the limitation of input voltage range is acceptable, then the buffer is always preferred.

The input impedance of the MSC1211 without the buffer is $5M\Omega/PGA$. The buffer is controlled by the state of the BUF bit in the ADC control register (ADCON0 DC_H).

ANALOG INPUT

When the buffer is not selected, the input impedance of the analog input changes with ACLK clock frequency (ACLK $F6_H$) and gain (PGA). The relationship is:

$$A_{IN} \text{ Impedance } (\Omega) = \left(\frac{1 \text{MHz}}{\text{ACLK Frequency}}\right) \bullet \left(\frac{5 \text{M} \Omega}{\text{PGA}}\right)$$

where ACLK frequency = $f_{CLK}/(ACLK + 1)$.

Figure 6 shows the basic input structure of the MSC1211. The sampling frequency varies according to the PGA settings, as shown in Table II.

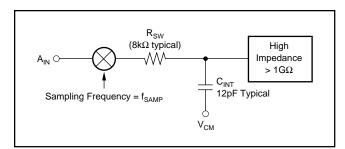


FIGURE 6. Analog Input Structure.

PGA	FULL-SCALE RANGE	SAMPLING FREQUENCY
1	±V _{REF}	f _{SAMP}
2	±V _{REF} /2	f _{SAMP}
4	±V _{REF} /4	f _{SAMP}
8	±V _{REF} /8	f _{SAMP} • 2
16	±V _{REF} /16	f _{SAMP} ● 4
32	±V _{REF} /32	f _{SAMP} • 8
64	±V _{REF} /64	f _{SAMP} • 16
128	±V _{REF} /128	f _{SAMP} • 16
NOTE: fear	AP = ACLK frequency/64.	

NOTE: $f_{SAMP} = ACLK$ frequency/64.

TABLE II. Sampling Frequency Versus PGA Setting.



PGA

The PGA can be set to gains of 1, 2, 4, 8, 16, 32, 64, or 128. Using the PGA can actually improve the effective resolution of the ADC. For instance, with a PGA of 1 on a ± 2.5 V full-scale range, the ADC can resolve to 1.5μ V. With a PGA of 128 on a ± 19 mV full-scale range, the ADC can resolve to 75nV. With a PGA of 1 on a ± 2.5 V full-scale range, it would require a 26-bit ADC to resolve 75nV, as shown in Table III.

PGA SETTING	FULL-SCALE RANGE (V)	ENOB AT 10Hz	RMS MEASUREMENT RESOLUTION (nV)	EQUIVALENT ENOB AT PGA = 1 (5V RANGE)
1	±2.5V	21.7	1468	21.7
2	±1.25	21.5	843	22.5
4	±0.625	21.4	452	23.4
8	±0.313	21.2	259	24.2
16	±0.156	20.8	171	24.8
32	±0.0781	20.4	113	25.4
64	±0.039	20	74.5	26
128	±0.019	19	74.5	26

TABLE III. ENOB Versus PGA.

OFFSET DAC

The analog input to the PGA can be offset by up to half the full-scale input range of the PGA by using the ODAC register (SFR $E6_H$). The ODAC (Offset DAC) register is an 8-bit value; the MSB is the sign and the seven LSBs provide the magnitude of the offset. Since the ODAC introduces an analog (instead of digital) offset to the PGA, using the ODAC does not reduce the performance of the ADC.

MODULATOR

The modulator is a single-loop 2nd-order system. The modulator runs at a clock speed (f_{MOD}) that is derived from the CLK using the value in the Analog Clock register (ACLK). The data output rate is:

 $\label{eq:def_MOD} Data \; Rate = f_{MOD}/Decimation \; Ratio$ where $f_{MOD} = f_{CLK}/(ACLK \; +1)/64$

CALIBRATION

The offset and gain errors in the MSC1211, or the complete system, can be reduced with calibration. Calibration is controlled through the ADCON1 register (SFR DD_H), bits CAL2:CAL0. Each calibration process takes seven t_{DATA} periods (data conversion time) to complete. Therefore, it takes 14 t_{DATA} periods to complete both an offset and gain calibration.

For system calibration, the appropriate signal must be applied to the inputs. The system offset command requires a "zero" differential input signal. It then computes an offset that will nullify offset in the system. The system gain command requires a positive "full-scale" differential input signal. It then computes a value to nullify gain errors in the system. Each of these calibrations will take seven t_{DATA} periods to complete.

Calibration should be performed after power on, a change in temperature, decimation ratio, buffer, or a change of the PGA. Calibration will remove the effects of the Offset DAC, therefore, changes to the Offset DAC register must be done after calibration.

At the completion of calibration, the ADC Interrupt bit goes HIGH which indicates the calibration is finished and valid data is available.

DIGITAL FILTER

The Digital Filter can use either the Fast Settling, sinc², or sinc³ filter, as shown in Figure 7. In addition, the Auto mode changes the sinc filter after the input channel or PGA is changed. When switching to a new channel, it will use the Fast Settling filter, for the next two conversions the first of which should be discarded. It will then use the sinc² followed by the sinc³ filter to improve noise performance. This combines the low-noise advantage of the sinc³ filter with the quick response of the Fast Settling Time filter. The frequency response of each filter is shown in Figure 8.

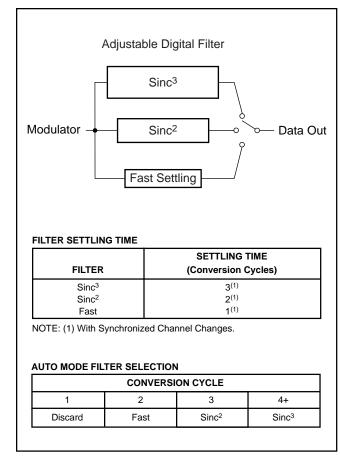


FIGURE 7. Filter Step Responses.



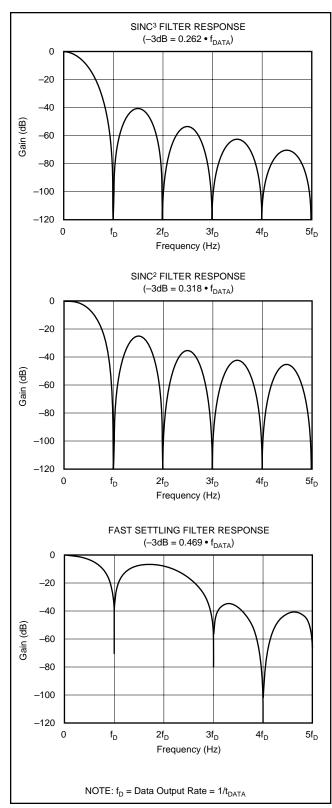


FIGURE 8. Filter Frequency Responses.

VOLTAGE REFERENCE

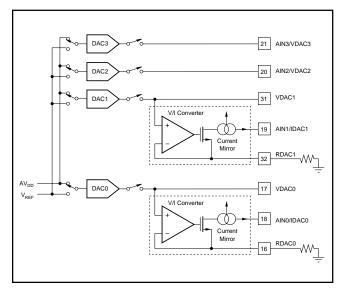
The voltage reference used for the MSC1211 can either be internal or external. The power-up configuration for the voltage reference is 2.5V internal. The selection for the voltage reference is made through the ADCON0 register (SFR DC_H).

The internal voltage reference is selectable as either 1.25V (AV_{DD} = 2.7V to 5.25V) or 2.5V (AV_{DD} = 4.5V to 5.25V). If the internal V_{REF} is not used, it should be turned off to reduce noise and power consumption. The V_{REFOUT} pin should have a 0.1µF capacitor to AGND.

The external voltage reference is differential and is represented by the voltage difference between the pins: REF IN+ and REF IN-. The absolute voltage on either pin (REF IN+ and REF IN-) can range from AGND to AV_{DD} , however, the differential voltage must not exceed 2.6V. The differential voltage reference provides easy means of performing ratiometric measurement.

DAC

The architecture consists of a string DAC followed by an output buffer amplifier. Figure 9 shows a block diagram of the DAC architecture.





The input coding to the DAC is straight binary, so the ideal output voltage is given by:

$$VDAC = V_{REF} \bullet \frac{D}{65536}$$

where D = decimal equivalent of the binary code that is loaded to the DAC register; it can range from 0 to 65535.



RESISTOR STRING

The DAC selects the voltage from a string of resistors from the reference to AGND. It is essentially a string of resistors, each of value R. The code loaded into the DAC register determines at which node on the string the voltage is tapped off to be fed into the output amplifier by closing one of the switches connecting the string to the amplifier. It is ensured monotonic because it is a string of resistors.

OUTPUT AMPLIFIER

The output buffer amplifier is capable of generating rail-to-rail voltages on its output which gives an output range of AGND to AV_{DD}. It is capable of driving a load of $2k\Omega$ in parallel with 1000pF to GND. The source and sink capabilities of the output amplifier can be seen in the typical curves. The slew rate is $1V/\mu s$ with a full-scale settling time of $8\mu s$ with the output unloaded.

DAC REFERENCE

Each DAC can be selected to use the internal REFOUT/REF IN+ voltage or the supply voltage AV_{DD} as the reference for the DAC. The full range of the voltage DAC is limited according to Table IV. The full range of the current DAC is limited according to Table V.

DAC REFERENCE	$AV_{DD} = 5V$	$AV_{DD} = 3V$	$AV_{DD} < 3.0V$
$DACREF = AV_{DD}$	Full Range	Full Range	Not Recommended
DACREF = 2.5V	Full Range	Not Recommended	Not Recommended
DACREF = 1.25V	Full Range	Full Range	Not Recommended

TABLE IV. Voltage DAC Code Range.

DAC REFERENCE	$AV_{DD} = 5V$	$AV_{DD} = 3V$	$AV_{DD} < 3.0V$
DACREF = AV _{DD}	0000-7FFF _H	0000-3FFF _H	Not Recommended
DACREF = 2.5V	Full Range	Not Recommended	Not Recommended
DACREF = 1.25V	Full Range	Full Range	Not Recommended

TABLE V. Current DAC Code Range.

DAC LOADING

The DAC can be selected to be turned off with a 1k Ω , 100k Ω , or open circuit on the DAC outputs.

BIPOLAR OPERATION USING THE DAC

The DAC can be used for a bipolar output range, as shown in Figure 10. The circuit shown will give an output voltage range of $\pm V_{\text{REF}}$. Rail-to-rail operation at the amplifier output is achievable using an OPA703 as the output amplifier.

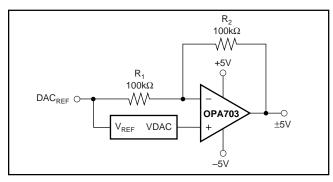


FIGURE 10. Bipolar Operation with the DAC.

The output voltage for any input code can be calculated as follows:

$$V_{O} = \left[\mathsf{DAC}_{\mathsf{REF}} \bullet \left(\frac{\mathsf{D}}{65536} \right) \bullet \left(\frac{\mathsf{R}_{1} + \mathsf{R}_{2}}{\mathsf{R}_{1}} \right) - \mathsf{DAC}_{\mathsf{REF}} \bullet \left(\frac{\mathsf{R}_{2}}{\mathsf{R}_{1}} \right) \right]$$

where D represents the input code in decimal (0–65535). With $DAC_{REF} = 5V$, $R_1 = R_2 = 10k\Omega$:

$$V_{\rm O} = \left(\frac{10 \bullet \rm D}{65536}\right) - 5\rm V$$

This is an output voltage range of $\pm 5V$ with 0000_{H} corresponding to a -5V output and FFFF_H corresponding to a +5V output. Similarly, using V_{REF} = 2.5V, a $\pm 2.5V$ output voltage can be achieved.

IDAC

The compliance specification of the IDAC output defines the maximum output voltage to achieve the expected current. Refer to Figure 9 for the IDAC structure and to Table V for the DAC reference selection and code range.

POWER-UP—SUPPLY VOLTAGE RAMP RATE

The built-in (on-chip) power-on reset circuitry was designed to accommodate analog or digital supply ramp rates as slow as 1V/10ms. To ensure proper operation, the power supply should ramp monotonically at the specified rate. If BOR is enabled, the ramp rate can be slower.

MEMORY MAP

The MSC1211 contains on-chip SFR, Flash Memory, Scratchpad RAM Memory, Boot ROM, and SRAM. The SFR registers are primarily used for control and status. The standard 8051 features and additional peripheral features of the MSC1211 are controlled through the SFR. Reading from undefined SFR will return zero and writing to undefined SFR registers is not recommended and will have indeterminate effects.

Flash Memory is used for both Program Memory and Data Memory. The user has the ability to select the partition size of Program and Data Memories. The partition size is set through hardware configuration bits, which are programmed through either the parallel or serial programming methods. Both Program and Data Flash Memories are erasable and writable (programmable) in user application mode. However, only program execution can occur from Program Memory. As an added precaution, a lock feature can be activated through the hardware configuration bits, which disables erase and writes to 4kB of Program Flash Memory or the entire Program Flash Memory in user application mode.

The MSC1211 includes 1kB of SRAM on-chip. SRAM starts at address 0 and is accessed through the MOVX instruction. This SRAM can also be located to start at $8400_{\rm H}$ and can be accessed as both Program and Data Memory.





FLASH MEMORY

The MSC1211 uses a memory addressing scheme that separates Program Memory (FLASH/ROM) from Data Memory (FLASH/RAM). Each area is 64kB beginning at address 0000_H and ending at FFFF_H, as shown in Figure 11. The program and data segments can overlap since they are accessed in different ways. Program Memory is fetched by the microcontroller automatically. There is one instruction (MOVC) that is used to explicitly read the program area. This is commonly used to read lookup tables. The Data Memory area is accessed explicitly using the MOVX instruction. This instruction provides multiple ways of specifying the target address. It is used to access the 64kB of Data Memory. The address and data range of devices with on-chip Program and Data Memory overlap the 64kB memory space. When on-chip memory is enabled, accessing memory in the on-chip range will cause the device to access internal memory. Memory accesses beyond the internal range will be addressed externally via Ports 0 and 2.

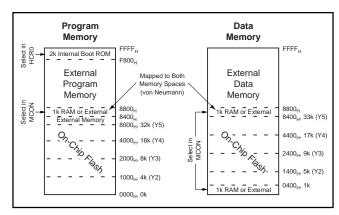


FIGURE 11. Memory Map.

The MSC1211 has two Hardware Configuration registers (HCR0 and HCR1) that are programmable only during Flash Memory Programming mode.

The MSC1211 allows the user to partition the Flash Memory between Program Memory and Data Memory. For instance, the MSC1211Y5 contains 32kB of Flash Memory on-chip. Through the HW configuration registers, the user can define the partition between Program Memory (PM) and Data Memory (DM), as shown in Tables VI and VII. The MSC1211 family offers four memory configurations.

HCR0	MSC1211Y2		MSC1211Y3		MSC1211Y4		MSC1211Y5	
DFSEL	PM	DM	PM	DM	PM	DM	PM	DM
000	0kB	4kB	0kB	8kB	0kB	16kB	0kB	32kB
001	0kB	4kB	0kB	8kB	0kB	16kB	0kB	32kB
010	0kB	4kB	0kB	8kB	0kB	16kB	16kB	16kB
011	0kB	4kB	0kB	8kB	8kB	8kB	24kB	8kB
100	0kB	4kB	4kB	4kB	12kB	4kB	28kB	4kB
101	2kB	2kB	6kB	2kB	14kB	2kB	30kB	2kB
110	3kB	1kB	7kB	1kB	15kB	1kB	31kB	1kB
111 (default)	4kB	0kB	8kB	0kB	16kB	0kB	32kB	0kB
NOTE: When a 0kB program memory configuration is selected program execution is external.								

TABLE VI. MSC1211Y Flash Partitioning.

HCR0	MSC1	211Y2	MSC1211Y3		MSC1211Y4		MSC1211Y5	
DFSEL	PM	DM	PM	DM	PM	DM	PM	DM
000	0000	0400- 13FF	0000	0400- 23FF	0000	0400- 43FF	0000	0400- 83FF
001	0000	0400- 13FF	0000	0400- 23FF	0000	0400- 43FF	0000	0400- 83FF
010	0000	0400 13FF	0000	0400 23FF	0000	0400 43FF	0000- 3FFF	0400- 43FF
011	0000	0400- 13FF	0000	0400- 23FF	0000- 1FFF	0400- 23FF	0000- 5FFF	0400- 23FF
100	0000	0400- 13FF	0000- 0FFF	0400- 13FF	0000- 2FFF	0400- 13FF	0000- 6FFF	0400- 13FF
101	0000- 07FF	0400- 0BFF	0000- 17FF	0400- 0BFF	0000- 37FF	0400- 0BFF	0000- 77FF	0400- 0BFF
110	0000- 0BFF	0400- 07FF	0000- 1BFF	0400- 07FF	0000- 3BFF	0400- 07FF	0000- 7BFF	0400- 07FF
111 (default)	0000- 0FFF	0000	0000- 1FFF	0000	0000- 3FFF	0000	0000- 7FFF	0000
NOTE: Program access external				pove the	e highes	st listed	addres	s will

TABLE VII. Flash Memory Partitioning.

It is important to note that the Flash Memory is readable and writable (depending on the MXWS bit in the MWS SFR) by the user through the MOVX instruction when configured as either Program or Data Memory. This means that the user may partition the device for maximum Flash Program Memory size (no Flash Data Memory) and use Flash Program Memory as Flash Data Memory. This may lead to undesirable behavior if the PC points to an area of Flash Program Memory that is being used for data storage. Therefore, it is recommended to use Flash partitioning when Flash Memory is used for data storage. Flash partitioning prohibits execution of code from Data Flash Memory. Additionally, the Program Memory erase/ write can be disabled through hardware configuration bits (HCR0), while still providing access (read/write/erase) to Data Flash Memory.

The effect of memory mapping on Program and Data Memory is straightforward. The Program Memory is decreased in size from the top of internal Program Memory. Therefore, if the MSC1211Y5 is partitioned with 31kB of Flash Program Memory and 1kB of Flash Data Memory, external Program Memory execution will begin at $7C00_H$ (versus 8000_H for 32kB). The Flash Data Memory is added on top of the SRAM memory. Therefore, access to Data Memory (through MOVX) will access SRAM for addresses 0000_H -03FF_H and access Flash Memory for addresses 0400_H -07FF_H.

Data Memory

The MSC1211 can address 64kB of Data Memory. Scratchpad Memory provides 256 bytes in addition to the 64kB of Data Memory. The MOVX instruction is used to access the Data SRAM Memory. This includes 1024 bytes of on-chip Data SRAM Memory. The data bus values do not appear on Port 0 (during data bus timing) for internal memory access.

The MSC1211 also has on-chip Flash Data Memory which is readable and writable (depending on Memory Write Select register) during normal operation (full V_{DD} range). This memory is mapped into the external Data Memory space directly above the SRAM.



REGISTER MAP

The Register Map is illustrated in Figure 12. It is entirely separate from the Program and Data Memory areas mentioned before. A separate class of instructions is used to access the registers. There are 256 potential register locations. In practice, the MSC1211 has 256 bytes of Scratchpad RAM and up to 128 SFRs. This is possible, since the upper 128 Scratchpad RAM locations can only be accessed indirectly. That is, the contents of a Working Register (described below) will designate the RAM location. Thus, a direct reference to one of the upper 128 locations must be an SFR access. Direct RAM is reached at locations 0 to $7F_{\rm H}$ (0 to 127).

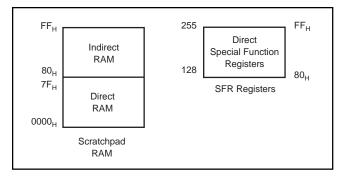


FIGURE 12. Register Map.

SFRs are accessed directly between $80_{\rm H}$ and FF_H (128 to 255). The RAM locations between 128 and 255 can be reached through an indirect reference to those locations. Scratchpad RAM is available for general-purpose data storage. It is commonly used in place of off-chip RAM when the total data contents are small. When off-chip RAM is needed, the Scratchpad area will still provide the fastest general-purpose access. Within the 256 bytes of RAM, there are several special-purpose areas.

Bit Addressable Locations

In addition to direct register access, some individual bits are also accessible. These are individually addressable bits in both the RAM and SFR area. In the Scratchpad RAM area, registers 20_H to $2F_H$ are bit addressable. This provides 128 (16 • 8) individual bits available to software. A bit access is distinguished from a full-register access by the type of instruction. In the SFR area, any register location ending in a 0 or 8 is bit addressable. Figure 13 shows details of the on-chip RAM addressing including the locations of individual RAM bits.

Working Registers

As part of the lower 128 bytes of RAM, there are four banks of Working Registers, as shown in Figure 13. The Working Registers are general-purpose RAM locations that can be addressed in a special way. They are designated R0 through R7. Since there are four banks, the currently selected bank will be used by any instruction using R0-R7. This allows software to change context by simply switching banks. This is controlled via the Program Status Word register (PSW; 0D0_H) in the SFR area described below. Registers R0 and R1 also allow their contents to be used for indirect addressing of the upper 128 bytes of RAM. Thus, an instruction can designate the value

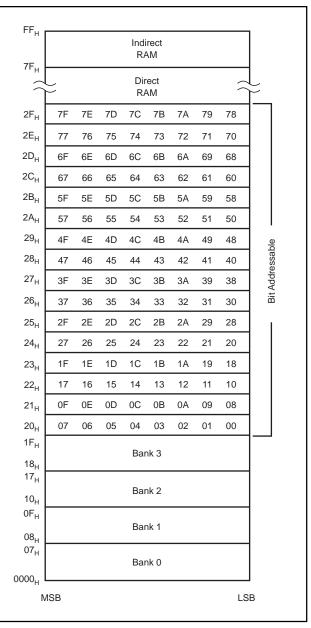


FIGURE 13. Scratchpad Register Addressing.

stored in R0 (for example) to address the upper RAM. The 16 bytes immediately above the these registers are bit addressable. So any of the 128 bits in this area can be directly accessed using bit addressable instructions.

Stack

Another use of the Scratchpad area is for the programmer's stack. This area is selected using the Stack Pointer (SP; 81_H) SFR. Whenever a call or interrupt is invoked, the return address is placed on the Stack. It also is available to the programmer for variables, etc., since the Stack can be moved and there is no fixed location within the RAM designated as Stack. The Stack Pointer will default to 07_H on reset. The user can then move it as needed. A convenient location would be the upper RAM area (> $7F_H$) since this is only available indirectly. The SP will point to the last used value. Therefore, the next value placed on the Stack is put at SP + 1. Each PUSH or CALL will increment the SP by the appropriate value. Each POP or RET will decrement as well.



Program Memory

After reset, the CPU begins execution from Program Memory location 0000_H. The selection of where Program Memory execution begins is made by tying the \overline{EA} pin to V_{DD} for internal access, or DGND for external access. When \overline{EA} is tied to V_{DD}, any PC fetches outside the internal Program Memory address occur from external memory. If \overline{EA} is tied to DGND, then all PC fetches address external memory. The standard internal Program Memory size for MSC1211 family members is shown in Table VIII. Refer to the Accessing External Memory section for details on using external Program Memory. If enabled the Boot ROM will appear from address F800_H to FFF_H.

MODEL NUMBER	STANDARD INTERNAL PROGRAM MEMORY SIZE (BYTES)
MSC1211Y5	32k
MSC1211Y4	16k
MSC1211Y3	8k
MSC1211Y2	4k

TABLE VIII. MSC1211 Maximum Internal Program Memory Sizes.

ACCESSING EXTERNAL MEMORY

If external memory is used, P0 and P2 can be configured as address and data lines. If external memory is not used, P0 and P2 can be configured as general-purpose I/O lines through the Hardware Configuration Register.

To enable access to external memory bits 0 and 1 of the HCR1 register must be set to 0. When these bits are enabled all memory accesses for both internal and external memory will appear on ports 0 and 2. During the data portion of the cycle for internal memory, Port 0 will be zero for security purposes.

Accesses to external memory are of two types: accesses to external Program Memory and accesses to external Data Memory. Accesses to external Program Memory use signal PSEN (program store enable) as the read strobe. Accesses to external Data Memory use RD or WR (alternate functions of P3.7 and P3.6) to strobe the memory.

External Program Memory and external Data Memory may be combined if desired by applying the $\overline{\text{RD}}$ and $\overline{\text{PSEN}}$ signals to the inputs of an AND gate and using the output of the gate as the read strobe to the external Program/Data Memory.

A program fetch from external Program Memory uses a 16bit address. Accesses to external Data Memory can use either a 16-bit address (MOVX @DPTR) or an 8-bit address (MOVX @R_I).

If Port 2 is selected for external memory use (HCR1, bit 0), it can not be used as a general-purpose I/O. This bit (or Bit 1 of HCR1) also forces bits P3.6 and P3.7 to be used for \overline{WR} and \overline{RD} instead of I/O. Port 2, P3.6, and P3.7 should all be written to '1'. If an 8-bit address is being used (MOVX $@R_1$), the contents of the MPAGE (92_H) SFR remain at the Port 2 pins throughout the external memory cycle. This will facilitate paging.

In any case, the low byte of the address is time-multiplexed with the data byte on Port 0. The ADDR/DATA signals use CMOS drivers in the Port 0, Port 2, \overline{WR} , and \overline{RD} output buffers. Thus, in this application the Port 0 pins are not opendrain outputs, and do not require external pull-ups for high-speed access. Signal ALE (Address Latch Enable) should be used to capture the address byte into an external latch. The address byte is valid at the negative transition of ALE. Then, in a write cycle, the data byte to be written appears on Port 0 just before \overline{WR} is activated, and remains there until after \overline{WR} is deactivated. In a read cycle, the incoming byte is accepted at Port 0 just before the read strobe is deactivated.

The function of Port 0 and Port 2 is selected in Hardware Configuration Register 1. This can only be changed during the Flash Program mode. There is no conflict in the use of these registers; they will either be used as general-purpose I/O or for external memory access. The default state is for Port 0 and Port 2 to be used as general-purpose I/O. If an external memory access is attempted when they are configured as general-purpose I/O, the values of Port 0 and Port 2 will not be affected.

External Program Memory is accessed under two conditions:

1) Whenever signal $\overline{\mathsf{EA}}$ is LOW during reset, then all future accesses are external, or

2) Whenever the Program Counter (PC) contains a number that is outside of the internal Program Memory address range, if the ports are enabled.

If Port 0 and Port 2 is selected for external memory, all 8 bits of Port 0 and Port 2, as well as P3.6 and P3.7, are dedicated to an output function and may not be used for generalpurpose I/O. During external program fetches, Port 2 outputs the high byte of the PC.

Programming Flash Memory

There are four sections of Flash Memory for programming.

- 1. 128 configuration bytes.
- 2. Reset sector (4kB) (not to be confused with the 2kB Boot ROM).
- 3. Program Memory.
- 4. Data Memory.

Boot Rom

There is a 2kB Boot ROM that controls operation during serial or parallel programming. Additionally, the Boot ROM routines can be accessed during the user mode if it is enabled. When enabled, the Boot ROM routines will be located at memory addresses $F800_{H}$ -FFFF_H during user mode. In program mode the Boot ROM is located in the first 2kB of Program Memory.



Flash Programming Mode

There are two programming modes: parallel and serial. The programming mode is selected by the state of the ALE and \overrightarrow{PSEN} signals during power-on reset. Serial programming mode is selected with $\overrightarrow{PSEN} = 0$ and $\overrightarrow{ALE} = 1$. Parallel programming mode is selected with $\overrightarrow{PSEN} = 1$ and $\overrightarrow{ALE} = 0$ (see Figure 14). If they are both HIGH, the MSC1211 will

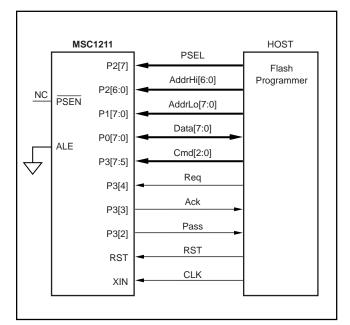


FIGURE 14. Parallel Programming Configuration.

operate in normal user mode. Both signals LOW is a reserved mode and is not defined. Programming mode is exited with a power-on reset signal and the normal mode selected.

The MSC1211 is shipped with Flash Memory erased (all 1's). Parallel programming methods typically involve a third-party programmer. Serial programming methods typically involve insystem programming. User Application mode allows Flash Program and Data Memory programming. The actual code for Flash programming can not execute from Flash. That code must execute from the Boot ROM or internal (von Neumann) RAM.

INTERRUPTS

The MSC1211 uses a three-priority interrupt system. As shown in Table IX, each interrupt source has an independent priority bit, flag, interrupt vector, and enable (except that nine interrupts share the Auxilliary Interrupt (AI) at the highest priority). In addition, interrupts can be globally enabled or disabled. The interrupt structure is compatible with the original 8051 family. All of the standard interrupts are available.

HARDWARE CONFIGURATION MEMORY

The 128 configuration bytes can only be written during the program mode. The bytes are accessed through SFR registers CADDR (SFR 93_H) and CDATA (SFR 94_H). Two of the configuration bytes control Flash partitioning and system control. If the security bit is set, these bits can not be changed except with a Mass Erase command that erases all of the Flash Memory including the 128 configuration bytes.

	INTER	RUPT			PRIORITY		
INTERRUPT/EVENT	ADDR	NUM	PRIORITY	FLAG	ENABLE	CONTROL	
DV _{DD} Low Voltage/HW Breakpoint	33 _H	6	HIGH 0	EDLVB (AIE.0) ⁽¹⁾ EBP (BPCON.0) ⁽¹⁾	EDLVV (AIE.0) ⁽¹⁾ EBP (BPCON.0) ⁽¹⁾	N/A	
AV _{DD} Low Voltage	33 _H	6	0	EALV (AIE.1) ⁽¹⁾	EALV (AIE.1) ⁽¹⁾	N/A	
SPI Receive / I ² C	33 _H	6	0	ESPIR (AIE.2) ⁽¹⁾	ESPIR (AIE.2) ⁽¹⁾	N/A	
SPI Transmit	33 _H	6	0	ESPIT (AIE.3) ⁽¹⁾	ESPIT (AIE.3) ⁽¹⁾	N/A	
Milliseconds Timer	33 _H	6	0	EMSEC (AIE.4) ⁽¹⁾	EMSEC (AIE.4) ⁽¹⁾	N/A	
ADC	33 _H	6	0	EADC (AIE.5) ⁽¹⁾	EADC (AIE .5) ⁽¹⁾	N/A	
Summation Register	33 _H	6	0	ESUM (AIE.6) ⁽¹⁾	ESUM (AIE.6) ⁽¹⁾	N/A	
Seconds Timer	33 _H	6	0	ESEC (AIE.7) ⁽¹⁾	ESEC (AIE.7) ⁽¹⁾	N/A	
External Interrupt 0	03 _H	0	1	IE0 (TCON.1) ⁽²⁾	EX0 (IE.0) ⁽⁴⁾	PX0 (IP.0)	
Timer 0 Overflow	0B _H	1	2	TF0 (TCON.5) ⁽³⁾	ET0 (IE.1) ⁽⁴⁾	PT0 (IP.1)	
External Interrupt 1	13 _H	2	3	IE1 (TCON.3) ⁽²⁾	EX1 (IE.2) ⁽⁴⁾	PX1 (IP.2)	
Timer 1 Overflow	1B _H	3	4	TF1 (TCON.7) ⁽³⁾	ET1 (IE.3) ⁽⁴⁾	PT1 (IP.3)	
Serial Port 0	23 _H	4	5	RI_0 (SCON0.0) TI_0 (SCON0.1)	ES0 (IE.4) ⁽⁴⁾	PS0 (IP.4)	
Timer 2 Overflow	2B _H	5	6	TF2 (T2CON.7)	ET2 (IE.5) ⁽⁴⁾	PT2 (IP.5)	
Serial Port 1	3B _H	7	7	RI_1 (SCON1.0) TI_1 (SCON1.1)	ES1 (IE.6) ⁽⁴⁾	PS1 (IP.6)	
External Interrupt 2	43 _H	8	8	IE2 (EXIF.4)	EX2 (EIE.0) ⁽⁴⁾	PX2 (IP.0)	
External Interrupt 3	4B _H	9	9	IE3 (EXIF.5)	EX3 (EIE.1) ⁽⁴⁾	PX3 (IP.1)	
External Interrupt 4	53 _H	10	10	IE4 (EXIF.6)	EX4 (EIE.2) ⁽⁴⁾	PX4 (IP.2)	
External Interrupt 5	5B _H	11	11	IE5 (EXIF.7)	EX5 (EIE.3) ⁽⁴⁾	PX5 (IP.3)	
Watchdog	63 _H	12	12 LOW	WDTI (EICON.3)	EWDI (EIE.4) ⁽⁴⁾	PWDI (IP.4)	

NOTES: (1) These interrupts set the AI flag (EICON.4) and are enabled by EAI (EICON.5). (2) If edge triggered, cleared automatically by hardware when the service routine is vectored to. If level triggered, the flag follows the state of the pin. (3) Cleared automatically by hardware when interrupt vector occurs. (4) Globally enabled by \overline{EA} (IE.7).

TABLE IX. Interrupt Summary.



	- J	- J	- (/		J -	3		
	bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0
CADDR 7F _H	EPMA	PML	RSL	EBR	EWDR	DFSEL2	DFSEL1	DFSEL0

Hardware Configuration Register 0 (HCR0)—Accessed Using SFR Registers CADDR and CDATA.

For access to this register during normal operation, refer to the register descriptions for CADDR and CDATA.

EPMA Enable Programming Memory Access (Security Bit).

bit 7 0: After reset in programming modes, Flash Memory can only be accessed in UAM mode until a mass erase is done. 1: Fully Accessible (default)

PML Program Memory Lock. (PML has Priority Over RSL)

bit 6 0: Enable all Flash Programming Modes in program mode, can be written in UAM.1: Enable read only for program mode, can't be written in UAM (default).

RSL Reset Sector Lock.

- bit 5 0: Enable Reset Sector Writing
 - 1: Enable Read Only Mode for Reset Sector (4kB) (default)
- **EBR Enable Boot Rom.** Boot Rom is 2kB of code located in ROM, not to be confused with the 4kB Boot Sector located in Flash Memory.
- bit 4 0: Disable Internal Boot Rom 1: Enable Internal Boot Rom (default)

EWDR Enable Watchdog Reset.

bit 3 0: Disable Watchdog Reset 1: Enable Watchdog Reset (default)

DFSEL Data Flash Memory Size. (see Table III)

- bits 2-0 000: Reserved
 - 001: 32kB, 16kB, 8kB, or 4kB Data Flash Memory
 - 010: 16kB, 8kB, or 4kB Data Flash Memory
 - 011: 8kB or 4kB Data Flash Memory
 - 100: 4kB Data Flash Memory
 - 101: 2kB Data Flash Memory
 - 110: 1kB Data Flash Memory
 - 111: No Data Flash Memory (default)

The reset sector can be used to provide another method of Flash Memory programming. This will allow Program Memory updates without changing the jumpers for in-circuit code updates or program development. The code in this boot sector would then provide the monitor and programming routines with the ability to jump into the main Flash code when programming is finished.



	7	6	5	4	3	2	1	0					
CADDR 7	E _H DBLSEL1	DBLSEL0	ABLSEL1	ABLSEL0	DAB	DDB	EGP0	EGP23					
	s to this register	•	•	efer to the regis	ster descriptio	ns for CADDF	R and CDATA						
DBLSEL	Digital Browno	ut Level Sele	ect										
bits 7-6	00: 4.5V												
	01: 4.2V												
	10: 2.7V												
	11: 2.5V (defau	lt)											
ABLSEL	Analog Brown	out Level Sel	ect										
bits 5-4	00: 4.5V												
	01: 4.2V												
	10: 2.7V												
	11: 2.5V (defau	lt)											
DAB	Disable Analog	g Power-Supp	oly Brownout	Detection									
bit 3	0: Enable Analo	og Brownout D	etection										
	1: Disable Anal	og Brownout [Detection (defa	ault).									
DDB	Disable Digital	Power-Supp	ly Brownout	Detection									
bit 2	0: Enable Digita	al Brownout D	etection										
	1: Disable Digita	al Brownout D	etection (defa	ult)									
EGP0	Enable Genera	I-Purpose I/O	for Port 0										
bit 1	0: Port 0 is Use	d for External	Memory, P3.	6 and P3.7 Us	ed for \overline{WR} an	d RD.							
	1: Port 0 is Use	d as General-	Purpose I/O (default)									
EGP23	Enable Genera	I-Purnose I/O	for Ports 2	and 3									

- 0: Port 2 is Used for External Memory, P3.6 and P3.7 Used for WR and RD. bit 0
 - 1: Port 2 and Port3 are Used as General-Purpose I/O (default)

Configuration Memory Programming

Certain key functions such as Brownout Reset and Watchdog Timer are controlled by the hardware configuration bits. These bits are nonvolatile and can only be changed through serial and parallel programming. Other peripheral control and status functions, such as ADC configuration timer setup, and Flash control are controlled through the SFRs.

bh_{11} FP_{11} $P0.1$ $P0.0$ $P0.1$ $P0.0$	ADDRESS	REGISTER	BIT 7	BIT 6	BIT 5	BIT 4	BIT 3	BIT 2	BIT 1	BIT 0	RESET VALUES
B2A, B3A, B4A, B4A, B4A, B4A, B4A, B4A, B4A, B4	80 _H	P0	P0.7	P0.6	P0.5	P0.4	P0.3	P0.2	P0.1	P0.0	FF _H
ISA. Bell, Bell, DPH1 DPH0 I Image: space of the spa	81 _H	SP									07 _H
ist, Bs, Bs, Bs, Bs, Bs, Bs, Bs, Bs, Bs, Bs	82 _H	DPL0									00 _H
BSs. Boss. DPH1 DPS 0 0 0 0 0 0 0 0 SEL 000, 00, 00, 00, 00, 00, 00, 00, 00, 00	83 _H	DPH0									
	84 _H										
			-				-	-	-		
			1								
IBB, GC, BC, BC, BC, BC, BC, BC, BC, BC, BC, B	89 _H	TMOD				'					00 _H
BB, GC, BC, BC, BC, BC, BC, BC, BC, BC, BC, B	8A _H	TL0									00 _H
BD ₁ TH1 P1.4 P1.3 P1.2 P1.4 P1.3 P1.4 P1.3 P1.4 P1.3 P1.4 P1.3 P1.4 P1.3 P1.4 P1.3 P1.2 P1.1 P1.0 CFF.Fr/Fr/Fr/Fr/Fr/Fr/Fr/Fr/Fr/Fr/Fr/Fr/Fr/F		TL1									00 _H
ise CKCON 0 0 71M TOM M02 MD1 MD0 O11, MD2 BFi, D0, 20, 20, 20, 20, 20, 20, 20, 20, 20, 2	8C _H	TH0									00 _H
	8D _H	TH1									
90/h P1.7 P1.6 P1.4 P1.3 P1.2 P1.4 P1.3 P1.3 <th< td=""><td></td><td></td><td>-</td><td></td><td></td><td></td><td></td><td></td><td></td><td></td><td></td></th<>			-								
C NTMARCORD NTT3ANOSI INT2/SS TXD1 RXD1 T2EX T2 Composition 92µ, MPAGE IEA IE											
91/1 ΕΧΙΓ ΙΕ5 ΙΕ4 ΙΕ3 ΙΕ2 1 0 0 0.0 08μ 93/4 CADDR C C C C C 0 0 0 0 0 94μ CADDR BPSEL 0 0 0 0 C C C 0 00μ 94μ SCON0 SM0_0 SM1_0 SM2_0 REN_0 TB8_0 TL_0 RL0 00μ 94μ SCON0 SM0_0 SM1_0 SM2_0 REN_0 TB8_0 TL_0 RL0 00μ 94μ SCON0 SM0_0 SM1_0 SM2_0 REN_0 TB8_0 TL_0 RL0 00μ 94μ SPIDATA CCON SCLK2 SCLK0 SCLK0 RXCNT5 RXCNT6 RXCNT3 RXCNT3 RXCNT2 RXCNT1 RXR0 RXR0 RXR0 RXR0 RXR0 00μ 95L SPICAN RXCNT7 RXCNT5 RXCNT5	90 _H	P1									FF _H
93 ₃ CADR CADR Constrained Set Set <td></td>											
			IE5	IE4	IE3	IE2	1	0	0	0	
94, 95, 96, 97, 97, 97, 98, 98, 98, 98, 98, 98, 98, 98, 98, 98											
954, 961, 971, MCON BPSEL 0 0 0 C C C RAMMAP 901, 901, 931, 934, SCON0 SM0_0 SM1_0 SM2_0 REN_0 TB8_0 RB8_0 TL_0 RL_0 001, 001, 001, 901, 934, 934, 934, 934, SBUF0 SCLX2 SCLK1 SCLK0 FIFO ORDER MSTR CPLA CPLA 001, 001, 901, 2CCAN SCLX2 SCLK1 SCLK0 FIFO ORDER MSTR SCLS CPLA 000, 001, 2CCAN 001, 2CCAN MSTR SCLS CRL 001, 2CCAN SCLS7 RXCNT5 RXCNT4 RXCNT3 RXCNT1 RXCNT1 RXCNT0 RXCNT0 RXCNT1											
66, 97, 97, 98, 98, 98, 1 SCON0 SM0_0 SM1_0 SM2_0 REN_0 TB8_0 RB8_0 TI_0 RI_0 00, 00, 00, 1 98, 99, 12CC0N SSUF0 SCLK2 SCLK1 SCLK2 SCLK2 SCLK1 SCLK2 SCLK1 SCLK2 SCLK1 SCLK2 SCLK2 SCLK2 SCLK2 SCLK2 SCLK2 SCLK2 SCLK2 SCLK1			PREL	0	0						
07, 98, 99, 1 CON0 SM0_0 SM1_0 SM2_0 REN_0 TB6_0 RB6_0 TL_0 RL_0 00, 00, 00, 00, 00, 00, 00, 00, 00, 00,		MCON	DPSEL	U	U					RAIVIIVIAP	UU _H
98 _h SCON0 SM1_0 SM1_0 SM2_0 REN_0 TEN_0 REN_0 TL_0 RL_0 00 _h 93 _h SPICON SCLX2 SCLX1 SCLK1 SCLK0 FIFO ORDER MSTR CPLA CPLA </td <td></td>											
99 _h SBUF0 CLX SCLX2 SCLX1 SCLX0 PIFO ORDER MSTR CPA ORDER MSTR SCLS FILEN ORDER MSTR SCLS FILEN ORDER 9B _H SPIDCON SSCATT SCATT RXCNT7 RXCNT6 RXCNT5 RXCNT4 RXCNT3 RXCNT1 RXCNT0 RXIR01 TXIR01 TXIR01 TXIR01 TXIR01 TXIR01 TXIR01 TXIR01		SCONO	SM0_0	SM1_0	SM2_0	REN 0	TB8_0	RB8 0	TLO	RL 0	00
9A _H SPICON IZCON SCL42 START SCL40 STOP SCL40 ACK FFO 0 ORDER FAST MSTR MSTR CPAL CPAL CPAL SLS CPAL FILEN OD _H 9B _H SPIDATA SPIDATA SPIDATA RXCNT7 RXFLUSH RXCNT7 RXFLUSH RXCNT6 RXCNT7 RXFLUSH RXCNT7 RXFLUSH RXCNT7 RXFLUSH RXCNT7 RXFLUSH RXCNT7 TXFLUSH RXCNT6 RXCNT7 RXFLUSH RXCNT7 RXFLUSH RXCNT7 RXFLUSH RXCNT6 TXCNT4 RXFLV RXCNT2 RXIRQ1 RXCNT7 TXRQ0 RXCNT7 TXRQ0 00 _H 9D _H SPITCON TXCNT7 TXFLUSH TXCNT6 TXCNT5 STAT5 SCK078AE TXCNT5 SCK078AE SCK078AS <			01010_0			IKEN_0	100_0	IXD0_0	11_0	IXI_0	
IZCCON START STOP ACK 0 FAST MSTR SCLS FILEN MOR 9B _H SPIDATA (ZCDATA - - - - - - - 00, 00, 9C _H SPIRCON RXCNT7 RXFLUSH RXCNT6 RXCNT5 RXCNT4 RXCNT3 RXCNT2 RXII01 RXIR01 RXIR01 00, 9D _H SPITCON TXCNT7 TXCNT6 TXCNT5 TXCNT4 TXCNT3 TXCNT1 TXCNT0 TXCNT1 TXCNT0 TXCNT0 <t< td=""><td></td><td></td><td>SCLK2</td><td>SCLK1</td><td>SCLK0</td><td>FIFO</td><td>ORDER</td><td>MSTR</td><td>СРНА</td><td>CPOL</td><td></td></t<>			SCLK2	SCLK1	SCLK0	FIFO	ORDER	MSTR	СРНА	CPOL	
IzCDATA RXCNT6 RXCNT6 RXCNT6 RXCNT6 RXCNT6 RXCNT7 RXCNT7 RXCNT1 TXCNT0 TXCNT1 TXCNT		I2CCON	1								
Instruct RXFLUSH GGMEN Proprint RXRQ2 RXRQ1 RXRQ0 9D _H SPITCON TXCNT7 TXFLUSH TXCNT6 TXFLUSH TXCNT6 TXFLUSH TXCNT6 CLK_EN TXCNT3 DRV_EN TXCNT3 TXRQ1 TXCNT1 TXRQ0 TXCNT0 0 TXCNT0 TXRQ1 TXCNT0 TXRQ0 TXCNT0 0	9В _Н										00 _H
9D _H SPITCON TXCNT7 TXFLUSH STAT7 TXCNT6 STAT5 TXCNT6 CLK_EN STAT4 TXCNT2 DRV_EN STAT5 TXCNT2 DRV_EN STAT5 TXCNT2 TXIRQ2 TXCNT1 TXIRQ0 TXCNT0 DRV_EN SCKD2SA2 TXCNT1 TXIRQ0 TXCNT1 TXIRQ0 TXCNT1 TXIRQ0 TXCNT0 DRV_EN TXIRQ0 DRV_EN Output SCKD2SA2 SCKD2SA2 SCKD1SA3 SCKD2SA2 SCKD2SA2 SC	9C _H	SPIRCON	1	RXCNT6	RXCNT5	RXCNT4	RXCNT3				00 _H
IZCGM TXFLUSH STATS CLK_EN STATS DRV_DLY STATS DRV_EN STATS TXIRQ2 STATS TXIRQ1 0 TXIRQ0 0 DV 0 DV 0 9E _H SPISTART 1 C C C C SCKD3/SAS		I2CSTAT	GCMEN								
	9D _H	SPITCON		TXCNT6							00 _H
Sechor/SAESCKD6/SAESCKD6/SAESCKD6/SAESCKD4/SA4SCKD3/SA3SCKD2/SA2SCKD1/SA1SCKD0/SA49E_HSPIEART1II <t< td=""><td></td><td>I2CGM</td><td></td><td>STAT6</td><td></td><td></td><td></td><td></td><td></td><td></td><td></td></t<>		I2CGM		STAT6							
								-		-	
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	9E _H	SPISTART	1								80 _H
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $		SPIEND	1								80 _H
A2 _H PWMLOW TONELOW PWM7 TDIV7 PWM6 TDIV6 PWM5 TDIV5 PWM4 TDIV3 PWM4 TDIV3 PWM3 TDIV2 PWM10 TDIV1 PWM10 TDIV0 PWM9 TDIV0 PWM8 TDIV0 O0 _H A3 _H PWM1H TONEHI PWM15 TDIV15 PWM14 TDIV15 PWM13 TDIV14 PWM12 TDIV12 PWM11 TDIV10 PWM9 TDIV9 PWM8 TDIV9 O0 _H A4 _H	A0 _H	P2	P2.7	P2.6	P2.5	P2.4	P2.3	P2.2	P2.1	P2.0	FF _H
$ \begin{array}{ c c c c c c c c c c c c c c c c c c c$	A1 _H	PWMCON			PPOL	PWMSEL	SPDSEL	TPCNTL2	TPCNTL1	TPCNTL0	00 _H
A3 _H PWMHI TONEHI PWM15 TDIV15 PWM14 TDIV14 PWM13 TDIV13 PWM12 TDIV12 PWM11 TDIV11 PWM10 TDIV10 PWM9 TDIV9 PWM8 TDIV8 00 _H A4 _H - -	A2 _H										00 _H
nTONEHITDIV15TDIV14TDIV13TDIV12TDIV11TDIV10TDIV9TDIV9TDIV8n $A4_{H}$											
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	A3 _H										00 _H
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	A4 _H										
A7 _H AISTAT SEC SUM ADC MSEC SPIT SPIR/2CSI ALVD DLVD 00 _H A8 _H IE EA ES1 ET2 ES0 ET1 EX1 ET0 EX0 00 _H A9 _H BPCON BP 0 0 0 0 0 PMSEL EBP 00 _H AA _H BPL 00 _H AA _H BPL 00 _H AA _H BPL								PAI2			
A8 _H IE EA ES1 ET2 ES0 ET1 EX1 ET0 EX0 O0 _H A9 _H BPCON BP 0 0 0 0 0 PMSEL EBP 00 _H AA _H BPL 00 _H AA _H BPL											
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$											
AA BPL Image: Constraint of the state											
AB _H BPH Image: constraint of the state of the sta			BP	0	0	0	0	0	PMSEL	EBP	00 _H
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $											
ΛD _n P0DDRH P07H P07L P06H P06L P05H P05L P04H P04L 00 _H AE _H P1DDRL P13H P13L P12H P12L P11H P11L P10H P10L 00 _H AF _H P1DDRH P17H P17L P16H P16L P15H P14H P14L 00 _H B0 _H P3 P3.7 P3.6 P3.5 P3.4 P3.3 P3.2 P3.1 P3.0 FF _H B0 _H P2DDRL P23H P23L P22H P21L P11L P20H P20L 00 _H B1 _H P2DDRL P23H P23L P22H P21L P21L P20H P20L 00 _H B2 _H P2DDRH P27H P27L P26H P26L P25L P24H P24L 00 _H B3 _H P3DDRL P33H P33L P32L P31H P31L P30H P30L 00 _H B4 _H			DOOLI	DOOL	DOOLI	DOOL	DOCU	DOCI	DOCU	DOCI	
AE _H P1DDRL P13H P13L P12H P12L P11H P11L P10H P10L 00H AF _H P1DDRH P17H P17L P16H P16L P15H P15L P14H P14L 00H B0 _H P3 P3.7 P3.6 P3.5 P3.4 P3.3 P3.2 P3.1 P3.0 FF _H B1 _H P2DDRL P23H P23L P22H P22L P21H P20H P20L 00H B2 _H P2DDRH P27H P23L P22H P22L P21H P20H P20L 00H B3 _H P3DDRL P33H P33L P32H P32L P31H P31L P30H P30L 00H B4 _H P3DDRL P37H P37L P36H P36L P35H P35L P34H P34L 00H B5 _H DACL </td <td></td> <td>-</td> <td></td> <td></td> <td></td> <td></td> <td></td> <td></td> <td></td> <td></td> <td></td>		-									
AF _H P1DDRH P17H P17L P16H P16L P15H P15L P14H P14L 00 _H B0 _H P3 P3.7 P3.6 P3.5 P3.4 P3.3 P3.2 P3.1 P3.0 FF _H B1 _H P2DDRL P23H P23L P22H P22L P21H P20H P20L 00 _H B2 _H P2DDRH P27H P27L P26H P26L P25H P24H P24L 00 _H B3 _H P3DDRL P33H P33L P32H P32L P31H P31L P30H P30L 00 _H B4 _H P3DDRL P37H P37L P36H P36L P35H P31L P30H P30L 00 _H B5 _H DACL B6 _H DACH <		-									
B0 H P3 P3.7 P3.6 P3.5 P3.4 P3.3 P3.2 P3.1 P3.0 FF _H B1 H P2DDRL P23H P23L P21H T0 INT1 INT0 TXD0 RXD0 B1 _H P2DDRL P23H P23L P22H P22L P21H P20H P20L 00 _H B2 _H P2DDRH P27H P27L P26H P26L P25H P24H P24L 00 _H B3 _H P3DDRL P33H P33L P32H P32L P31H P31L P30H P30L 00 _H B4 _H P3DDRH P37H P37L P36H P36L P35H P34H P34L 00 _H B5 _H DACL <t< td=""><td></td><td></td><td></td><td></td><td></td><td></td><td></td><td></td><td></td><td></td><td></td></t<>											
RD WR T1 T0 INT1 INT0 TXD0 RXD0 B1 _H P2DDRL P23H P23L P22H P22L P21H P21L P20H P20L 00 _H B2 _H P2DDRH P27H P27L P26H P26L P25H P25L P24H P24L 00 _H B3 _H P3DDRL P33H P33L P32H P32L P31H P31L P30H P30L 00 _H B4 _H P3DDRH P37H P37L P36H P36L P35H P31L P30H P30L 00 _H B5 _H DACL -											
B1 _H P2DDRL P23H P23L P22H P22L P21H P21L P20H P20L 00 _H B2 _H P2DDRH P27H P27L P26H P26L P25H P25L P24H P24L 00 _H B3 _H P3DDRL P33H P33L P32H P32L P31H P31L P30H P30L 00 _H B4 _H P3DDRH P37H P37L P36H P36L P35H P35L P34H P34L 00 _H B5 _H DACL	H										· · H
B2 _H P2DDRH P27H P27L P26H P26L P25H P25L P24H P24L 00 _H B3 _H P3DDRL P33H P33L P32H P32L P31H P31L P30H P30L 00 _H B4 _H P3DDRH P37H P37L P36H P36L P35H P35L P34H P34L 00 _H B5 _H DACL	B1	P2DDRI									00
B3 P3DDRL P33H P33L P32H P32L P31H P31L P30H P30L 00H B4 P3DDRH P37H P37L P36H P36L P35H P35L P34H P30L 00H B5 _H DACL -											
B4 _H P3DDRH P37H P37L P36H P36L P35H P35L P34H P34L 00 _H B5 _H DACL Image: Constraint of the system o											
B5 _H DACL Image: Constraint of the state of the sta											
B6 _H DACH Image: Constraint of the state of the sta											
B7 _H DACCON DSEL7 DSEL6 DSEL5 DSEL4 DSEL3 DSEL2 DSEL1 DSEL0 00 _H											
			DSEL7	DSEL6	DSEL5	DSEL4	DSEL3	DSEL2	DSEL1	DSEL0	00 _H
ן און און אין איז און איז ארע און אין ארע און	B8 _H	IP	1	PS1	PT2	PS0	PT1	PX1	PT0	PX0	80 _H

SFR Definitions (Boldface is unique to the MSC1211)



ADDRESS	REGISTER	BIT 7	BIT 6	BIT 5	BIT 4	BIT 3	BIT 2	BIT 1	BIT 0	RESET VALUES
B9 _H										
BA _H										
BB _H BC _H										
BD _H										
BE _H										
BF _H										
C0 _H	SCON1	SM0_1	SM1_1	SM2_1	REN_1	TB8_1	RB8_1	TI_1	RI_1	00 _H
C1 _H	SBUF1									00 _H
C2 _H										
C3 _H										
C4 _H										
C5 _H	EWU						EWUWDT	EWUEX1	EWUEX0	00
C6 _H	SYSCLK	0	0	DIVMOD1	DIVMOD0	0	DIV2	DIV1	DIVO	00 _H
С7 _Н		-					+			00 _H
С8 _Н С9 _Н	T2CON	TF2	EXF2	RCLK	TCLK	EXEN2	TR2	C/T2	CP/RL2	00 _H
C3 _H CA _H	RCAP2L									00 _H
CA _H CB _H	RCAP2L RCAP2H									00 _H
CC _H	TL2									00 _H
CD _H	TH2									00 _H
CD _H CE _H	1112		+							
CF _H			1							
D0 _H	PSW	CY	AC	F0	RS1	RS0	OV	F1	Р	00 _H
D0 _H D1 _H	OCL		1.0	10		1.00			LSB	00 _H
D2 _H	OCM		1							00 _H
D3 _H	OCH	MSB								00 _H
D3 _H D4 _H	GCL		1	+					LSB	24 _H
D5 _H	GCM								200	90 _H
D6 _H	GCH	MSB								67 _H
D7 _H	ADMUX	INP3	INP2	INP1	INP0	INN3	INN2	INN1	INN0	01 _H
D8 _H	EICON	SMOD1	1	EAI	AI	WDTI	0	0	0	40 _H
D9 _H	ADRESL						-	-	LSB	00 _H
DA _H	ADRESM									00 _H
DB _H	ADRESH	MSB								00 _H
DCH	ADCON0	_	BOD	EVREF	VREFH	EBUF	PGA2	PGA1	PGA0	38 _H
DD _H	ADCON1	-	POL	SM1	SMO	_	CAL2	CAL1	CALO	x000_0000 _B
DE _H	ADCON2	DR7	DR6	DR5	DR4	DR3	DR2	DR1	DR0	1B _H
DF _H	ADCON3	0	0	0	0	0	DR10	DR9	DR8	06 _H
E0 _H	ACC									00 _H
E1 _H	SSCON	SSCON1	SSCON0	SCNT2	SCNT1	SCNT0	SHF2	SHF1	SHF0	00 _H
E2 _H	SUMR0									00 _H
E3 _H	SUMR1									00 _H
E4 _H	SUMR2									00 _H
E5 _H	SUMR3									00 _H
E6 _H	ODAC									00 _H
E7 _H	LVDCON	ALVDIS	ALVD2	ALVD1	ALVD0	DLVDIS	DLVD2	DLVD1	DLVD0	00 _H
E8 _H	EIE	1	1	1	EWDI	EX5	EX4	EX3	EX2	E0 _H
E9 _H	HWPC0						1	MEMORY	Y SIZE	0000_01xx _B
EA _H	HWPC1					1				08 _H
EBH	HWVER									
ECH	Reserved									00 _H
ED _H	Reserved									00 _H
EEH	FMCON	0	PGERA	0	FRCM	0	BUSY	1	0	02 _H
EF _H	FTCON	FER3	FER2	FER1	FER0	FWR3	FWR2	FWR1	FWR0	A5 _H
F0 _H	В									00 _H
F1 _H	PDCON	0	PDDAC	PDI2C	PDPWM	PDAD	PDWDT	PDST	PDSPI	7F _H
F2 _H	PASEL	0	0	PSEN2	PSEN1	PSEN0	0	ALE1	ALE0	00 _H
F3 _H										
F4 _H										
F5 _H		0	ERFOR	EBEOS	EBEO4	EBEOG	EBEOG	EDE04	EBEOG	
F6 _H	ACLK	0	FREQ6	FREQ5	FREQ4	FREQ3	FREQ2	FREQ1	FREQ0	03 _H
F7 _Н ⊑∘	SRST EIP	0	0	0	0 PWDI	0 PX5	0 PX4	0 PX3	RSTREQ PX2	00 H
F8 _H		1 WPT								E0 _H
F9 _H	SECINT	WRT	SECINT6	SECINT5	SECINT4	SECINT3	SECINT2	SECINT1	SECINTO	7F _H
FA _H	MSINT USEC	WRT 0	MSINT6	MSINT5	MSINT4	MSINT3	MSINT2	MSINT1	MSINT0	7F _H
FB _H	MSECL	U	U	FREQ5	FREQ4	FREQ3	FREQ2	FREQ1	FREQ0	03 _H
FC _H			1							9F _H
FD _H	MSECH HMSEC		1							0F _H
FE _H		EMDT	DWDT	DWDT	WDONT	WDONTO	WDONTO	WDONT4	WDONTO	63 _H
FF _H	WDTCON	EWDT	DWDT	RWDT	WDCNT4	WDCNT3	WDCNT2	WDCNT1	WDCNT0	00 _H



Port 0 (P0)

	7	6	5	4	3	2	1	0	Reset Value
SFR 80 _H	P0.7	P0.6	P0.5	P0.4	P0.3	P0.2	P0.1	P0.0	FF _H

 P0.7-0 Port 0. This port functions as a multiplexed address/data bus during external memory access, and as a generalbits 7-0 purpose I/O port when external memory access is not needed. During external memory cycles, this port will contain the LSB of the address when ALE is HIGH, and Data when ALE is LOW. When used as a general-purpose I/O, this port drive is selected by P0DDRL and P0DDRH (AC_H, AD_H). Whether Port 0 is used as general-purpose I/O or for external memory access is determined by the Flash Configuration Register (HCR1.1) (see SFR CADDR 93_H).

Stack Pointer (SP)

	7	6	5	4	3	2	1	0	Reset Value
SFR 81 _H	SP.7	SP.6	SP.5	SP.4	SP.3	SP.2	SP.1	SP.0	07 _H

SP.7-0 Stack Pointer. The stack pointer identifies the location where the stack will begin. The stack pointer is incremented before bits 7-0 every PUSH or CALL operation and decremented after each POP or RET/RETI. This register defaults to 07_H after reset.

Data Pointer Low 0 (DPL0)

	7	6	5	4	3	2	1	0	Reset Value
SFR 82 _H	DPL0.7	DPL0.6	DPL0.5	DPL0.4	DPL0.3	DPL0.2	DPL0.1	DPL0.0	00 _H

DPL0.7-0 Data Pointer Low 0. This register is the low byte of the standard 8051 16-bit data pointer. DPL0 and DPH0 bits 7-0 are used to point to non-scratchpad data RAM. The current data pointer is selected by DPS (SFR 86_H).

Data Pointer High 0 (DPH0)

	7	6	5	4	3	2	1	0	Reset Value
SFR 83 _H	DPH0.7	DPH0.6	DPH0.5	DPH0.4	DPH0.3	DPH0.2	DPH0.1	DPH0.0	00 _H

DPH0.7-0 Data Pointer High 0. This register is the high byte of the standard 8051 16-bit data pointer. DPL0 and DPH0 bits 7-0 are used to point to non-scratchpad data RAM. The current data pointer is selected by DPS (SFR 86_H).

Data Pointer Low 1 (DPL1)

	7	6	5	4	3	2	1	0	Reset Value
SFR 84 _H	DPL1.7	DPL1.6	DPL1.5	DPL1.4	DPL1.3	DPL1.2	DPL1.1	DPL1.0	00 _H

DPL1.7-0 Data Pointer Low 1. This register is the low byte of the auxiliary 16-bit data pointer. When the SEL bit (DPS.0) bits 7-0 (SFR 86_H) is set, DPL1 and DPH1 are used in place of DPL0 and DPH0 during DPTR operations.

Data Pointer High 1 (DPH1)

	7	6	5	4	3	2	1	0	Reset Value
SFR 85 _H	DPH1.7	DPH1.6	DPH1.5	DPH1.4	DPH1.3	DPH1.2	DPH1.1	DPH1.0	00 _H

DPH1.7-0 Data Pointer High. This register is the high byte of the auxiliary 16-bit data pointer. When the SEL bit (DPS.0) bits 7-0 (SFR 86_H) is set, DPL1 and DPH1 are used in place of DPL0 and DPH0 during DPTR operations.

Data Pointer Select (DPS)

	7	6	5	4	3	2	1	0	Reset Value
SFR 86 _H	0	0	0	0	0	0	0	SEL	00 _H

SEL Data Pointer Select. This bit selects the active data pointer.

0: Instructions that use the DPTR will use DPL0 and DPH0.

1: Instructions that use the DPTR will use DPL1 and DPH1.

bit 0



Power Control (PCON)

	7	6	5	4	3	2	1	0	Reset Value
SFR 87 _H	SMOD	0	1	1	GF1	GF0	STOP	IDLE	30 _H

SMOD Serial Port 0 Baud Rate Doubler Enable. The serial baud rate doubling function for Serial Port 0.

bit 7 0: Serial Port 0 baud rate will be a standard baud rate.

1: Serial Port 0 baud rate will be double that defined by baud rate generation equation.

GF1 General-Purpose User Flag 1. This is a general-purpose flag for software control.

- GF0 General-Purpose User Flag 0. This is a general-purpose flag for software control.
- bit 2

bit 3

STOP Stop Mode Select. Setting this bit will halt the oscillator and block external clocks. This bit will always read as a 0. bit 1 Exit with RESET.

IDLE Idle Mode Select. Setting this bit will freeze the CPU, Timer 0, 1, and 2, and the UARTs; other peripherals remain bit 0 active. This bit will always be read as a 0. Exit with AI ($A6_H$) and EWU ($C6_H$) interrupts.

Timer/Counter Control (TCON)

	7	6	5	4	3	2	1	0	Reset Value
SFR 88 _H	TF1	TR1	TF0	TR0	IE1	IT1	IE0	IT0	00 _H

TF1 Timer 1 Overflow Flag. This bit indicates when Timer 1 overflows its maximum count as defined by the current mode. This bit can be cleared by software and is automatically cleared when the CPU vectors to the Timer 1 interrupt service routine.

0: No Timer 1 overflow has been detected.

1: Timer 1 has overflowed its maximum count.

- **TR1 Timer 1 Run Control.** This bit enables/disables the operation of Timer 1. Halting this timer will preserve the current bit 6 count in TH1, TL1.
 - 0: Timer is halted.

1: Timer is enabled.

- **TF0 Timer 0 Overflow Flag.** This bit indicates when Timer 0 overflows its maximum count as defined by the current mode. This bit can be cleared by software and is automatically cleared when the CPU vectors to the Timer 0 interrupt service routine.
 - 0: No Timer 0 overflow has been detected.
 - 1: Timer 0 has overflowed its maximum count.
- **TR0 Timer 0 Run Control.** This bit enables/disables the operation of Timer 0. Halting this timer will preserve the current count in TH0, TL0.
 - 0: Timer is halted.
 - 1: Timer is enabled.
- IE1 Interrupt 1 Edge Detect. This bit is set when an edge/level of the type defined by IT1 is detected. If IT1 = 1, this bit will remain set until cleared in software or the start of the External Interrupt 1 service routine. If IT1 = 0, this bit will inversely reflect the state of the INT1 pin.
- **IT1** Interrupt 1 Type Select. This bit selects whether the INT1 pin will detect edge or level triggered interrupts.
- bit 2 0: INT1 is level triggered.

1: INT1 is edge triggered.

- IE0 Interrupt 0 Edge Detect. This bit is set when an edge/level of the type defined by IT0 is detected. If IT0 = 1, this bit 3 bit will remain set until cleared in software or the start of the External Interrupt 0 service routine. If IT0 = 0, this bit will inversely reflect the state of the INT0 pin.
- **ITO** Interrupt 0 Type Select. This bit selects whether the INTO pin will detect edge or level triggered interrupts.
- bit 2 0: INTO is level triggered.
 - 1: INTO is edge triggered.



Timer Mode Control (TMOD)

	7	6	5	4	3	2	0		
		TIM	ER 1			Reset Value			
SFR 89 _H	GATE	C/T	M1	M0	GATE	C/T	M1	M0	00 _H

GATE Timer 1 Gate Control. This bit enables/disables the ability of Timer 1 to increment.

bit 7 0: Timer 1 will clock when TR1 = 1, regardless of the state of pin $\overline{INT1}$.

1: Timer 1 will clock only when TR1 = 1 and pin $\overline{INT1}$ = 1.

C/T Timer 1 Counter/Timer Select.

0: Timer is incremented by internal clocks.

1: Timer is incremented by pulses on T1 pin when TR1 (TCON.6, SFR 88_{H}) is 1.

M1, M0 Timer 1 Mode Select. These bits select the operating mode of Timer 1.

M1	MO	MODE
0	0	Mode 0: 8-bit counter with 5-bit prescale.
0	1	Mode 1: 16 bits.
1	0	Mode 2: 8-bit counter with auto reload.
1	1	Mode 3: Timer 1 is halted, but holds its count.

GATE Timer 0 Gate Control. This bit enables/disables the ability of Timer 0 to increment.

- bit 3 0: Timer 0 will clock when TR0 = 1, regardless of the state of pin $\overline{INT0}$ (software control).
 - 1: Timer 0 will clock only when TR0 = 1 and pin $\overline{INT0}$ = 1 (hardware control).

C/T Timer 0 Counter/Timer Select.

bit 2 0: Timer is incremented by internal clocks.

1: Timer is incremented by pulses on pin T0 when TR0 (TCON.4, SFR 88_{H}) is 1.

M1, M0 Timer 0 Mode Select. These bits select the operating mode of Timer 0.

bits 1-0

bit 6

bits 5-4

M1	MO	MODE
0	0	Mode 0: 8-bit counter with 5-bit prescale.
0	1	Mode 1: 16 bits.
1	0	Mode 2: 8-bit counter with auto reload.
1	1	Mode 2: 8-bit counter with auto reload. Mode 3: Timer 1 is halted, but holds its count.

Timer 0 LSB (TL0)

	7	6	5	4	3	2	1	0	Reset Value
SFR 8A _H	TL0.7	TL0.6	TL0.5	TL0.4	TL0.3	TL0.2	TL0.1	TL0.0	00 _H

TL0.7-0 **Timer 0 LSB.** This register contains the least significant byte of Timer 0.

bits 7-0

Timer 1 LSB (TL1)

	7	6	5	4	3	2	1	0	Reset Value
SFR 8B _H	TL1.7	TL1.6	TL1.5	TL1.4	TL1.3	TL1.2	TL1.1	TL1.0	00 _H

TL1.7-0 **Timer 1 LSB.** This register contains the least significant byte of Timer 1.

bits 7-0

Timer 0 MSB (TH0)

	7	6	5	4	3	2	1	0	Reset Value
SFR 8C _H	TH0.7	TH0.6	TH0.5	TH0.4	TH0.3	TH0.2	TH0.1	TH0.0	00 _H

TH0.7-0 Timer 0 MSB. This register contains the most significant byte of Timer 0.

bits 7-0



Timer 1 MSB (TH1)

	7	6	5	4	3	2	1	0	Reset Value
SFR 8D _H	TH1.7	TH1.6	TH1.5	TH1.4	TH1.3	TH1.2	TH1.1	TH1.0	00 _H

TH1.7-0 Timer 1 MSB. This register contains the most significant byte of Timer 1. bits 7-0

Clock Control (CKCON)

	7	6	5	4	3	2	1	0	Reset Value
SFR 8E _H	0	0	T2M	T1M	TOM	MD2	MD1	MD0	01 _H

T2MTimer 2 Clock Select. This bit controls the division of the system clock that drives Timer 2. This bit has no effectbit 5when the timer is in baud rate generator or clock output modes. Clearing this bit to 0 maintains 8051compatibility. This bit has no effect on instruction cycle timing.

0: Timer 2 uses a divide by 12 of the crystal frequency.

1: Timer 2 uses a divide by 4 of the crystal frequency.

T1M Timer 1 Clock Select. This bit controls the division of the system clock that drives Timer 1. Clearing this bit to 0 maintains 8051 compatibility. This bit has no effect on instruction cycle timing.

0: Timer 1 uses a divide by 12 of the crystal frequency.

1: Timer 1 uses a divide by 4 of the crystal frequency.

- **TOM Timer 0 Clock Select.** This bit controls the division of the system clock that drives Timer 0. Clearing this bit to 0 maintains 8051 compatibility. This bit has no effect on instruction cycle timing.
 - 0: Timer 0 uses a divide by 12 of the crystal frequency.
 - 1: Timer 0 uses a divide by 4 of the crystal frequency.
- MD2, MD1, MD0 bits 2-0 Stretch MOVX Select 2-0. These bits select the time by which external MOVX cycles are to be stretched. This allows slower memory or peripherals to be accessed without using ports or manual software intervention. The for RD or WR strobe will be stretched by the specified interval, which will be transparent to the software except for the increased time to execute the MOVX instruction. All internal MOVX instructions on devices containing MOVX SRAM are performed at the 2 instruction cycle rate.

MD2	MD1	MD0	STRETCH VALUE	MOVX DURATION	RD or WR STROBE WIDTH (SYS CLKs)	RD or WR STROBE WIDTH (μs) AT 12MHz
0	0	0	0	2 Instruction Cycles	2	0.167
0	0	1	1	3 Instruction Cycles (default)	4	0.333
0	1	0	2	4 Instruction Cycles	8	0.667
0	1	1	3	5 Instruction Cycles	12	1.000
1	0	0	4	6 Instruction Cycles	16	1.333
1	0	1	5	7 Instruction Cycles	20	1.667
1	1	0	6	8 Instruction Cycles	24	2.000
1	1	1	7	9 Instruction Cycles	28	2.333

Memory Write Select (MWS)

	7	6	5	4	3	2	1	0	Reset Value
SFR 8F _H	0	0	0	0	0	0	0	MXWS	00 _H

MXWS MOVX Write Select. This allows writing to the internal Flash program memory.

0: No writes are allowed to the internal Flash program memory.

1: Writing is allowed to the internal Flash program memory, unless PML (HCR0) or RSL (HCR0) are on.



bit 0

Port	1	(P	1)
------	---	----	----

	7	6	5	4	3	2	1	0	Reset Value	
SFR 90 _H	P1.7 INT5/SCLK/SCK	P1.6 INT4/MISO/SDA	P1.5 INT3/MOSI	P1.4 INT2/SS	P1.3 TXD1	P1.2 RXD1	P1.1 T2EX	P1.0 T2	FF _H	
P1.7-0 bits 7-0	an alternative 1 latch bit mus	pose I/O Port 1. function listed be st contain a logic he appropriate n	elow. Each o '1' before th	f the functio e pin can be	ns is contro e used in its	olled by seve alternate fu	eral other S unction capa	FRs. The a	associated Por	
INT5/SCLK/S bit 7	SCK Externa SPI Clo Serial C		falling edge ne master cl ne serial clo	ock for SPI	data trans	fers.	l interrupt {	5 if enable	d.	
INT4/MISO/S bit 6		l Interrupt 4. A n Slave Out. Fo Fo	•••	insfers, this p	in receives o	lata for the n	-		a from the slave	
INT3/MOSI bit 5		rrupt 3. A falling lave In. For SP		•			•		data.	
INT2/SS bit 4	External Inte Slave Select	rrupt 2. A rising During	edge on th SPI operatio	•			•		rice.	
TXD1 bit 3		Transmit. This clock in serial p	•		al Port 1 da	ata in seria	l port mode	es 1, 2, 3,	and emits the	
RXD1 bit 2		Receive. This p pin in serial port		he serial Po	ort 1 data ir	n serial port	modes 1, 2	2, 3, and is	a bidirectiona	
T2EX bit 1	Timer 2 Capture/Reload Trigger. A 1 to 0 transition on this pin will cause the value in the T2 registers to b transferred into the capture registers if enabled by EXEN2 (T2CON.3, SFR C8 _H). When in auto-reload mode, a 1 to transition on this pin will reload the Timer 2 registers with the value in RCAP2L and RCAP2H if enabled b EXEN2 (T2CON.3, SFR C8 _H).									
T2 bit 0	Time 2 External Input. A 1 to 0 transition on this pin will cause Timer 2 to increment or decrement dependit on the timer configuration.									

External Interrupt Flag (EXIF)

	7	6	5	4	3	2	1	0	Reset Value
SFR 91 _H	IE5	IE4	IE3	IE2	1	0	0	0	08 _H

IE5	External Interrupt 5 Flag. This bit will be set when a falling edge is detected on INT5. This bit must be
bit 7	cleared manually by software. Setting this bit in software will cause an interrupt if enabled.
IF4	External Interrupt 4 Flag. This bit will be set when a rising edge is detected on INT4. This bit must be cleared

External Interrupt 4 Flag. This bit will be set when a rising edge is detected on INT4. This bit must be cleared bit 6 manually by software. Setting this bit in software will cause an interrupt if enabled.

IE3 External Interrupt 3 Flag. This bit will be set when a falling edge is detected on INT3. This bit must be cleared bit 5 manually by software. Setting this bit in software will cause an interrupt if enabled.

IE2 External Interrupt 2 Flag. This bit will be set when a rising edge is detected on INT2. This bit must be cleared bit 4 manually by software. Setting this bit in software will cause an interrupt if enabled.

Memory Page (MPAGE)

	7	6	5	4	3	2	1	0	Reset Value
SFR 92 _H									00 _H

 MPAGE
 The 8051 uses Port 2 for the upper 8 bits of the external data memory access by MOVX A@R₁ and MOVX @R₁,

 bits 7-0
 A instructions. The MSC1211 uses register MPAGE instead of Port 2. To access external data memory using the MOVX A@R₁ and MOVX @R₁, A instructions, the user should preload the upper byte of the address into MPAGE (versus preloading into P2 for the standard 8051).



Configuration Address Register (CADDR) (write only)

	7	6	5	4	3	2	1	0	Reset Value
SFR 93 _H									00 _H

CADDR Configuration Address Register. This register supplies the address for reading bytes in the 128 bytes of Flash Configuration bits 7-0 Memory. WARNING: If this register is written to while executing from Flash Memory, the CDATA register will be incorrect.

Configuration Data Register (CDATA)

	7	6	5	4	3	2	1	0	Reset Value
SFR 94 _H									00 _H

CDATA Configuration Data Register. This register will contain the data in the 128 bytes of Flash Configuration Memory bits 7-0 that is located at the last written address in the CADDR register. This is a read-only register.

Memory Control (MCON)

	7	6	5	4	3	2	1	0	Reset Value
SFR 95 _H	BPSEL	0	0	_	-	_	_	RAMMAP	00 _H

BPSEL Breakpoint Address Selection

- bit 7 Write: Select one of two Breakpoint registers: 0 or 1.
 0: Select breakpoint register 0.
 1: Select breakpoint register 1.
 Read: Provides the Breakpoint register that created the last interrupt: 0 or 1.
- RAMMAP
 Memory Map 1kB extended SRAM.

 bit 0
 0: Address is: 0000_H-03FF_H (default) (Data Memory)

 1: Address is 8400_H-87FF_H (Data and Program Memory)

Serial Port 0 Control (SCON0)

	7	6	5	4	3	2	1	0	Reset Value
SFR 98 _H	SM0_0	SM1_0	SM2_0	REN_0	TB8_0	RB8_0	TI_0	RI_0	00 _H

SM0-2 Serial Port 0 Mode. These bits control the mode of serial Port 0. Modes 1, 2, and 3 have 1 start and 1 stop bit in addition to the 8 or 9 data bits.

MODE	SM0	SM1	SM2	FUNCTION	LENGTH	PERIOD				
0	0	0	0	Synchronous	8 bits	12 p _{CLK} ⁽¹⁾				
0	0	0	1	Synchronous	8 bits	4 p _{CLK} ⁽¹⁾				
1 ⁽²⁾	0	1	х	Asynchronous	10 bits	Timer 1 or 2 Baud Rate Equation				
2	1	0	0	Asynchronous	11 bits	$64 p_{CLK}^{(1)} (SMOD = 0)$				
						$32 p_{CLK}^{(1)} (SMOD = 1)$				
2	1	0	1	Asynchronous with	11 bits	64 $p_{CLK}^{(1)}$ (SMOD = 0)				
				Multiprocessor Communication		$32 p_{CLK}^{(1)} (SMOD = 1)$				
3(2)	1	1	0	Asynchronous	11 bits	Timer 1 or 2 Baud Rate Equation				
3(2)	1	1	1	Asynchronous with	11 bits	Timer 1 or 2 Baud Rate Equation				
				Multiprocessor Communication						
	NOTE: (1) p_{CLK} will be equal to t_{CLK} , except that p_{CLK} will stop for IDLE. (2) For modes 1 and 3, the selection of Timer 1 or 2 for baud rate is specified via the T2CON (C8 _H) register.									

REN_0 Receive Enable. This bit enables/disables the serial Port 0 received shift register.

bit 4 0: Serial Port 0 reception disabled.

1: Serial Port 0 received enabled (modes 1, 2, and 3). Initiate synchronous reception (mode 0).

TB8_0 9th Transmission Bit State. This bit defines the state of the 9th transmission bit in serial Port 0 modes 2 and 3. bit 3

- **RB8_09th Received Bit State.** This bit identifies the state of the 9th reception bit of received data in serial Port 0 modesbit 22 and 3. In serial port mode 1, when SM2_0 = 0, RB8_0 is the state of the stop bit. RB8_0 is not used in mode 0.
- TI_0Transmitter Interrupt Flag. This bit indicates that data in the serial Port 0 buffer has been completely shiftedbit 1out. In serial port mode 0, TI_0 is set at the end of the 8th data bit. In all other modes, this bit is set at the end
of the last data bit. This bit must be manually cleared by software.





RI_0 Receiver Interrupt Flag. This bit indicates that a byte of data has been received in the serial Port 0 buffer. In serial port mode 0, RI_0 is set at the end of the 8th bit. In serial port mode 1, RI_0 is set after the last sample of the incoming stop bit subject to the state of SM2_0. In modes 2 and 3, RI_0 is set after the last sample of RB8_0. This bit must be manually cleared by software.

Serial Data Buffer 0 (SBUF0)

	7	6	5	4	3	2	1	0	Reset Value
SFR 99 _H									00 _H

SBUF0 Serial Data Buffer 0. Data for Serial Port 0 is read from or written to this location. The serial transmit and bits 7-0 receive buffers are separate registers, but both are addressed at this location.

SPI Control (SPICON). Any change resets the SPI interface, counters, and pointers. PDCON controls which is enabled.

	7	6	5	4	3	2	1	0	Reset Value
SFR 9A _H	SCLK2	SCLK1	SCLK0	FIFO	ORDER	MSTR	CPHA	CPOL	00 _H

SCLK Sck Selection. Selection of t_{CLK} divider for generation of SCK in Master mode.

bits 7-5

bit 2

SCLK2	SCLK1	SCLK0	SCK PERIOD
0	0	0	t _{CLK} /2
0	0	1	t _{CLK} /4
0	1	0	t _{CLK} /8
0	1	1	t _{CLK} /16
1	0	0	t _{CLK} /32
1	0	1	t _{CLK} /64
1	1	0	t _{CLK} /128
1	1	1	t _{CLK} /256

FIFO	Enable FIFO in on-chip indirect memory.
hi+ 1	Or Both transmit and reasing are double buffers

- bit 4 0: Both transmit and receive are double buffers
 - 1: Circular FIFO used for transmit and receive bytes

ORDER Set Bit Order for Transmit and Receive.

- bit 3 0: Most Significant Bits First
 - 1: Least Significant Bits First

MSTR SPI Master Mode.

- 0: Slave Mode
 - 1: Master Mode

CPHA Serial Clock Phase Control.

- bit 1 0: Valid data starting from half SCK period before the first edge of SCK
 - 1: Valid data starting from the first edge of SCK

CPOL Serial Clock Polarity.

- bit 0 0: SCK idle at logic LOW
 - 1: SCK idle at logic HIGH

I²C Control Register (I2CCON)

	7	6	5	4	3	2	1	0	Reset Value
SFR 9A _H	START	STOP	ACK	0	FAST	MSTR	SCLS	FILEN	00 _H

START Start Condition (Master mode).

bit 7 Read: Current status of start condition or repeated start condition.

Write: When operating as a master, a start condition is transmitted when the START bit is set to 1. During a data transfer, if the START bit is set, a repeated start is transmitted after the current data transfer is complete. If no transfer is in progress when the START and STOP bits are set simultaneously, a START will be followed by a STOP.





STOP Stop Condition (Master mode).

- Read: Current status of stop condition. bit 6
 - Write: Setting STOP to logic 1 causes a stop condition to be transmitted. When a stop condition is received, hardware clears STOP to logic 0. If both START and STOP are set during a transfer, a stop condition is transmitted followed by a start condition.
- Acknowledge. Defines the ACK/NACK generation from the master/slave receiver during the acknowledge cycle. ACK bit 5 0: A NACK (high level on SDA) is returned during the acknowledge cycle.
 - 1: An ACK (low level on SDA) is returned during the ackowledge cycle.

ero.

bit 4

FAST Fast Mode Enable.

- bit 3 0: Standard Mode (100kHz) 1: Fast Mode (400kHz)
- **MSTR** SPI Master Mode.
- bit 2 0: Slave Mode
 - 1: Master Mode

Clock Stretch. SCLS

bit 1 0: No effect

1: Release the clock line. For the slave mode, the clock is stretched for each data transfer. This bit releases the clock. This bit can be set during a transfer to eliminate any clock stretching.

- FILEN Filter Enable. 50ns glitch filter.
- bit 0 0: Filter disabled
 - 1: Filter enabled

SPI Data Register (SPIDATA) / I²C Data Register (I2CDATA)

	7	6	5	4	3	2	1	0	Reset Value
SFR 9B _H									00 _H

SPIDATA SPI Data Register. Data for SPI is read from or written to this location. The SPI transmit and receive buffers bits 7-0 are separate registers, but both are addressed at this location.

I2CDATA I2C Data Register. Data for I2C is read from or written to this location. The I2C transmit and receive buffers bits 7-0 are separate registers, but both are addressed at this location.

SPI Receive Control Register (SPIRCON)

	7	6	5	4	3	2	1	0	Reset Value
SFR 9C _H	RXCNT7 RXFLUSH	RXCNT6	RXCNT5	RXCNT4	RXCNT3	RXCNT2 RXIRQ2	RXCNT1 RXIRQ1	RXCNT0 RXIRQ0	00 _H

RXCNT Receive Counter. Read only bits which read the number of bytes in the receive buffer (0 to 128).

bits 7-0

bits 2-0

RXFLUSH Flush Receive FIFO. Write only.

bit 7 0: No Action

1: SPI Receive Buffer Set to Empty

Read IRQ Level. Write only. RXIRQ

000	Generate IRQ when Receive Count = 1 or more.
001	Generate IRQ when Receive Count = 2 or more.
010	Generate IRQ when Receive Count = 4 or more.
011	Generate IRQ when Receive Count = 8 or more.
100	Generate IRQ when Receive Count = 16 or more.
101	Generate IRQ when Receive Count = 32 or more.
110	Generate IRQ when Receive Count = 64 or more.
111	Generate IRQ when Receive Count = 128 or more.



I²C GM Register (I2CGM)

	7	6	5	4	3	2	1	0	Reset Value
SFR 9C _H	GCMEN								00 _H

GCMEN General Call/Multiple Master Enable. Write only.

bit 7 Slave mode: 0 = General call ignored, 1 = General call will be detected Master mode: 0 = Single master, 1 = Multiple master mode

SPI Transmit Control Register (SPITCON)

	7	6	5	4	3	2	1	0	Reset Value
SFR 9D _H	TXCNT7	TXCNT6	TXCNT5	TXCNT4	TXCNT3	TXCNT2	TXCNT1	TXCNT0	00 _H
	TXFLUSH		CLK_EN	DRV_DLY	DRV_EN	TXIRQ2	TXIRQ1	TXIRQ0	

TXCNT Transmit Counter. Read only bits which read the number of bytes in the transmit buffer (0 to 128).

bits 7-0

TXFLUSH Flush Transmit FIFO. This bit is write only. When set, the SPI transmit pointer is set equal to the FIFO bit 7 Output pointer. This bit is 0 for a read operation.

CLK_EN SCLK Driver Enable.

bit 5 0: Disable SCLK Driver (Master Mode)

1: Enable SCLK Driver (Master Mode)

DRV_DLY Drive Delay (refer to DRV_EN bit).

- 0: Drive Output Immediately
 - 1: Drive Output After Current Byte Transfer

DRV_EN Drive Enable.

bit 3

bit 4

DRV_DLY	DRV_EN	MOSI or MISO OUTPUT CONTROL					
0	0	Tristate Immediately					
0	1	Drive Immediately					
1	0	Tristate After the Current Byte Transfer					
1	1	Drive After the Current Byte Transfer					

TXIRQ

Transmit IRQ Level. Write only bits.

bits 2-0

000	Generate IRQ when Transmit count = 1 or less.
001	Generate IRQ when Transmit count = 2 or less.
010	Generate IRQ when Transmit count = 4 or less.
011	Generate IRQ when Transmit count = 8 or less.
100	Generate IRQ when Transmit count = 16 or less.
101	Generate IRQ when Transmit count = 32 or less.
110	Generate IRQ when Transmit count = 64 or less.
111	Generate IRQ when Transmit count = 128 or less.

I²C Status Register (I2CSTAT)

	7	6	5	4	3	2	1	0	Reset Value
SFR 9D _H	STAT7	STAT6	STAT5	STAT4	STAT3	0	0	0	00 _H
	SCKD7/SAE	SCKD6/SA6	SCKD5/SA5	SCKD4/SA4	SCKD3/SA3	SCKD2/SA2	SCKD1/SA1	SCKD0/SA0	

STAT7-3 bit 7-3	Status Code. Read only.
SCKD7-0	Serial Clock Divisor. Write only, master mode.
bit 7-0	The frequency of the SCL line is set equal to Sysclk/[2 • (SCKD + 1)]. The minimum value for SCKD is 3.
SAE	Slave Address Enable. Write only, slave mode.
bit 7	In slave mode, if this is set, address recognition is enabled.

SA6-0 Slave Address. Write only, slave mode.

bit 6-0 The address of this device is used in slave mode for address recognition.





SPI Buffer Start Address (SPISTART)

	7	6	5	4	3	2	1	0	Reset Value
SFR 9E _H	1								80 _H

SPISTARTSPI FIFO Start Address. Write only. This specifies the start address of the SPI data buffer. This is a
circular FIFO that is located in the 128 bytes of indirect RAM. The FIFO starts at this address and ends
at the address specified in SPIEND. Must be less than SPIEND. Writing clears SPI transmit and receive counters.

SPITP SPI Transmit Pointer. Read Only. This is the FIFO address for SPI transmissions. This is where the next byte will be written into the SPI FIFO buffer. This pointer increments after each write to the SPI Data register unless that would make it equal to the SPI Receive pointer.

SPI Buffer End Address (SPIEND)

	7	6	5	4	3	2	1	0	Reset Value
SFR 9F _H	1								80 _H

SPIEND SPI FIFO End Address. Write only. This specifies the end address of the SPI data FIFO. This is a circular buffer bits 6-0 that is located in the 128 bytes of indirect RAM. The buffer starts at SPISTART and ends at this address.

SPIRP SPI Receive Pointer. Read Only. This is the FIFO address for SPI received bytes. This is the location of the next bits 6-0 byte to be read from the SPI FIFO. This increments with each read from the SPI Data register until the RxCNT is zero.

Port 2 (P2)

	7	6	5	4	3	2	1	0	Reset Value
SFR A0 _H									FF _H

P2 Port 2. This port functions as an address bus during external memory access, and as a general-purpose I/O port. bits 7-0 During external memory cycles, this port will contain the MSB of the address. Whether Port 2 is used as generalpurpose I/O or for external memory access is determined by the Flash Configuration Register (HCR1.0).

PWM Control (PWMCON)

	7	6	5	4	3	2	1	0	Reset Value
SFR A1 _H	—	_	PPOL	PWMSEL	SPDSEL	TPCNTL.2	TPCNTL.1	TPCNTL.0	00 _H

PPOL Period Polarity. Specifies the starting level of the PWM pulse.

- bit 5 0: ON Period. PWM Duty register programs the ON period.
 - 1: OFF Period. PWM Duty register programs the OFF period.
- PWMSEL PWM Register Select. Select which 16-bit register is accessed by PWMLOW/PWMHIGH.
- bit 4 0: Period (must be 0 for TONE mode)
 - 1: Duty
- SPDSEL Speed Select.
- bit 3 0: 1MHz (the USEC Clock)
 - 1: SYSCLK

TPCNTL Tone Generator/Pulse Width Modulation Control.

bits 2-0	TPCNTL.2	TPCNTL.1	TPCNTL.0	MODE
	0	0	0	Disable (default)
	0	0	1	PWM
	0	1	1	TONE—Square
	1	1	1	TONE—Staircase

Tone Low (TONELOW) /PWM Low (PWMLOW)

	7	6	5	4	3	2	1	0	Reset Value
SFR A2 _H	PWM7	PWM6	PWM5	PWM4	PWM3	PWM2	PWM1	PWM0	00 _H
	TDIV7	TDIV6	TDIV5	TDIV4	TDIV3	TDIV2	TDIV1	TDIV0	

PWMLOW Pulse Width Modulator Low Bits. These 8 bits are the least significant 8 bits of the PWM register. bits 7-0

TDIV7-0 Tone Divisor. The low order bits that define the half-time period. For staircase mode the output is high impedance for the last 1/4 of this period.





Tone High (TONEHI)/PWM High (PWMHI)

	7	6	5	4	3	2	1	0	Reset Value
SFR A3 _H	PWM15	PWM14	PWM13	PWM12	PWM11	PWM10	PWM9	PWM8	00 _H
	TDIV15	TDIV14	TDIV13	TDIV12	TDIV11	TDIV10	TDIV9	TDIV8	

PWMHI Pulse Width Modulator High Bits. These 8 bits are the high order bits of the PWM register. bits 7-0

TDIV15-8 Tone Divisor. The high order bits that define the half time period. For staircase mode the output is high bits 7-0 impedance for the last 1/4 of this period.

Pending Auxiliary Interrupt (PAI)

	7	6	5	4	3	2	1	0	Reset Value
SFR A5 _H	0	0	0	0	PAI3	PAI2	PAI1	PAI0	00 _H

PAI bits 3-0

Pending Auxiliary Interrupt Register. The results of this register can be used as an index to vector to the appropriate interrupt routine. All of these interrupts vector through address 0033_H.

PAI3	PAI2	PAI1	PAI0	AUXILIARY INTERRUPT STATUS
0	0	0	0	No Pending Auxiliary IRQ
0	0	0	1	Digital Low Voltage IRQ Pending
0	0	1	0	Analog Low Voltage IRQ Pending
0	0	1	1	SPI Receive IRQ Pending. I ² C Status Pending.
0	1	0	0	SPI Transmit IRQ Pending
0	1	0	1	One Millisecond System Timer IRQ Pending
0	1	1	0	Analog to Digital Conversion IRQ Pending
0	1	1	1	Accumulator IRQ Pending
1	0	0	0	One Second System Timer IRQ Pending

Auxiliary Interrupt Enable (AIE)

	7	6	5	4	3	2	1	0	Reset Value
SFR A6 _H	ESEC	ESUM	EADC	EMSEC	ESPIT	ESPIR/EI2C	EALV	EDLVB	00 _H

Interrupts are enabled by EICON.4 (SFR D8_H). The other interrupts are controlled by the IE and EIE registers.

ESEC bit 7	Enable Seconds Timer Interrupt (lowest priority auxialiary interrupt). Write: Set mask bit for this interrupt 0 = masked, 1 = enabled. Read: Current value of Seconds Timer Interrupt before masking.
ESUM bit 6	Enable Summation Interrupt. Write: Set mask bit for this interrupt 0 = masked, 1 = enabled. Read: Current value of Summation Interrupt before masking.
EADC bit 5	Enable ADC Interrupt. Write: Set mask bit for this interrupt 0 = masked, 1 = enabled. Read: Current value of ADC Interrupt before masking.
EMSEC bit 4	Enable Millisecond System Timer Interrupt. Write: Set mask bit for this interrupt 0 = masked, 1 = enabled. Read: Current value of Millisecond System Timer Interrupt before masking.
ESPIT bit 3	Enable SPI Transmit Interrupt. Write: Set mask bit for this interrupt 0 = masked, 1 = enabled. Read: Current value of SPI Transmit Interrupt before masking.
ESPIR/EI2C bit 2	Enable SPI Receive Interrupt. Enable I ² C Status Interrupt. Write: Set mask bit for this interrupt 0 = masked, 1 = enabled. Read: Current value of SPI Receive Interrupt or I2C Status Interrupt before masking.
EALV bit 1	Enable Analog Low Voltage Interrupt. Write: Set mask bit for this interrupt 0 = masked, 1 = enabled. Read: Current value of Analog Low Voltage Interrupt before masking.
EDLVB bit 0	Enable Digital Low Voltage or Breakpoint Interrupt (highest priority auxiliary interrupt). Write: Set mask bit for this interrupt 0 = masked, 1 = enabled. Read: Current value of Digital Low Voltage or Breakpoint Interrupt before masking.

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Auxiliary Interrupt Status Register (AISTAT)

	7	6	5	4	3	2	1	0	Reset Value
SFR A7 _H	SEC	SUM	ADC	MSEC	SPIT	SPIR/I2CSI	ALVD	DLVD	00 _H
SEC pit 7	0: SEC int	ystem Time errupt inact terrupt active	ive or mask		g (lowest	priority Al).			
SUM bit 6	0: SUM int	on Register errupt inacti terrupt activ	ve or maske	-		tive by readir	ng the lowes	t byte of the	Summation registe
ADC bit 5	0: ADC inte	•	e or masked	•		ive by reading itten to the D		•	ata Output Registe
MSEC bit 4	0: MSEC i	nd System Interrupt ina Interrupt act	ctive or mas	-	Flag.				
SPIT bit 3	0: SPI trar	mit Interru nsmit interru nsmit interru	pt inactive of	-					
SPIR/I2CS bit 2		ve Interrup eive or I2CS eive or I2CS	SI interrupt i	nactive or r		pt.			
ALVD pit 1	0: ALVD in	ow Voltage nterrupt inac nterrupt acti	tive or mas		ıs Flag.				
DLVD	Digital Lo	w Voltage	Detect or B	reakpoint	Interrupt S	tatus Flag (ł	nighest pric	ority Al).	

- bit 0 0: DLVD interrupt inactive or masked.
 - 1: DLVD interrupt active.

Interrupt Enable (IE)

	-	-							
	7	6	5	4	3	2	1	0	Reset Value
SFR A8 _H	EA	ES1	ET2	ES0	ET1	EX1	ET0	EX0	00 _H

- EA Global Interrupt Enable. This bit controls the global masking of all interrupts except those in AIE (SFR A6_H).
 bit 7 0: Disable interrupt sources. This bit overrides individual interrupt mask settings for this register.
- 1: Enable all individual interrupt masks. Individual interrupts in this register will occur if enabled.
- ES1 Enable Serial Port 1 Interrupt. This bit controls the masking of the serial Port 1 interrupt.
- bit 6 0: Disable all serial Port 1 interrupts.
 - 1: Enable interrupt requests generated by the RI_1 (SCON1.0, SFR C0_H) or TI_1 (SCON1.1, SFR C0_H) flags.
- ET2 Enable Timer 2 Interrupt. This bit controls the masking of the Timer 2 interrupt.
- bit 5 0: Disable all Timer 2 interrupts.
 - 1: Enable interrupt requests generated by the TF2 flag (T2CON.7, SFR $C8_{H}$).
- **ES0** Enable Serial port 0 interrupt. This bit controls the masking of the serial Port 0 interrupt.
- bit 4 0: Disable all serial Port 0 interrupts.
 - 1: Enable interrupt requests generated by the RI_0 (SCON0.0, SFR 98_H) or TI_0 (SCON0.1, SFR 98_H) flags.



- ET1 Enable Timer 1 Interrupt. This bit controls the masking of the Timer 1 interrupt. bit 3
 Disable Timer 1 interrupt. 1: Enable interrupt requests generated by the TF1 flag (TCON.7, SFR 88_H).
 EX1 Enable External Interrupt 1. This bit controls the masking of external interrupt 1. bit 2
 Disable external interrupt 1. 1: Enable interrupt requests generated by the INT1 pin.
 ET0 Enable Timer 0 Interrupt. This bit controls the masking of the Timer 0 interrupt. bit 1
 Disable all Timer 0 interrupts. 1: Enable interrupt requests generated by the TF0 flag (TCON.5, SFR 88_H).
- **EX0** Enable External Interrupt 0. This bit controls the masking of external interrupt 0.
- bit 0 0: Disable external interrupt 0.
 - 1: Enable interrupt requests generated by the INTO pin.

Breakpoint Control (BPCON)

	7	6	5	4	3	2	1	0	Reset Value
SFR A9 _H	BP	0	0	0	0	0	PMSEL	EBP	00 _H

Writing to register sets the breakpoint condition specified by MCON, BPL, and BPH.

- BP Breakpoint Interrupt. This bit indicates that a break condition has been recognized by a hardware breakpoint register(s).
- bit 7 Read: Status of Breakpoint Interrupt. Will indicate a breakpoint match for any of the breakpoint registers. Write: 0: No effect.

1: Clear Breakpoint 1 for breakpoint register selected by MCON (SFR 95_H).

- PMSEL
 Program Memory Select. Write this bit to select memory for address breakpoints of register selected in

 bit 1
 MCON (SFR 95_H).
 - 0: Break on address in data memory.
 - 1: Break on address in program memory.
- **EBP Enable Breakpoint.** This bit enables this breakpoint register. Address of breakpoint register selected by bit 0 MCON (SFR 95_H).
 - 0: Breakpoint disabled.
 - 1: Breakpoint enabled.

Breakpoint Low (BPL) Address for BP Register Selected in MCON (95_H)

	7	6	5	4	3	2	1	0	Reset Value
SFR AA _H	BPL.7	BPL.6	BPL.5	BPL.4	BPL.3	BPL.2	BPL.1	BPL.0	00 _H

BPL.7-0 Breakpoint Low Address. The low 8 bits of the 16 bit breakpoint address.

bits 7-0

Breakpoint High Address (BPH) Address for BP Register Selected in MCON (95_H)

	7	6	5	4	3	2	1	0	Reset Value
SFR AB _H	BPH.7	BPH.6	BPH.5	BPH.4	BPH.3	BPH.2	BPH.1	BPH.0	00 _H

BPH.7-0 Breakpoint High Address. The high 8 bits of the 16 bit breakpoint address.

bits 7-0



Port 0 Data Direction Low Register (P0DDRL)

	7	6	5	4	3	2	1	0	Reset Value
SFR AC _H	P03H	P03L	P02H	P02L	P01H	P01L	P00H	P00L	00 _H

P0.3 bits 7-6

Port 0 bit 3 control.

P03H	P03L	
0	0	Standard 8051(Pull-Up)
0	1	CMOS Output
1	0	Open Drain Output
1	1	Input

P0.2 Port 0 bit 2 control.

P02H	P02L	
0	0	Standard 8051(Pull-Up)
0	1	CMOS Output
1	0	Open Drain Output
1	1	Input

P0.1 P0

bits 3-2

bits 1-0

bits 5-4

Port 0 bit 1 control.

P01H	P01L	
0	0	Standard 8051(Pull-Up)
0	1	CMOS Output
1	0	Open Drain Output
1	1	Input

P0.0 Port 0 bit 0 control.

P00H	P00L	
0	0	Standard 8051(Pull-Up)
0	1	CMOS Output
1	0	Open Drain Output
1	1	Input

NOTE: Port 0 also controlled by $\overline{\mathsf{EA}}$ and Memory Access Control HCR1.1.

Port 0 Data Direction High Register (P0DDRH)

	7	6	5	4	3	2	1	0	Reset Value
SFR AD _H	P07H	P07L	P06H	P06L	P05H	P05L	P04H	P04L	00 _H

P0.7 Port 0 bit 7 control. bits 7-6 P07H P07I

P07H	ł	P07L	
0		0	Standard 8051(Pull-Up)
0		1	CMOS Output
1		0	Open Drain Output
1		1	Input

P0.6 F

bits 5-4

Port 0 bit 6 control.

P06H	P06L	
0	0	Standard 8051(Pull-Up)
0	1	CMOS Output
1	0	Open Drain Output
1	1	Input

P0.5

bits 3-2

Port 0 bit 5 control.

P05H	P05L	
0	0	Standard 8051(Pull-Up)
0	1	CMOS Output
1	0	Open Drain Output
1	1	Input

P0.4 Port 0 bit 4 control. bits 1-0 P04H P04L

P04H	P04L	
0	0	Standard 8051(Pull-Up)
0	1	CMOS Output
1	0	Open Drain Output
1	1	Input





	7	6	5	4	3	2	1	0	Reset
SFR AE _H	P13H	P13L	P12H	P12L	P11H	P11L	P10H	P10L	00
P1.3	Port 1 bi	t 3 conti	rol.					• • •	
bits 7-6	P13H	P13L							
	0	0	Standard 8051						
	0	1	CMOS Output						
	1	0	Open Drain Out	put					
	1	1	Input						
P1.2	Port 1 bi	t 2 conti	rol.						
bits 5-4	P12H	P12L							
	0	0	Standard 8051						
	0	1	CMOS Output						
	1	0	Open Drain Out	put					
	1	1	Input						
P1.1	Port 1 bi	t 1 conti	rol.						
bits 3-2	P11H	P11L							
	0	0	Standard 8051						
	0	1	CMOS Output						
	1	0	Open Drain Out	put					
	1	1	Input						
P1.0	Port 1 bi	t 0 conti	rol.						
bits 1-0	P10H	P10L							
	0	0	Standard 8051						
	0	1	CMOS Output						
	1	0	Open Drain Out	put					
	1	1	Input						

Port 1 Data Direction Low Register (P1DDRL)

Port 1 Data Direction High Register (P1DDRH)

	7	6	5	4	3	2	1	0	Reset Value
SFR AF _H	P17H	P17L	P16H	P16L	P15H	P15L	P14H	P14L	00 _H

P1.7	Port 1 bi	t 7 contr	ol.
bits 7-6	P17H	P17L	
	0	0	Standard 8051
	0	1	CMOS Output
	1	0	Open Drain Output
	1	1	Input
P1.6	Port 1 bi	t 6 contr	ol.
bits 5-4	P16H	P16L	
	0	0	Standard 8051
	0	1	CMOS Output
	1	0	Open Drain Output
	1	1	Input
P1.5	Port 1 bi	t 5 contr	ol.
bits 3-2	P15H	P15L	
	0	0	Standard 8051
	0	1	CMOS Output
	1	0	Open Drain Output
	1	1	Input
P1.4	Port 1 bi		
P1.4 bits 1-0			
	Port 1 bi	t 4 contr	
	Port 1 bi	t 4 contr P14L	OL Standard 8051 CMOS Output
	Port 1 bi	t 4 contr P14L 0	Ol. Standard 8051



	7	6	5	4	3	2	1	0	Reset Value
SFR B0 _H	P3.7 RD	P3.6 WR	P3.5 T1	P3.4 T0	P3.3 INT1	P3.2 INT0	P3.1 TXD0	P3.0 RXD0	FF _H
°3.7-0 bits 7-0	an altern	ative function		ow. Each o	f the function	ns is contro	lled by seve	ral other SF	on, all the pins hav Rs. The associate capacity.
RD bit 7	If Port 0	or Port 2 is	•	external me	emory in the	HCR1 regis	ter, this func	tion will be	rnal memory devic enabled even if a ' e ignored.
NR bit 6	device. If	Port 0 or P	ort 2 is selec	ted for exte	ernal memory	in the HCF	R1 register, th	nis function	an external memo will be enabled eve NRRH are ignored.
F1 Dit 5	Timer/Co	ounter 1 E	kternal Inpu	t. A 1 to 0	transition on	this pin wil	l increment	Timer 1.	
ΓΟ Dit 4	Timer/Co	ounter 0 E	kternal Inpu	t. A 1 to 0	transition on	this pin wil	l increment	Timer 0.	
NT1 bit 3	External	Interrupt '	1. A falling e	dge/low lev	el on this pir	n will cause	an external	interrupt 1	if enabled.
NTO bit 2	External	Interrupt (). A falling e	dge/low lev	el on this pir	n will cause	an external	interrupt 0	if enabled.
FXD0 bit 1			smit. This pi in serial port		the serial F	Port 0 data	in serial por	t modes 1,	2, 3, and emits th
RXD0 bit 0			ve. This pin serial port m		e serial Port	0 data in se	rial port moc	les 1, 2, 3, a	and is a bidirection
Port 2 Da	ta Directi	on Low R	egister (P2	2DDRL)	1				
	7	6	5	4	3	2	1	0	Reset Value
SFR B1 _H	P23H	P23L	P22H	P22L	P21H	P21L	P20H	P20L	

P2.3 bits 7-6

Port 2 bit 3 control.

P23H	P23L	
0	0	Standard 8051
0	1	CMOS Output
1	0	Open Drain Output
1	1	Input

P2.2 Port 2 bit 2 control. bits 5-4

P22H	P22L			
0	0	Standard 8051		
0	1	CMOS Output		
1	0	Open Drain Output		
1	1	Input		
Port 2 bit 1 control.				

P2.1

bits 3-2

Port	2	bit	1	со

P21H	P21L	
0	0	Standard 8051
0	1	CMOS Output
1	0	Open Drain Output
1	1	Input

P2.0 Port 2 bit 0 control. bits 1-0

P20H	P20L	
0	0	Standard 8051
0	1	CMOS Output
1	0	Open Drain Output
1	1	Input

NOTE: Port 2 also controlled by $\overline{\mathsf{EA}}$ and Memory Access Control HCR1.1.



	7	6	5	4	
SFR B2 _H	P27H	P27L	P26H	P26L	
P2.7	Port 2 b	it 7 contr	ol.		
bits 7-6	P27H	P27L			
	0	0	Standard 8051		
	0	1	CMOS Output		
	1	0	Open Drain Ou	tput	
	1	1	Input		
P2.6	Port 2 b	it 6 contr	ol.		
bits 5-4	P26H	P26L			
	0	0	Standard 8051		
	0	1	CMOS Output		
	1	0	Open Drain Ou	tput	
	1	1	Input		
P2.5	Port 2 b	it 5 contr	ol.		
bits 3-2	P25H	P25L			
	0	0	Standard 8051		
	0	1	CMOS Output		
	1	0	Open Drain Ou	tput	
	1	1	Input		
P2.4	Port 2 b	it 4 contr	ol.		
bits 1-0	P24H	P24L			
	0	0	Standard 8051		
	0	1	CMOS Output		
	1	0	Open Drain Ou	tput	
	1	1	Input		

Port 2 Data Direction High Register (P2DDRH)

Г

NOTE: Port 2 also controlled by $\overline{\mathsf{EA}}$ and Memory Access Control HCR1.1.

Port 3 Data Direction Low Register (P3DDRL)

	7	6	5	4	3	2	1	0	Reset Value
SFR B3 _H	P33H	P33L	P32H	P32L	P31H	P31L	P30H	P30L	00 _H

3

P25H

2

P25L

1

P24H

0

P24L

P3.3 Port 3 bit 3 control. bits 7-6 P33H P33L 0 0 Standard 8051 0 1 CMOS Output 1 0 Open Drain Output Input 1 1 P3.2 Port 3 bit 2 control. bits 5-4 P32H P32L 0 0 Standard 8051 0 1 CMOS Output Open Drain Output 1 0 Input 1 1 P3.1 Port 3 bit 1 control. bits 3-2 P31H P31L Standard 8051 0 0 CMOS Output 0 1 0 Open Drain Output 1 Input 1 1 P3.0 Port 3 bit 0 control. bits 1-0 P30H P30L Standard 8051 0 0 CMOS Output 0 1 1 0 Open Drain Output 1 1 Input



Reset Value

00_H

Port 3 Data Direction High Register (P3DDRH)

	7	6	5	4	3	2	1	0	Reset Value
SFR B4 _H	P37H	P37L	P36H	P36L	P35H	P35L	P34H	P34L	00 _H
P3.7	Port 3 b	it 7 contr	ol.						
bits 7-6	P37H	P37L							
	0	0	Standard 8051						
	0	1	CMOS Output						
	1	0	Open Drain Out	put					
	1	1	Input						
NOTE: Port 3.	7 also control	led by EA ar	d Memory Acces	s Control HCR	1.1.				
P3.6	Port 3 b	it 6 contr	ol.						
oits 5-4	P36H	P36L							
	0	0	Standard 8051						
	0	1	CMOS Output						
	1	0	Open Drain Out	put					
	1	1	Input						
NOTE: Port 3.	6 also control	led by EA ar	nd Memory Acces	s Control HCR	1.1.				
P3.5	Port 3 b	it 5 contr	ol.						
bits 3-2	P35H	P35L							
	0	0	Standard 8051						
	0	1	CMOS Output						
	1	0	Open Drain Out	put					
	1	, v	opon brain ou						

P3.4

Port 3 bit 4 control.

bits	1-0

		1
P34H	P34L	
0	0	Standard 8051
0	1	CMOS Output
1	0	Open Drain Output
1	1	Input

DAC Low Byte (DACL)

	7	6	5	4	3	2	1	0	Reset Value
SFR B5 _H									00 _H

DACL7-0 Least Significant Bit Register for DAC0-3 and DAC Control (0 and 2). bits 7-0

DAC High Byte (DACH)

	7	6	5	4	3	2	1	0	Reset Value
SFR B6 _H									00 _H

DACH7-0 Most Significant Byte Register for DAC0-3 and DAC Control (1 and 3). bits 7-0

DAC Select Register (DACSEL)

	7	6	5	4	3	2	1	0	Reset Value
SFR B7 _H	DSEL7	DSEL6	DSEL5	DSEL4	DSEL3	DSEL2	DSEL1	DSEL0	00 _H

DSEL7-0 DAC and DAC Control Select. The DACSEL register selects which DAC output register or which DAC control bits 7-0 register is accessed by the DACL and DACH registers.

DACSEL (B7 _H)	DACH (B6H)	DACL (B5H)	RESET VALUE
00 _H	DAC0 (high)	DAC0 (low)	0000 _H
01 _H	DAC1 (high)	DAC1 (low)	0000 _H
02 _H	DAC2 (high)	DAC2 (low)	0000 _H
03 _H	DAC3 (high)	DAC3 (low)	0000 _H
04 _H	DACCON1	DACCON0	6363 _H
05 _H	DACCON3	DACCON2	0303 _H
06 _H	—	LOADCON	00 _H
07 _H	-	—	—



DAC0 Control Register (DACCON0)

DACSEL = 04 _H	7	6	5	4	3	2	1	0	Reset Value				
SFR B5 _H	COR0	EOD0	IDAC0DIS	0	0	SELREF0	DOM0_1	DOM0_0	63 _H				
bit 7 \	Current Over Range on DAC0 Write: 0 = Clear to release from high-impedance state back to normal mode unless an over-range exists. 1 = NOP Read: 0 = No current over range for DAC0. 1 = COR0 signal after 3ms filter (EOD0 = 1) or raw signal (EOD0 = 0).												
bit 6 (Enable Over-Current Detection 0 = Disable over-current detection. 1 = Enable over-current detection (default).												
bit 5 (D = IDAC	on mode for	DOM0 = 00) or DAC0. or DAC0 (de										
Not Used bits 4-3													
bit 2 0	Select the Reference Voltage for DAC0 Voltage Reference. $0 = DAC0 V_{REF} = AV_{DD}$ (default). $1 = DAC0 V_{REF} = internal V_{REF}$.												
DOM0_1-0 I	DAC Output Mode DAC0.												
bits 1-0	DOM0	OUTPUT MC	DDE FOR DAC	D									
r													

DOM0	OUTPUT MODE FOR DAC0
00	Normal VDAC output, IDAC controlled by IDAC0DIS bit.
01	Power-Down mode—VDAC output off $1k\Omega$ to AGND, IDAC off.
10	Power-Down mode—VDAC output off $100k\Omega$ to AGND, IDAC off.
11	Power-Down mode—VDAC output off high impedance, IDAC off (default).

DAC1 Control Register (DACCON1)

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DACSEL = 04 _H	7	6	5	4	3	2	1	0	Reset Value			
SFR B6 _H	COR1	EOD1	IDAC1DIS	0	0	SELREF1	DOM1_1	DOM1_0	63 _H			
	Write: 0 = 1 = Read: 0 =	NOP No current o	on DAC1 ease from high over range fo al after 3ms f	or DAC1.				s an over-ra	inge exists.			
-	Enable Over-Current Detection D = Disable over-current detection. 1 = Enable over-current detection (default).											
	IDAC1 Disable (for DOM1 = 00) 0 = IDAC on mode for DAC1. 1 = IDAC off mode for DAC1 (default).											
Not Used bits 4-3												
	0 = DAC1	Reference V _{REF} = AV _D V _{REF} = inter		DAC1 Vol	tage Refe	rence.						
	DAC Outp	out Mode D	AC0.									
bits 1-0	DOM1	OUTPUT MOD	DE FOR DAC1									
	00 01 10 11	Power-Down n Power-Down n	output, IDAC co node—VDAC our node—VDAC our node—VDAC our	tput off 1kΩ to tput off 100kΩ	o AGND, IDA 2 to AGND, I	DAC off.	t).					

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DAC2 Control Register (DACCON2)

DACSEL = 05 _H	7	6	5	4	3	2	1	0	Reset Value
SFR B5 _H	0	0	0	0	0	SELREF2	DOM2_1	DOM2_0	03 _H

SELREF2 Select the Reference Voltage for DAC2 Voltage Reference.

- $0 = DAC2 V_{REF} = AV_{DD}$ (default).
 - 1 = DAC2 V_{REF} = internal V_{REF} .

DOM2_1-0 DAC Output Mode DAC2.

bits 1-0

bit 2

DOM2	OUTPUT MODE FOR DAC2
00	Normal VDAC output.
01	Power-Down mode—VDAC output off $1k\Omega$ to AGND, IDAC off.
10	Power-Down mode—VDAC output off $100k\Omega$ to AGND, IDAC off.
11	Power-Down mode—VDAC output off high impedance, IDAC off (default).

DAC3 Control Register (DACCON3)

DACSEL = 05 _H	7	6	5	4	3	2	1	0	Reset Value
SFR B6 _H	0	0	0	0	0	SELREF3	DOM3_1	DOM3_0	03 _H

SELREF3 Select the Reference Voltage for DAC3 Voltage Reference.

bit 2 $0 = DAC2 V_{REF} = AV_{DD}$ (default).

1 = DAC2 V_{REF} = internal V_{REF} .

DOM3_1-0 DAC Output Mode DAC3.

bits 1-0

DOM2	OUTPUT MODE FOR DAC2
00	Normal VDAC output.
01	Power-Down mode—VDAC output off $1k\Omega$ to AGND, IDAC off.

10 Power-Down mode—VDAC output off $100k\Omega$ to AGND, IDAC off.

11 Power-Down mode—VDAC output off high impedance, IDAC off (default).

DAC Load Control Register (LOADCON)

DACSEL = 06 _H	7	6	5	4	3	2	1	0	Reset Value
SFR B5 _H	D3LOAD1	D3LOAD0	D2LOAD1	D2LOAD0	D1LOAD1	D1LOAD0	D0LOAD1	D0LOAD0	00 _H

D3LOAD1-0 DAC Load Options.

bit 7-6	DxLOAD	OUTPUT MODE FOR DACx
D2LOAD1-0	00	Direct load: write to DACxL directly loads the DAC buffer and the DAC output (write to DACxH does not load DAC output).
bit 5-4	01	Delay load: the values last written to DACxL/DACxH will be transferred to the DAC output on the next MSEC timer tick.
D1LOAD1-0	10	Delay load: the values last written to DACxL/DACxH will be transferred to the DAC output on the next HMSEC timer tick.
	11	Sync load: the values contained in the DACxL/DACxH registers will be transferred to the DAC output immediately after
bit 3-2		11 _B is written to this register.
D0LOAD1-0		

bit 1-0



Interrupt Priority (IP)

	7	6	5	4	3	2	1	0	Reset Value
SFR B8 _H	1	PS1	PT2	PS0	PT1	PX1	PT0	PX0	80 _H
PS1 bit 6	0 = Seria	al Port 1 pri	-	rmined by tl	he natural p	the serial P priority order	ort 1 interrup	ot.	
PT2 bit 5	0 = Time	er 2 priority	This bit cont is determine is a high pri	ed by the na	atural priorit	Timer 2 inter y order.	rupt.		
PS0 bit 4	0 = Seria	al Port 0 pri	-	rmined by t	he natural p	the serial P priority order	Port 0 interrup	ot.	
PT1 bit 3	0 = Time	er 1 priority	This bit cont is determine is a high pri	ed by the na	atural priorit	Timer 1 inter y order.	rupt.		
PX1 bit 2	0 = External	rnal interrup		s determine	ed by the na	tternal interr atural priority	-		
PT0 bit 1	0 = Time	er 0 priority	This bit cont is determine is a high pri	ed by the na	atural priorit	Timer 0 inter y order.	rupt.		
PX0 bit 0	0 = Exte	rnal interrup		s determine	ed by the na	tternal interr atural priority	•		

Serial Port 1 Control (SCON1)

	7	6	5	4	3	2	1	0	Reset Value
SFR C0 _H	SM0_1	SM1_1	SM2_1	REN_1	TB8_1	RB8_1	TI_1	RI_1	00 _H

SM0-2 Serial Port 1 Mode. These bits control the mode of serial Port 1. Modes 1, 2, and 3 have 1 start and 1 stop bit in addition to the 8 or 9 data bits.

MODE	SM0	SM1	SM2	FUNCTION	LENGTH	PERIOD
0	0	0	0	Synchronous	8 bits	12 p _{CLK} ⁽¹⁾
0	0	0	1	Synchronous	8 bits	4 p _{CLK} ⁽¹⁾
1 ⁽²⁾	0	1	х	Asynchronous	10 bits	Timer 1 or 2 Baud Rate Equation
2	1	0	0	Asynchronous	11 bits	$64 p_{CLK}^{(1)} (SMOD = 0)$
						$32 p_{CLK}^{(1)} (SMOD = 1)$
2	1	0	1	Asynchronous with	11 bits	64 $p_{CLK}^{(1)}$ (SMOD = 0)
				Multiprocessor Communication		$32 p_{CLK}^{(1)} (SMOD = 1)$
3(2)	1	1	0	Asynchronous	11 bits	Timer 1 or 2 Baud Rate Equation
3(2)	1	1	1	Asynchronous with	11 bits	Timer 1 or 2 Baud Rate Equation
				Multiprocessor Communication		
				b t _{CLK} , except that p _{CLK} will stop for pecified via the SCON register.	IDLE. (2) For	modes 1 and 3, the selection of

REN_1 Receive Enable. This bit enables/disables the serial Port 1 received shift register.

- bit 4 0 = Serial Port 1 reception disabled.
 - 1 = Serial Port 1 received enabled (modes 1, 2, and 3). Initiate synchronous reception (mode 0).

TB8_1 9th Transmission Bit State. This bit defines the state of the 9th transmission bit in serial Port 1 modes 2 and 3. bit 3

- **RB8_1 9th Received Bit State.** This bit identifies the state of the 9th reception bit of received data in serial Port 1 modes 2 and 3. In serial port mode 1, when SM2_1 = 0, RB8_1 is the state of the stop bit. RB8_1 is not used in mode 0.
- TI_1
 Transmitter Interrupt Flag. This bit indicates that data in the serial Port 1 buffer has been completely shifted

 bit 1
 out. In serial port mode 0, TI_1 is set at the end of the 8th data bit. In all other modes, this bit is set at the end of the last data bit. This bit must be cleared by software to transmit the next byte.



RI_1 Receiver Interrupt Flag. This bit indicates that a byte of data has been received in the serial Port 1 buffer. In serial port mode 0, RI_1 is set at the end of the 8th bit. In serial port mode 1, RI_1 is set after the last sample of the incoming stop bit subject to the state of SM2_1. In modes 2 and 3, RI_1 is set after the last sample of RB8_1. This bit must be cleared by software to receive the next byte.

Serial Data Buffer 1 (SBUF1)

	7	6	5	4	3	2	1	0	Reset Value
SFR C1 _H									00 _H

SBUF1.7-0 Serial Data Buffer 1. Data for serial Port 1 is read from or written to this location. The serial transmit and receive buffers are separate registers, but both are addressed at this location.

Enable Wake Up (EWU) Waking Up from IDLE Mode

	7	6	5	4	3	2	1	0	Reset Value
SFR C6 _H	—	_	—	_	—	EWUWDT	EWUEX1	EWUEX0	00 _H

Auxialiary interrupts will wake up from IDLE. They are enabled with EAI (EICON.5).

EWUWDT Enable Wake Up Watchdog Timer. Wake using watchdog timer interrupt.

- bit 2 0 = Don't wake up on watchdog timer interrupt.
 - 1 = Wake up on watchdog timer interrupt.
- **EWUEX1** Enable Wake Up External 1. Wake using external interrupt source 1.
- bit 1 0 = Don't wake up on external interrupt source 1.
 - 1 = Wake up on external interrupt source 1.
- EWUEX0 Enable Wake Up External 0. Wake using external interrupt source 0.
- bit 0 0 = Don't wake up on external interrupt source 0.
 - 1 = Wake up on external interrupt source 0.

System Clock Divider Register (SYSCLK)

	7	6	5	40	3	2	1	0	Reset Value
SFR C7 _H	0	0	DIVMOD1	DIVMOD0	0	DIV2	DIV1	DIV0	00 _H

DIVMOD1-0 Clock Divide Mode

bits 5-4 W	rite:
------------	-------

DIVMOD	DIVIDE MODE
00	Normal mode (default, no divide)
01	Immediate mode: start divide immediately, return to Normal mode on IDLE wakeup condition
10	Delay mode: same as Immediate mode, except that the mode changes with the millisecond interrupt (MSINT). If MSINT is enabled, the divide will start on the next MSINT and return to normal mode on the following MSINT. If MSINT is not enabled, the divide will start on the next MSINT condition (even if masked) but will not leave the divide mode until the MSINT counter overflows, which follows a wakeup condition.
11	Reserved

Read:

DIVMOD	DIVISION MODE STATUS
00	No divide
01	Divider is in Immediate mode
10	Divider is in Delay mode
11	Reserved

DIV2-0 Divide Mode

DIV DIVISOR 000 Divide by 2 (default) Divide by 4 001 010 Divide by 8 Divide by 16 011 100 Divide by 32 101 Divide by 1024 110 Divide by 2048 Divide by 4096 111

NOTE:

Do not clear the DIVMOD register to exit Immediate or Delay modes. Exit these modes only through the appropriate interrupt (the interrupt can be either normally generated or software generated).



bit 2-0

Timer 2 Control (T2CON)

	7	6	5	4	3	2	1	0	Reset Value	
SFR C8 _H	TF2	EXF2	RCLK	TCLK	EXEN2	TR2	C/T2	CP/RL2	00 _H	
TF2 bit 7 EXF2 bit 6	TF2 will of Timer 2 the EXE	only be set if External F EN2 (T2CO	RCLK and T	CLK are bo tive transiti set by a i	th cleared to on on the Tan negative trai	0. Writing a 2EX pin (P [.] nsition, this	1 to TF2 forc	es a Timer se this flag	cleared by software. 2 interrupt if enabled. to be set based on to 0 by software.	
RCLK bit 5	0 = Time 1 = Time Setting t	er 1 overflov er 2 overflov	w is used to w is used to	determine i determine i	receiver bau	d rate for U d rate for U	ART0. ART0.	-	serial modes 1 or 3. rom a divide by 2 of	
TCLK bit 4	0 = Time 1 = Time Setting t	er 1 overflov er 2 overflov	w is used to w is used to	determine f determine f	transmitter b transmitter b	aud rate for aud rate for	UART0. UART0.	·	n serial modes 1 or 3. rom a divide by 2 of	
EXEN2 bit 3	generatir 0 = Time	 Timer 2 External Enable. This bit enables the capture/reload function on the T2EX pin if Timer 2 is not generating baud rates for the serial port. 0 = Timer 2 will ignore all external events at T2EX. 1 = Timer 2 will capture or reload a value if a negative transition is detected on the T2EX pin. 								
TR2 bit 2	current c 0 = Time	Run Contr count in TH2 er 2 is halte er 2 is enab	2, TL2. d.	enables/dis	ables the op	peration of -	Fimer 2. Hal	ting this tin	ner will preserve the	
C/T2 bit 1	this bit, ⁻ 0 = Time	Timer 2 run er 2 functior	ect. This bit s at 2 clocks ns as a timer int negative t	per tick wl . The spee	hen used in d of Timer 2	baud rate g is determir	enerator mo	de.	nter. Independent of CON.5).	
CP/RL2 bit 0	either R following 0 = Auto	CLK or TC each overf -reloads wi	LK is set, t low.	his bit will n Timer 2 o	not functior verflows or a	n and the t	imer will fui le is detecte	nction in a d on T2EX	used for Timer 2. If n auto-reload mode if EXEN2 = 1.	

Timer 2 Capture LSB (RCAP2L)

	7	6	5	4	3	2	1	0	Reset Value
SFR CA _H									00 _H

RCAP2L Timer 2 Capture LSB. This register is used to capture the TL2 value when Timer 2 is configured in capture bits 7-0 mode. RCAP2L is also used as the LSB of a 16-bit reload value when Timer 2 is configured in auto-reload mode.



Timer 2 Capture MSB (RCAP2H)

	7	6	5	4	3	2	1	0	Reset Value
SFR CB _H									00 _H

Timer 2 LSB (TL2)

	. ,								
	7	6	5	4	3	2	1	0	Reset Value
$SFR\;CC_H$									00 _H

TL2 Timer 2 LSB. This register contains the least significant byte of Timer 2.

bits 7-0

Timer 2 MSB (TH2)

	7	6	5	4	3	2	1	0	Reset Value
SFR CD _H									00 _H

TH2 Timer 2 MSB. This register contains the most significant byte of Timer 2.

bits 7-0

Program Status Word (PSW)

	7	6	5	4	3	2	1	0	Reset Value
SFR D0 _H	CY	AC	F0	RS1	RS0	OV	F1	Р	00 _H

CY Carry Flag. This bit is set when the last arithmetic operation resulted in a carry (during addition) or a borrow (during subtraction). Otherwise it is cleared to 0 by all arithmetic operations.

AC Auxiliary Carry Flag. This bit is set to 1 if the last arithmetic operation resulted in a carry into (during addition), bit 6 or a borrow (during substraction) from the high order nibble. Otherwise it is cleared to 0 by all arithmetic operations.

F0 User Flag 0. This is a bit-adressable, general-purpose flag for software control.

bit 5

RS1, RS0 Register Bank Select 1-0. These bits select which register bank is addressed during register accesses.

bits 4-3

RS1	RS0	REGISTER BANK	ADDRESS
0	0	0	00 _H -07 _H
0	1	1	08 _H -0F _H
1	0	2	10 _H -17 _H
1	1	3	18 _H -1F _H
			1

OV Overflow Flag. This bit is set to 1 if the last arithmetic operation resulted in a carry (addition), borrow bit 2 (subtraction), or overflow (multiply or divide). Otherwise it is cleared to 0 by all arithmetic operations.

F1 User Flag 1. This is a bit-addressable, general-purpose flag for software control.

bit 1

t1

P Parity Flag. This bit is set to 1 if the modulo-2 sum of the 8 bits of the accumulator is 1 (odd parity); and bit 0 cleared to 0 on even parity.

ADC Offset Calibration Register Low Byte (OCL)

	7	6	5	4	3	2	1	0	Reset Value
SFR D1 _H									00 _H

OCLADC Offset Calibration Register Low Byte. This is the low byte of the 24-bit word that contains thebits 7-0ADC offset calibration. A value which is written to this location will set the ADC offset calibration value.



RCAP2H Timer 2 Capture MSB. This register is used to capture the TH2 value when Timer 2 is configured in capture mode. RCAP2H is also used as the MSB of a 16-bit reload value when Timer 2 is configured in auto-reload mode.

ADC Offset Calibration Register Middle Byte (OCM)

	7	6	5	4	3	2	1	0	Reset Value
SFR D2 _H									00 _H

OCM ADC Offset Calibration Register Middle Byte. This is the middle byte of the 24-bit word that contains the ADC offset calibration. A value which is written to this location will set the ADC offset calibration value.

ADC Offset Calibration Register High Byte (OCH)

	7	6	5	4	3	2	1	0	Reset Value
SFR D3 _H									00 _H

OCHADC Offset Calibration Register High Byte. This is the high byte of the 24-bit word that contains the
bits 7-0bits 7-0ADC offset calibration. A value which is written to this location will set the ADC offset calibration value.

ADC Gain Calibration Register Low Byte (GCL)

	7	6	5	4	3	2	1	0	Reset Value
SFR D4 _H									5A _H

GCL ADC Gain Calibration Register Low Byte. This is the low byte of the 24-bit word that contains the ADC gain calibration. A value which is written to this location will set the ADC gain calibration value.

ADC Gain Calibration Register Middle Byte (GCM)

	7	6	5	4	3	2	1	0	Reset Value
SFR D5 _H									EC _H

GCM ADC Gain Calibration Register Middle Byte. This is the middle byte of the 24-bit word that contains the ADC gain calibration. A value which is written to this location will set the ADC gain calibration value.

ADC Gain Calibration Register High Byte (GCH)

	7	6	5	4	3	2	1	0	Reset Value
SFR D6 _H									5F _H

GCH ADC Gain Calibration Register High Byte. This is the high byte of the 24-bit word that contains the bits 7-0 ADC gain calibration. A value which is written to this location will set the ADC gain calibration value.

ADC Multiplexer Register (ADMUX)

	7	6	5	4	3	2	1	0	Reset Value
SFR D7 _H	INP3	INP2	INP1	INP0	INN3	INN2	INN1	INN0	01 _H

INP3-0 Input Multiplexer Positive Channel. This selects the positive signal input.

bits 7-4

INP3	INP2	INP1	INP0	POSITIVE INPUT
0	0	0	0	AIN0 (default)
0	0	0	1	AIN1
0	0	1	0	AIN2
0	0	1	1	AIN3
0	1	0	0	AIN4
0	1	0	1	AIN5
0	1	1	0	AIN6
0	1	1	1	AIN7
1	0	0	0	AINCOM
1	1	1	1	Temperature Sensor (Requires ADMUX = FF _H)



INN3-0 Input Multiplexer Negative Channel. This selects the negative signal input.

bits 3-0

INN3	INN2	INN1	INN0	NEGATIVE INPUT
0	0	0	0	AINO
0	0	0	1	AIN1 (default)
0	0	1	0	AIN2
0	0	1	1	AIN3
0	1	0	0	AIN4
0	1	0	1	AIN5
0	1	1	0	AIN6
0	1	1	1	AIN7
1	0	0	0	AINCOM
1	1	1	1	Temperature Sensor (Requires ADMUX = FF_H)

Enable Interrupt Control (EICON)

	7	6	5	4	3	2	1	0	Reset Value
SFR D8 _H	SMOD1	1	EAI	AI	WDTI	0	0	0	40 _H

SMOD1 Serial Port 1 Mode. When this bit is set the serial baud rate for Port 1 will be doubled.

bit 7 0 = Standard baud rate for Port 1 (default).

1 = Double baud rate for Port 1.

EAI Enable Auxiliary Interrupt. The Auxiliary Interrupt accesses nine different interrupts which are masked and bit 5 identified by SFR registers PAI (SFR A5_H), AIE (SFR A6_H), and AISTAT (SFR A7_H).

0 = Auxiliary Interrupt disabled (default).

1 = Auxiliary Interrupt enabled.

Al Auxiliary Interrupt Flag. Al must be cleared by software before exiting the interrupt service routine, bit 4 after the source of the interrupt is cleared. Otherwise, the interrupt occurs again. Setting Al in software generates an Auxiliary Interrupt, if enabled.

0 = No Auxiliary Interrupt detected (default).

1 = Auxiliary Interrupt detected.

WDTIWatchdog Timer Interrupt Flag. WDTI must be cleared by software before exiting the interrupt service routine.bit 3Otherwise, the interrupt occurs again. Setting WDTI in software generates a watchdog time interrupt, if enabled.
The Watchdog timer can generate an interrupt or reset. The interrupt is available only if the reset action is disabled
in HCR0.

0 = No Watchdog Timer Interrupt Detected (default).

1 = Watchdog Timer Interrupt Detected.

ADC Results Register Low Byte (ADRESL)

	7	6	5	4	3	2	1	0	Reset Value
SFR D9 _H									00 _H

ADRESLThe ADC Results Low Byte. This is the low byte of the 24-bit word that contains the ADCbits 7-0Converter Results. Reading from this register clears the ADC interrupt.

ADC Results Register Middle Byte (ADRESM)

	7	6	5	4	3	2	1	0	Reset Value
SFR DA _H									00 _H

ADRESM The ADC Results Middle Byte. This is the middle byte of the 24-bit word that contains the ADC bits 7-0 Converter Results.

ADC Results Register High Byte (ADRESH)

	7	6	5	4	3	2	1	0	Reset Value
$SFR\;DB_H$									00 _H

ADRESH The ADC Results High Byte. This is the high byte of the 24-bit word that contains the ADC bits 7-0 Converter Results.



ADC Control Register 0 (ADCON0)

	7	6	5	4	3	2	1	0	Reset Value			
SFR DC _H	_	BOD	EVREF	VREFH	EBUF	PGA2	PGA1	PGA0	30 _H			
BOD bit 6	Burnout Detect. When enabled this connects a positive current source to the positive channel and a negative current source to the negative channel. If the channel is open circuit then the ADC results will be full-scale. 0 = Burnout Current Sources Off (default). 1 = Burnout Current Sources On.											
EVREF bit 5	 Enable Internal Voltage Reference. If the internal voltage reference is not used, it should be turned off to save power and reduce noise. 0 = Internal Voltage Reference Off. 1 = Internal Voltage Reference On (default). 											
VREFH bit 4	Voltage Reference High Select. The internal voltage reference can be selected to be 2.5V or 1.25V. 0 = REFOUT/REF IN+ is 1.25V. 1 = REFOUT/REF IN+ is 2.5V (default).											
EBUF bit 3	dissipate 0 = Buffe	Buffer. Ena es more pov er disabled	ver.	buffer to p	rovide highe	r input impe	dance but lir	mits the inpu	ut voltage range and			

1 = Buffer enabled.

PGA2-0 Programmable Gain Amplifier. Sets the gain for the PGA from 1 to 128.

PGA2	PGA1	PGA0	GAIN
0	0	0	1 (default)
0	0	1	2
0	1	0	4
0	1	1	8
1	0	0	16
1	0	1	32
1	1	0	64
1	1	1	128

ADC Control Register 1 (ADCON1)

	7	6	5	4	3	2	1	0	Reset Value
$SFR\;DD_H$	—	POL	SM1	SM0	—	CAL2	CAL1	CAL0	x000 0000 _B

POL Polarity. Polarity of the ADC result and Summation register.

0 = Bipolar.

1 = Unipolar.

POL	ANALOG INPUT	DIGITAL OUTPUT		
	+FSR	0x7FFFFF		
0	ZERO	0x000000		
	–FSR	0x800000		
	+FSR	0xFFFFFF		
1	ZERO	0x000000		
	–FSR	0x000000		

SM1-0 Settling Mode. Selects the type of filter or auto select which defines the digital filter settling characteristics.

bits	5_1
DILO	J-4

bit 6

bits 2-0

SM1	SM0	SETTLING MODE
0	0	Auto
0	1	Fast Settling Filter
1	0	Sinc ² Filter
1	1	Sinc ³ Filter



CAL2-0 Calibration Mode Control Bits.

bits 2-0

CAL2	CAL1	CAL0	CALIBRATION MODE
0	0	0	No Calibration (default)
0	0	1	Self Calibration, Offset and Gain
0	1	0	Self Calibration, Offset Only
0	1	1	Self Calibration, Gain Only
1	0	0	System Calibration, Offset Only
1	0	1	System Calibration, Gain Only
1	1	0	Reserved
1	1	1	Reserved

Read Value-000_B.

ADC Control Register 2 (ADCON2)

	7	6	5	4	3	2	1	0	Reset Value
SFR DE _H	DR7	DR6	DR5	DR4	DR3	DR2	DR1	DR0	1B _H

DR7-0 Decimation Ratio LSB.

bits 7-0

bits 7-6

ADC Control Register 3 (ADCON3)

	7	6	5	4	3	2	1	0	Reset Value
SFR DF _H	_	-	_		—	DR10	DR9	DR8	06 _H

DR10-8 Decimation Ratio Most Significant 3 Bits. The output data rate = (ACLK + 1)/64/Decimation Ratio. bits 2-0

Accumulator (A or ACC)

	7	6	5	4	3	2	1	0	Reset Value
SFR E0 _H	ACC.7	ACC.6	ACC.5	ACC.4	ACC.3	ACC.2	ACC.1	ACC.0	00 _H

ACC.7-0 Accumulator. This register serves as the accumulator for arithmetic and logic operations. bits 7-0

Summation/Shifter Control (SSCON)

	7	6	5	4	3	2	1	0	Reset Value
SFR E1 _H	SSCON1	SSCON0	SCNT2	SCNT1	SCNT0	SHF2	SHF1	SHF0	00 _H

The Summation register is powered down when the ADC is powered down. If all zeroes are written to this register the 32-bit SUMR3-0 registers will be cleared. The Summation registers will do sign extend if Bipolar is selected in ADCON1.

SSCON1-0 Summation/Shift Control.

SSCON1	SSCON0	SCNT2	SCNT1	SCNT0	SHF2	SHF1	SHF0	DESCRIPTION
0	0	0	0	0	0	0	0	Clear Summation Register
0	0	0	1	0	0	0	0	CPU Summation on Write to SUMR0
0	0	1	0	0	0	0	0	CPU Subtraction on Write to SUMR0
1	0	х	x	х	Note (1)	Note (1)	Note (1)	CPU Shift Only
0	1	Note (1)	Note (1)	Note (1)	х	x	х	ADC Summation Only
1	1	Note (1)	ADC Summation Completes then Shift Completes					

NOTES: (1) Refer to register bit definition.

SCNT2-0 Summation Count. When the summation is complete an interrupt will be generated unless masked. Reading the bits 5-3 SUMR0 register clears the interrupt.

SCNT2	SCNT1	SCNT0	SUMMATION COUNT
0	0	0	2
0	0	1	4
0	1	0	8
0	1	1	16
1	0	0	32
1	0	1	64
1	1	0	128
1	1	1	256





Shift Count SHF2-0

bits 2-0

π	CC	DUI	π.	

SHF2	SHF1	SHF0	SHIFT	DIVIDE
0	0	0	1	2
0	0	1	2	4
0	1	0	3	8
0	1	1	4	16
1	0	0	5	32
1	0	1	6	64
1	1	0	7	128
1	1	1	8	256

Summation Register 0 (SUMR0)

	7	6	5	4	3	2	1	0	Reset Value
SFR E2 _H									00 _H

SUMR0 Summation Register 0. This is the least significant byte of the 32-bit summation register or bits 0 to 7. bits 7-0 Write: will cause values in SUMR3-0 to be added to the summation register. Read: will clear the Summation Count Interrupt.

Summation Register 1 (SUMR1)

	7	6	5	4	3	2	1	0	Reset Value
SFR E3 _H									00 _H

SUMR1 Summation Register 1. This is the most significant byte of the lowest 16 bits of the summation register or bits 8-15. bits 7-0

Summation Register 2 (SUMR2)

	7	6	5	4	3	2	1	0	Reset Value
SFR E4 _H									00 _H

SUMR2 Summation Register 2. This is the most significant byte of the lowest 24 bits of the summation register or bits 16-23. bits 7-0

Summation Register 3 (SUMR3)

	7	6	5	4	3	2	1	0	Reset Value
SFR E5 _H									00 _H

SUMR3 Summation Register 3. This is the most significant byte of the 32-bit summation register or bits 24-31. bits 7-0

Offset DAC Register (ODAC)

	7	6	5	4	3	2	1	0	Reset Value
SFR E6 _H									00 _H

ODAC Offset DAC Register. This register will shift the input by up to half of the ADC input range. The least bits 7-0 significant bit is equal to the input voltage range divided by 256. The input range will depend on the setting of the PGA. The ODAC is a signed magnitude register with bit 7 providing the sign of the offset and bits 6-0 providing the magnitude.

bit 7 Offset DAC Sign bit. 0 = Positive

1 = Negative

bit 6-0

Offset =
$$\frac{V_{REF}}{2 \bullet PGA} \bullet \left(\frac{ODAC[6:0]}{127}\right) \bullet (-1)^{bit 7}$$

NOTE: The offset must be used after calibration or the calibration will nullify the effects.





Low Voltage Detect Control (LVDCON)

	7	6	5	4	3	2	1	0	Reset Value
SFR E7 _H	ALVDIS	ALVD2	ALVD1	ALVD0	DLVDIS	DLVD2	DLVD1	DLVD0	00 _H

ALVDIS Analog Low Voltage Detect Disable.

- 0 = Enable Detection of Low Analog Supply Voltage.
- 1 = Disable Detection of Low Analog Supply Voltage.

ALVD2-0 Analog Voltage Detection Level.

ALVD2	ALVD1	ALVD0	VOLTAGE LEVEL
0	0	0	AV _{DD} 2.7V (default)
0	0	1	AV _{DD} 3.0V
0	1	0	AV _{DD} 3.3V
0	1	1	AV _{DD} 4.0V
1	0	0	AV _{DD} 4.2V
1	0	1	AV _{DD} 4.5V
1	1	0	AV _{DD} 4.7V
1	1	1	External Voltage AIN7 Compared to 1.2V

DLVDIS Digital Low Voltage Detect Disable.

bit 3 0 = Enable Detection of Low Digital Supply Voltage. 1 = Disable Detection of Low Digital Supply Voltage.

1

DLVD2-0 Digital Voltage Detection Level.

bits	2-0
DILO	20

bit 7

bits 6-4

Jightai	Tonage						
DLVD2	DLVD1	VD1 DLVD0 VOLTAGE LEVEL					
0	0	0	DV _{DD} 2.7V (default)				
0	0	1	DV _{DD} 3.0V				
0	1	0	DV _{DD} 3.3V				
0	1	1	DV _{DD} 4.0V				
1	0	0	DV _{DD} 4.2V				
1	0	1	DV _{DD} 4.5V				
1	1	0	DV _{DD} 4.7V				

Extended Interrupt Enable (EIE)

1

	7	6	5	4	3	2	1	0	Reset Value
SFR E8 _H	1	1	1	EWDI	EX5	EX4	EX3	EX2	E0 _H
EWDI pit 4	the WDT 0 = Disat	CON (SFR	FF _H) and F chdog Inter	DCON (SFF	R F1 _H) regis	sters.	g interrupt. TI	he Watchdog	timer is enabled
EX5 bit 3	0 = Disab	Interrupt 5 ble External le External	Interrupt 5	his bit enabl	es/disables	external int	errupt 5.		
EX4 bit 2	0 = Disab	Interrupt 4 ble External le External	Interrupt 4	his bit enabl	es/disables	external int	errupt 4.		

External Voltage AIN6 Compared to 1.2V

- EX3 External Interrupt 3 Enable. This bit enables/disables external interrupt 3.
- bit 1 0 = Disable External Interrupt 3
- 1 = Enable External Interrupt 3
- EX2 External Interrupt 2 Enable. This bit enables/disables external interrupt 2.
- bit 0 0 = Disable External Interrupt 2
 - 1 = Enable External Interrupt 2



Hardware Product Code Register 0 (HWPC0)

	7	6	5	4	3	2	1	0	Reset Value
SFR E9 _H	HWPC0.7	HWPC0.6	HWPC0.5	HWPC0.4	HWPC0.3	1	MEMORY SIZE		0000_001xx _B

HWPC0.7-0 Hardware Product Code LSB. Read only.

bits 7-0

MEMOR	Y SIZE	MODEL	FLASH MEMORY
0	0	MSC1211Y2	4kB
0	1	MSC1211Y3	8kB
1	0	MSC1211Y4	16kB
1	1	MSC1211Y5	32kB

Hardware Product Code Register 1 (HWPC1)

	7	6	5	4	3	2	1	0	Reset Value
SFR EA _H					1				08 _H

HWPC1.7-0 Hardware Product Code MSB. Read only.

bits 7-0

Hardware Version Register (HDWVER)

	7	6	5	4	3	2	1	0	Reset Value
$SFR\;EB_H$									

Flash Memory Control (FMCON)

	7	6	5	4	3	2	1	0	Reset Value
$SFR\;EE_H$	0	PGERA	0	FRCM	0	BUSY	1	0	02 _H

PGERA	Page Erase.	Available in	both user	and program modes.
-------	-------------	--------------	-----------	--------------------

bit 6 0 = Disable Page Erase Mode

1 = Enable Page Erase Mode

FRCM Frequency Control Mode. The bypass is only used for slow clocks to save power.

bit 4 0 = Bypass (default)

1 = Use Delay Line. Saves power (Recommended).

BUSY Write/Erase BUSY Signal.

- bit 2 0 = Idle or Available
 - 1 = Busy

Flash Memory Timing Control Register (FTCON)

	7	6	5	4	3	2	1	0	Reset Value
$SFR\;EF_H$	FER3	FER2	FER1	FER0	FWR3	FWR2	FWR1	FWR0	A5 _H

Refer to Flash Timing Characteristics

FER3-0	Set Erase. Flash Erase Time = (1 + FER) • (MSEC + 1) • t _{CLK} .
bits 7-4	11ms industrial temperature range.
	5ms commercial temperature range.
FWR3-0	Set Write. Flash Write Time = $(1 + FWR) \cdot (USEC + 1) \cdot 5 \cdot t_{CLK}$.

bits 3-0 30µs to 40µs.



B Register (B)

	7	6	5	4	3	2	1	0	Reset Value
SFR F0 _H	B.7	B.6	B.5	B.4	B.3	B.2	B.1	B.0	00 _H

B.7-0 B Register. This register serves as a second accumulator for certain arithmetic operations. bits 7-0

Power-Down Control Register (PDCON)

	7	6	5	4	3	2	1	0	Reset Value
SFR F1 _H	0	PDDAC	PDI2C	PDPWM	PDAD	PDWDT	PDST	PDSPI	7F _H

Turning peripheral modules off puts the MSC1211 in the lowest power mode.

PDDAC bit 6	Pulse Width Module Control. 0 = DACs On 1 = DACs Power Down
PDI2C bit 5	I2C Control.0 = I2C On (the state is undefined if PDSPI is also = 0)1 = I2C Power Down
PDPWM bit 4	Pulse Width Module Control. 0 = PWM On 1 = PWM Power Down
PDAD bit 3	ADC Control. 0 = ADC On 1 = ADC, V _{REF} , Summation registers, and Analog Brownout are powered down. Analog current = 0.
PDWDT bit 2	Watchdog Timer Control. 0 = Watchdog Timer On 1 = Watchdog Timer Power Down
PDST bit 1	System Timer Control. 0 = System Timer On 1 = System Timer Power Down
PDSPI bit 0	 SPI System Control. 0 = SPI System On (the state is undefined if PDI2C is also = 0) 1 = SPI System Power Down

PSEN/ALE Select (PASEL)

	7	6	5	4	3	2	1	0	Reset Value
SFR F2 _H	0	0	PSEN2	PSEN1	PSEN0	0	ALE1	ALE0	00 _H

PSEN2-0	PSEN Mo	de Select.	
bits 5-3	DEENO	DOENIA	-

PSEN2	PSEN1	PSEN0	
0	0	Х	PSEN
0	1	х	CLK
1	0	Х	ADC MODCLK
1	1	0	LOW
1	1	1	HIGH

ALE1-0

F Mode Select

bits	1	-0
------	---	----

 ALE	woue	Select	

ALE1	ALE0	
0	Х	ALE
1	0	LOW
1	1	HIGH

Analog Clock (ACLK)

	7	6	5	4	3	2	1	0	Reset Value
SFR F6 _H	0	FREQ6	FREQ5	FREQ4	FREQ3	FREQ2	FREQ1	FREQ0	03 _H

FREQ6-0 Clock Frequency – 1. This value + 1 divides the system clock to create the ADC clock.

bits 6-0 ACLK frequency = $f_{CLK}/(FREQ + 1)$ $f_{MOD} = f_{CLK}/(FREQ + 1)/64$ Data Rate = $f_{MOD}/Decimation$

System Reset Register (SRST)

	7	6	5	4	3	2	1	0	Reset Value
SFR F7 _H	0	0	0	0	0	0	0	RSTREQ	00 _H

RSTREQ Reset Request. Setting this bit to 1 and then clearing to 0 will generate a system reset. bit 0

Extended Interrupt Priority (EIP)

	7	6	5	4	3	2	1	0	Reset Value
SFR F8 _H	1	1	1	PWDI	PX5	PX4	PX3	PX2	E0 _H

PWDI bit 4	 Watchdog Interrupt Priority. This bit controls the priority of the watchdog interrupt. 0 = The watchdog interrupt is low priority. 1 = The watchdog interrupt is high priority.
PX5 bit 3	 External Interrupt 5 Priority. This bit controls the priority of external interrupt 5. 0 = External interrupt 5 is low priority. 1 = External interrupt 5 is high priority.
PX4 bit 2	 External Interrupt 4 Priority. This bit controls the priority of external interrupt 4. 0 = External interrupt 4 is low priority. 1 = External interrupt 4 is high priority.
PX3 bit 1	 External Interrupt 3 Priority. This bit controls the priority of external interrupt 3. 0 = External interrupt 3 is low priority. 1 = External interrupt 3 is high priority.
PX2 bit 0	 External Interrupt 2 Priority. This bit controls the priority of external interrupt 2. 0 = External interrupt 2 is low priority. 1 = External interrupt 2 is high priority.

Seconds Timer Interrupt (SECINT)

	7	6	5	4	3	2	1	0	Reset Value
SFR F9 _H	WRT	SECINT6	SECINT5	SECINT4	SECINT3	SECINT2	SECINT1	SECINT0	7F _H

This system clock is divided by the value of the 16-bit register MSECH:MSECL. Then that 1ms timer tick is divided by the register HMSEC which provides the 100ms signal used by this seconds timer. Therefore, this seconds timer can generate an interrupt which occurs from 100ms to 12.8 seconds. Reading this register will clear the Seconds Interrupt. This Interrupt can be monitored in the AIE register.

WRT Write Control. Determines whether to write the value immediately or wait until the current count is finished.bit 7 Read = 0.

- 0 = Delay Write Operation. The SEC value is loaded when the current count expires.
- 1 = Write Immediately. The counter is loaded once the CPU completes the write operation.

SECINT6-0 Seconds Count. Normal operation would use 100ms as the clock interval.

bits 6-0 Seconds Interrupt = $(1 + SEC) \cdot (HMSEC + 1) \cdot (MSEC + 1) \cdot t_{CLK}$.



Milliseconds Interrupt (MSINT)

	7	6	5	4	3	2	1	0	Reset Value
SFR FA _H	WRT	MSINT6	MSINT5	MSINT4	MSINT3	MSINT2	MSINT1	MSINT0	7F _H

The clock used for this timer is the 1ms clock which results from dividing the system clock by the values in registers MSECH:MSECL. Reading this register will clear the interrupt.

 WRT
 Write Control. Determines whether to write the value immediately or wait until the current count is finished. Read = 0.

 bit 7
 0 = Delay Write Operation. The MSINT value is loaded when the current count expires.

 1
 Write Uperation. The MSINT value is loaded when the current count expires.

1 = Write Immediately. The MSINT counter is loaded once the CPU completes the write operation.

MSINT6-0 Seconds Count. Normal operation would use 1ms as the clock interval.

bits 6-0 MS Interrupt Interval = $(1 + MSINT) \cdot (MSEC + 1) \cdot t_{CLK}$

One Microsecond Register (USEC)

	7	6	5	4	3	2	1	0	Reset Value
SFR FB _H	0	0	0	FREQ4	FREQ3	FREQ2	FREQ1	FREQ0	03 _H

FREQ4-0 Clock Frequency – 1. This value + 1 divides the system clock to create a 1µs Clock.

bits 4-0 USEC = CLK/(FREQ + 1). This clock is used to set Flash write time. See FTCON (SFR EF_H).

One Millisecond Low Register (MSECL)

	7	6	5	4	3	2	1	0	Reset Value
SFR FC _H	MSECL7	MSECL6	MSECL5	MSECL4	MSECL3	MSECL2	MSECL1	MSECL0	9F _H

MSECL7-0 One Millisecond Low. This value in combination with the next register is used to create a 1ms Clock. bits 7-0 $1ms Clock = (MSECH \cdot 256 + MSECL + 1) \cdot t_{CLK}$. This clock is used to set Flash erase time. See FTCON (SFR EF_H).

One Millisecond High Register (MSECH)

	7	6	5	4	3	2	1	0	Reset Value
$SFR\;FD_H$	MSECH7	MSECH6	MSECH5	MSECH4	MSECH3	MSECH2	MSECH1	MSECH0	0F _H

MSECH7-0 One Millisecond High. This value in combination with the previous register is used to create a 1ms clock. bits 7-0 $1ms = (MSECH \cdot 256 + MSECL + 1) \cdot t_{CLK}$.

One Hundred Millisecond Register (HMSEC)

	7	6	5	4	3	2	1	0	Reset Value
$SFR\;FE_H$	HMSEC7	HMSEC6	HMSEC5	HMSEC4	HMSEC3	HMSEC2	HMSEC1	HMSEC0	63 _H

HMSEC7-0 One Hundred Millisecond. This clock divides the 1ms clock to create a 100ms clock.

bits 7-0 $100ms = (MSECH \cdot 256 + MSECL + 1) \cdot (HMSEC + 1) \cdot t_{CLK}$

Watchdog Timer Register (WDTCON)

	7	6	5	4	3	2	1	0	Reset Value
$SFR\;FF_H$	EWDT	DWDT	RWDT	WDCNT4	WDCNT3	WDCNT2	WDCNT1	WDCNT0	00 _H

EWDT Enable Watchdog (R/W).

bit 7 Write 1/Write 0 sequence sets the Watchdog Enable Counting bit.

DWDT Disable Watchdog (R/W).

bit 6 Write 1/Write 0 sequence clears the Watchdog Enable Counting bit.

RWDT Reset Watchdog (R/W).

bit 5 Write 1/Write 0 sequence restarts the Watchdog Counter.

WDCNT4-0 Watchdog Count (R/W).

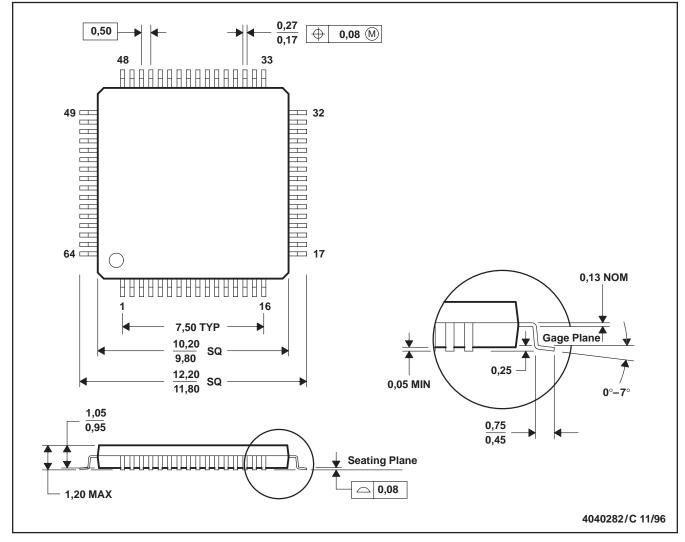
bits 4-0 Watchdog expires in (WDCNT + 1) • HMSEC to (WDCNT + 2) • HMSEC, if the sequence is not asserted. There is an uncertainty of 1 count.





PAG (S-PQFP-G64)

PLASTIC QUAD FLATPACK



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS-026



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PACKAGING INFORMATION

ORDERABLE DEVICE	STATUS(1)	PACKAGE TYPE			
		FACKAGE ITPE	PACKAGE DRAWING	PINS	PACKAGE QTY
MSC1211Y2PAGR	ACTIVE	TQFP	PAG	64	2000
MSC1211Y2PAGT	ACTIVE	TQFP	PAG	64	250
MSC1211Y3PAGR	ACTIVE	TQFP	PAG	64	2000
MSC1211Y3PAGT	ACTIVE	TQFP	PAG	64	250
MSC1211Y4PAGR	ACTIVE	TQFP	PAG	64	2000
MSC1211Y4PAGT	ACTIVE	TQFP	PAG	64	250
MSC1211Y5PAGR	ACTIVE	TQFP	PAG	64	2000
MSC1211Y5PAGT	ACTIVE	TQFP	PAG	64	250

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs. **LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

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